

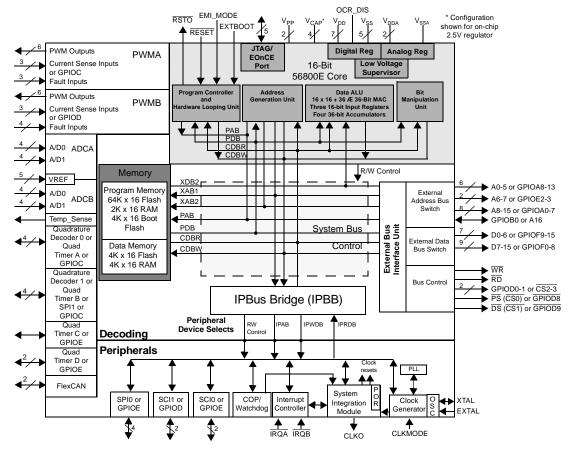
56F8346

Preliminary Technical Data

56F8346 16-bit Hybrid Controller

- Up to 60 MIPS at 60MHz core frequency
- DSP and MCU functionality in a unified, C-efficient architecture
- Access up to 1MB of off-chip program and data memory
- Chip Select Logic for glueless interface to ROM and SRAM
- · 128KB of Program Flash
- 4KB of Program RAM
- 8KB of Data Flash
- · 8KB of Data RAM
- · 8KB of Boot Flash
- · Two 6-channel PWM Modules
- Four 4-channel, 12-bit ADCs

- Temperature Sensor
- · Two Quadrature Decoders
- Optional On-Chip Regulator
- · FlexCAN Module
- Two Serial Communication Interfaces (SCIs)
- Up to two Serial Peripheral Interfaces (SPIs)
- Up to four General Purpose Quad Timers
- Computer Operating Properly (COP) / Watchdog
- JTAG/Enhanced On-Chip Emulation (OnCETM) for unobtrusive, real-time debugging
- Up to 62 GPIO lines
- 144-pin LQFP Package



56F8346 Block Diagram



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 $Please \ see \ http://www.motorola.com/semiconductors \ for \ the \ most \ current \ Data \ Sheet \ revision.$

Part 1 Overview

1.1 56F8346 Features

1.1.1 Digital Signal Processing Core

- Efficient 16-bit 56800E family hybrid controller engine with dual Harvard architecture
- As many as 60 Million Instructions Per Second (MIPS) at 60 MHz core frequency
- Single-cycle 16 × 16-bit parallel Multiplier-Accumulator (MAC)
- Four 36-bit accumulators including extension bits
- Arithmetic and logic multi-bit shifter
- Parallel instruction set with unique DSP addressing modes
- Hardware DO and REP loops
- Three internal address buses
- Four internal data buses
- Instruction set supports both DSP and controller functions
- Controller style addressing modes and instructions for compact code
- Efficient C compiler and local variable support
- Software subroutine and interrupt stack with depth limited only by memory
- JTAG/EOnCE debug programming interface

1.1.2 Memory

- Harvard architecture permits as many as three simultaneous accesses to program and data memory
- Flash security protection feature
- On-chip memory including a low-cost, high-volume Flash solution
 - 128KB of Program Flash
 - 4KB of Program RAM
 - 8KB of Data Flash
 - 8KB of Data RAM
 - 8KB of Boot Flash
- Off-chip memory expansion capabilities programmable for 0 30 wait states
 - Access up to 1MB of program memory or 1MB of data memory
 - Chip select logic for glue-less interface to ROM and SRAM
- Temperature Sense diode can be connected, on the board, to any of the ADC inputs to monitor the on-chip temperature
- EEPROM emulation capability

1.1.3 Peripheral Circuits for 56F8346

- Two Pulse Width Modulator modules each with six PWM outputs, three Current Sense inputs, and three Fault inputs, fault-tolerant design with dead time insertion, supports both center-aligned and edge-aligned modes
- Four 12-bit, Analog-to-Digital Converters (ADCs), which support four simultaneous conversions with quad, 4-pin multiplexed inputs; ADC and PWM modules can be synchronized through Timer C, channels 2 and 3

- Temperature Sensor, which can be tied to an analog input pin to monitor the on-chip temperature
- Two four-input Quadrature Decoders or two additional Quad Timers
- Four dedicated General Purpose Quad Timers totaling three dedicated pins: Timer C with one pin and Timer D with two pins
- Optional On-Chip Regulator
- FlexCAN (CAN Version 2.0 B-compliant) Module with 2-pin port for transmit and receive
- Two Serial Communication Interfaces each with two pins (or four additional GPIO lines)
- Up to two Serial Peripheral Interfaces (SPIs) with configurable 4-pin port (or eight additional GPIO lines). SPI1 can also be used as Quadrature Decoder 1 or Quad Timer B
- Computer-Operating Properly (COP) / Watchdog timer
- Two dedicated external interrupt pins
- 62 General Purpose I/O (GPIO) pins
- External reset input pin for hardware reset
- External reset output pin for system reset
- Integrated low-voltage interrupt module
- JTAG/Enhanced On-Chip Emulation (OnCETM) for unobtrusive, processor speed-independent, real-time debugging
- Software-programmable, Phase Lock Loop-based frequency synthesizer for the core clock

1.1.4 Energy Information

- Fabricated in high-density CMOS with 5V-tolerant, TTL-compatible digital inputs
- On-board 3.3V down to 2.6V voltage regulator for powering internal logic and memories; can be disabled
- On-chip regulators for digital and analog circuitry to lower cost and reduce noise
- Wait and Stop modes available
- ADC smart power management
- Each peripheral can be individually disabled to save power

1.2 56F8346 Description

The 56F8346 is a member of the 56800E core-based family of hybrid controllers. It combines, on a single chip, the processing power of a DSP and the functionality of a microcontroller with a flexible set of peripherals to create an extremely cost-effective solution. Because of its low cost, configuration flexibility, and compact program code, the 56F8346 is well-suited for many applications. The 56F8346 includes many peripherals that are especially useful for applications such as motion control, smart appliances, steppers, encoders, tachometers, limit switches, power supply and control, automotive control, engine management, noise suppression, remote utility metering, industrial control for power, lighting, and automation.

The 56800E core is based on a Harvard-style architecture consisting of three execution units operating in parallel, allowing as many as six operations per instruction cycle. The MCU-style programming model and optimized instruction set allow straightforward generation of efficient, compact DSP and control code. The instruction set is also highly efficient for C/C++ Compilers to enable rapid development of optimized control applications.

The 56F8346 supports program execution from either internal or external memories. Two data operands can be accessed from the on-chip data RAM per instruction cycle. The 56F8346 also provides two external dedicated interrupt lines and up to 62 General Purpose Input/Output (GPIO) lines, depending on peripheral configuration.

The 56F8346 hybrid controller includes 128KB of Program Flash and 8KB of Data Flash (each programmable through the JTAG port) with 4KB of Program RAM and 8KB of Data RAM.

A total of 8KB of Boot Flash is incorporated for easy customer-inclusion of field-programmable software routines that can be used to program the main Program and Data Flash memory areas. Both Program and Data Flash memories can be independently bulk erased or erased in pages. Program Flash page erase size is 1KB. Boot and Data Flash page erase size is 512 bytes. The Boot Flash memory can also be either bulk or page erased.

A key application-specific feature of the 56F8346 is the inclusion of two Pulse Width Modulator (PWM) modules. These modules each incorporate three complementary, individually programmable PWM signal output pairs (each module is also capable of supporting six independent PWM functions, for a total of 12 PWM outputs) to enhance motor control functionality. Complementary operation permits programmable dead time insertion, distortion correction via current sensing by software, and separate top and bottom output polarity control. The up-counter value is programmable to support a continuously variable PWM frequency. Edge- and center-aligned synchronous pulse width control (0% to 100% modulation) is supported. The device is capable of controlling most motor types: ACIM (AC Induction Motors), both BDC and BLDC (Brush and Brushless DC motors), SRM and VRM (Switched and Variable Reluctance Motors), and stepper motors. The PWMs incorporate fault protection and cycle-by-cycle current limiting with sufficient output drive capability to directly drive standard optoisolators. A "smoke-inhibit", write-once protection feature for key parameters is also included. A patented PWM waveform distortion correction circuit is also provided. Each PWM is double-buffered and includes interrupt controls to permit integral reload rates to be programmable from 1 to 16. The PWM modules provide reference outputs to synchronize the analog-to-digital converters through two channels of Quad Timer C.

The 56F8346 incorporates two Quadrature Decoders capable of capturing all four transitions on the two-phase inputs, permitting generation of a number proportional to actual position. Speed computation capabilities accommodate both fast- and slow-moving shafts. An integrated watchdog timer in the Quadrature Decoder can be programmed with a timeout value to alert when no shaft motion is detected. Each input is filtered to ensure only true transitions are recorded.

This hybrid controller also provides a full set of standard programmable peripherals that include two Serial Communications Interfaces (SCIs), two Serial Peripheral Interfaces (SPIs), and four Quad Timers. Any of these interfaces can be used as General-Purpose Input/Outputs (GPIOs) if that function is not required. A Flex Controller Area Network interface (CAN Version 2.0 A/B compliant) and an internal interrupt controller are included on the 56F8346.

1.3 Award-Winning Development Environment

Processor ExpertTM (PE) provides a Rapid Application Design (RAD) tool that combines easy-to-use component-based software application creation with an expert knowledge system.

The CodeWarrior Integrated Development Environment is a sophisticated tool for code navigation, compiling, and debugging. A complete set of evaluation modules (EVMs) and development system cards will support concurrent engineering. Together, PE, CodeWarrior and EVMs create a complete, scalable tools solution for easy, fast, and efficient development.

1.4 Architecture Block Diagram

The 56F8346 architecture is shown in **Figure 1-1** and **Figure 1-2**. **Figure 1-1** illustrates how the 56800E system buses communicate with internal memories, the external memory interface and the IP Bus Bridge. **Table 1-1** lists the internal buses in the 56800E architecture and provides a brief description of their function. **Figure 1-2** shows the peripherals and control blocks connected to the IP Bus Bridge. The figures do not show the on-board regulator and power and ground signals. They also do not show the multiplexing between peripherals or the dedicated GPIOs. Please see **Part 2**, **Signal/Connection Descriptions**, to see which signals are multiplexed with those of other peripherals.

Also shown in Figure 1-2 are connections between the PWM, Timer C and ADC blocks. These connections allow the PWM and/or Timer C to control the timing of the start of ADC conversions. The Timer C channel indicated can generate periodic start (SYNC) signals to the ADC to start its conversions. In another operating mode, the PWM load interrupt (SYNC output) signal is routed internally to the Timer C input channel as indicated. The timer can then be used to introduce a controllable delay before generating its output signal. The timer output then triggers the ADC. To fully understand this interaction, please see the **56F8300 Peripheral User Manual** for clarification on the operation of all three of these peripherals.

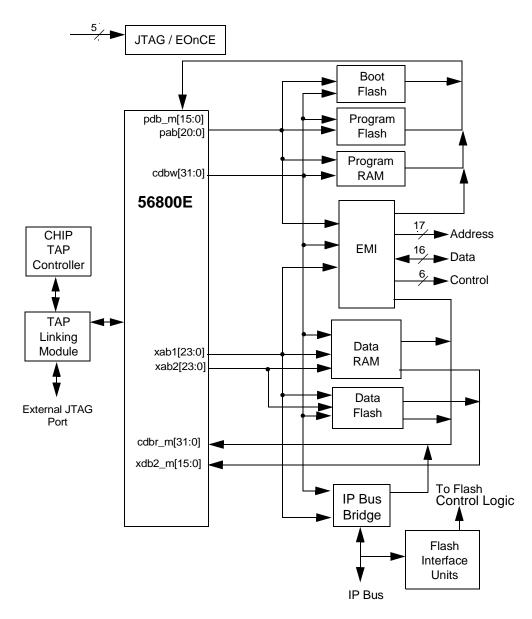


Figure 1-1 System Bus Interfaces

Note: Flash memories are encapsulated within the Flash Interface Unit (FIU). Flash control is accomplished by the I/O to the FIU over the peripheral bus, while reads and writes are completed between the core and the Flash memories.

Note: The primary data RAM port is 32 bits wide. Other data ports are 16 bits.

Interrupt **CLKGEN** Controller (OSC/PLL) Low Voltage Interrupt Timer A POR & LVI System POR Quadrature Decoder 0 RESET SIM Timer D **COP** Reset Timer B COP **FlexCAN** Quadrature Decoder 1 SPI 1 **PWMA** SYNC Output **GPIOA PWMB GPIOB** SYNC Output **GPIOC** ch2i ch3i Timer C **GPIOD** ch3o ch2o **GPIOE GPIOF ADCB** SPI0 **ADCA** SCI0 Temp. Sense SCI1 Note: ADCA and ADCB use the same voltage reference circuit with $V_{REFH}, \\ V_{REFP}, V_{REFMID}, V_{REFN}, and V_{REFLO}$ IP Bus

To/From IP Bus Bridge

Figure 1-2 Peripheral Subsystem

Table 1-1 Bus Signal Names

Name	Function					
	Program Memory Interface					
pdb_m[15:0]	Program data bus for instruction word fetches or read operations.					
cdbw[15:0]	Primary core data bus used for program memory writes. (Only these 16 bits of the cdbw[31:0] bus are used for writes to program memory.)					
pab[20:0]	Program memory address bus. Data is returned on pdb_m bus.					
	Primary Data Memory Interface Bus					
cdbr_m[31:0]	Primary core data bus for memory reads. Addressed via xab1 bus.					
cdbw[31:0]	Primary core data bus for memory writes. Addressed via xab1 bus.					
xab1[23:0]	Primary data address bus. Capable of addressing bytes ¹ , words, and long data types. Data is written on cdbw and returned on cdbr_m. Also used to access memory mapped I/O.					
	Secondary Data Memory Interface					
xdb2_m[15:0]	Secondary data bus used for Secondary data address bus xab2 in the dual memory reads.					
xab2[23:0]	Secondary data address bus used for the second of two simultaneous accesses. Capable of addressing only words. Data is returned on xdb2_m.					
	Peripheral Interface Bus					
IPBus [15:0]	Peripheral Bus accesses all On-Chip peripherals registers. This bus operates at the same clock rate as the Primary Data Memory and therefore generates no delays when accessing the processor. Write data is obtained from cdbw. Read data is provided to cdbr_m.					

^{1.} Byte accesses can only occur in the bottom half of the memory address space. The MSB of the address will be forced to 0.

1.5 Product Documentation

The four documents in **Table 1-2** are required for a complete description and proper design with the 56F8346. Documentation is available from local Motorola distributors, Motorola semiconductor sales offices, Motorola Literature Distribution Centers, or online at **http://www.motorola.com/semiconductors**.

Table 1-2 56F8346 Chip Documentation

Topic	Description	Order Number
DSP56800E Reference Manual	Detailed description of the 56800E family architecture, and 16-bit hybrid controller core processor and the instruction set	DSP56800ERM/D
568300 Peripheral User Manual	Detailed description of peripherals of the 56F8300 devices	MC56F8300UM/D
56F8346 Technical Data Sheet	Electrical and timing specifications, pin descriptions, and package descriptions (this document)	MC56F8346/D
56F8346 Product Brief	Summary description and block diagram of the 56F8346 core, memory, peripherals and interfaces	MC56F8346PB/D
56F8346 Errata	Details any chip issues that might be present	MC56F8346E/D

1.6 Data Sheet Conventions

This data sheet uses the following conventions:

OVERBAR This is used to indicate a signal that is active when pulled low. For example, the RESET pin is

active when low.

"asserted" A high true (active high) signal is high or a low true (active low) signal is low.

"deasserted" A high true (active high) signal is low or a low true (active low) signal is high.

Examples:	Signal/Symbol	Logic State	Signal State	Voltage ¹
	PIN	True	Asserted	V_{IL}/V_{OL}
	PIN	False	Deasserted	V_{IH}/V_{OH}
	PIN	True	Asserted	V_{IH}/V_{OH}
	PIN	False	Deasserted	V_{IL}/V_{OL}

^{1.} Values for VIL, VOL, VIH, and VOH are defined by individual product specifications.

Part 2 Signal/Connection Descriptions

2.1 Introduction

The input and output signals of the 56F8346 are organized into functional groups, as shown in **Table 2-1** and as illustrated in **Figure 2-1**. In **Table 2-2**, each table row describes the signal or signals present on a pin.

Table 2-1 Functional Group Pin Allocations

Functional Group	Number of Pins
Power (V _{DD} or V _{DDA}) ¹	9
Power Option Control	1
Ground (V _{SS} or V _{SSA})	6
Supply Capacitors & V _{PP}	6
PLL and Clock	4
Address Bus	17
Data Bus	16
Bus Control	6
Interrupt and Program Control	6
Pulse Width Modulator (PWM) Ports	25
Serial Peripheral Interface (SPI) Port 0	4
Quadrature Decoder Port 0 ²	4
Quadrature Decoder Port 1 ³	4
Serial Communications Interface (SCI) Ports	4
CAN Ports	2
Analog to Digital Converter (ADC) Ports	21
Timer Module Ports	3
JTAG/Enhanced On-Chip Emulation (EOnCE)	5
Temperature Sense	1

^{1.} If the on-chip regulator is disabled, the V_{CAP} pins serve as 2.5V V_{DD_CORE} power inputs

^{2.} Alternately, can function as Quad Timer pins or GPIO

^{3.} Pins in this section can function as Quad Timer, SPI #1, or GPIO

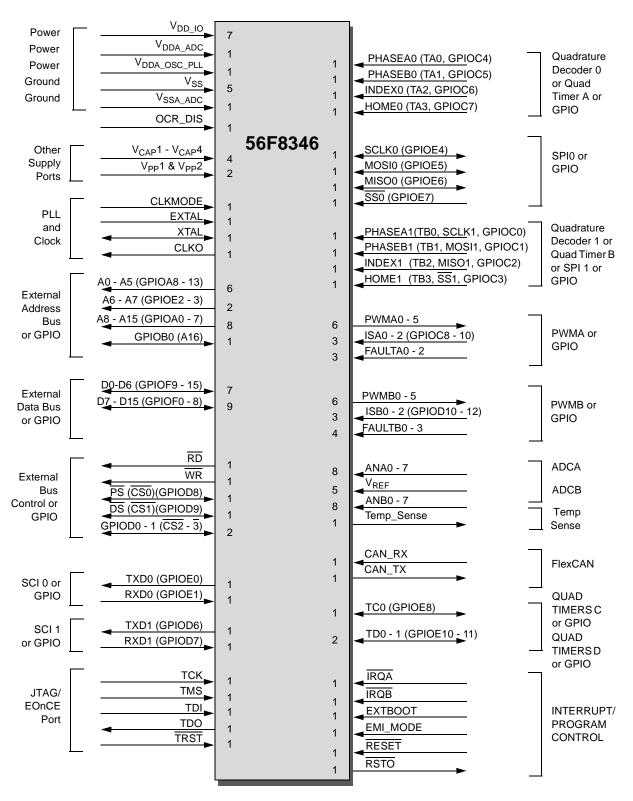


Figure 2-1 56F8346 Signals Identified by Functional Group¹ (144 pin LQFP)

^{1.} Alternate pin functionality is shown in parenthesis; pin direction/type shown is the default functionality.

2.2 56F8346 Signal Pins

After reset, all pins are by default the primary function. Any alternate functionality must be programmed.

Table 2-2 56F8346 Signal and Package Information for the 144 Pin LQFP

Signal Name	Pin No.	Туре	State During Reset	Signal Description
V _{DD_IO}	1	Supply		I/O Power — This pin supplies 3.3V power to the chip I/O
V_{DD_IO}	16			interface.
V _{DD_IO}	31			
V _{DD_IO}	38			
V _{DD_IO}	66			
V _{DD_IO}	84			
V _{DD_IO}	119			
V _{DDA_ADC}	102	Supply		ADC Power — This pin supplies 3.3V power to the ADC modules. It must be connected to a clean analog power supply.
V _{DDA_OSC_PLL}	80	Supply		Oscillator and PLL Power — This pin supplies 3.3V power to the OSC and to the internal regulator that in turn supplies the phase locked loop. It must be connected to a clean analog power supply.
V _{SS}	27	Supply		V _{SS} — These pins provide ground for chip logic and I/O
V _{SS}	37			drivers.
V _{SS}	63			
V _{SS}	69			
V _{SS}	144			
V _{SSA_ADC}	103	Supply		ADC Analog Ground — This pin supplies an analog ground to the ADC modules.
OCR_DIS	79	Input	Input	On-Chip Regulator Disable — Tie this pin to V _{SS} to enable the on-chip regulator Tie this pin to V _{DD} to disable the on-chip regulator This pin is intended to be a static DC signal from power-up to shut down. Do not try to toggle this pin for power savings during operation.

Table 2-2 56F8346 Signal and Package Information for the 144 Pin LQFP

Signal Name	Pin No.	Туре	State During Reset	Signal Description	
V _{CAP} 1	51	Supply	Supply	V _{CAP} 1 - 4 — When OCR_DIS is tied to V _{SS} (regulator	
V _{CAP} 2	128			enabled), connect each pin to a 2.2μF or greater bypass capacitor in order to bypass the core logic voltage	
V _{CAP} 3	83			regulator, required for proper chip operation. When OCR_DIS is tied to V _{DD} (regulator disabled), these pins	
V _{CAP} 4	15			become V _{DD_CORE} and should be connected to a regulated 2.5V power supply.	
V _{PP} 1	125	Input	Input	V _{PP} 1 - V _{PP} 2 — These pins should be left unconnected as	
V _{PP} 2	2			an open circuit for normal functionality.	
CLKMODE	87	Input	Input	Clock Input Mode Selection — This input determines the function of the XTAL and EXTAL pins.	
					1 = External clock input on XTAL is used to directly drive the input clock of the chip. The EXTAL pin should be grounded.
				0 = A crystal or ceramic resonator should be connected between XTAL and EXTAL.	
EXTAL	82	Input	Input	External Crystal Oscillator Input — This input can be connected to an 8MHz external crystal. Tie this pin low if XTAL is driven by an external clock source.	
XTAL	81	Input/ Output	Chip-driven	Crystal Oscillator Output — This output connects the internal crystal oscillator output to an external crystal.	
				If an external clock is used, XTAL must be used as the input and EXTAL connected to GND.	
				The input clock can be selected to provide the clock directly to the core. This input clock can also be selected as the input clock for the on-chip PLL.	
CLKO	3	Output	Tri-Stated	Clock Output — This pin outputs a buffered clock signal. Using the SIM CLKO Select Register (SIM_CLKOSR), this pin can be programmed as any of the following: disabled, CLK_MSTR (system clock), IP Bus clock, oscillator output, prescaler clock and postscaler clock. Other signals are also available for test purposes.	
				See Section 6.5.7 for details.	

Table 2-2 56F8346 Signal and Package Information for the 144 Pin LQFP

Signal Name	Pin No.	Туре	State During Reset	Signal Description					
A0 (GPIOA8)	138	Output	Output Tri-stated	Address Bus — A0 - A5 specify six of the address lines for external program or data memory accesses. Depending upon the state of the DRV bit in the EMI bus control register (BCR), A0–A16 and EMI control signals are tri-stated when					
A1 (GPIOA9)	10					Port A GPIO — These six GPIO pins can programmed as input or output pins. After reset, these pins default to address I and must be programmed as GPIO. To deactivate the internal pull-up resistor,	programmed as input or output pins. After reset, these pins default to addr		Port A GPIO — These six GPIO pins can be individually
A2 (GPIOA10)	11							After reset, these pins default to address bus functionality	
A3 (GPIOA11)	12						To deactivate the internal pull-up resistor, clear the		
A4 (GPIOA12)	13			appropriate GPIO bit in the GPIOA_PUR register. Example: GPIOA8, clear bit 8 in the GPIOA_PUR register.					
A5 (GPIOA13)	14								
A6 (GPIOE2)	17	Output Schmitt Input/	Schmitt	Schmitt	Tri-stated Input	Address Bus — A6 - A7 specify two of the address lines for external program or data memory accesses. Depending upon the state of the DRV bit in the EMI bus control register (BCR), A0–A16 and EMI control signals are tri-stated when			
A7 (GPIOE3)	18	Output		Port E GPIO — These two GPIO pins can be individually programmed as input or output pins. After reset, the default state is Address Bus. To deactivate the internal pull-up resistor, clear the					
				appropriate GPIO bit in the GPIOE_PUR register. Example: GPIOE2, clear bit 2 in the GPIOE_PUR register.					

Table 2-2 56F8346 Signal and Package Information for the 144 Pin LQFP

Signal Name	Pin No.	Туре	State During Reset	Signal Description
A8 (GPIOA0)	19	Output	Tri-stated	Address Bus— A8 - A15 specify eight of the address lines for external program or data memory accesses. Depending
A9 (GPIOA1)	20	Schmitt Input/ Output	Input	upon the state of the DRV bit in the EMI bus control register (BCR), A0–A16 and EMI control signals are tri-stated when the external bus is inactive.
A10 (GPIOA2)	21	σαιραί		Port A GPIO — These eight GPIO pins can be individually programmed as input or output pins.
A11 (GPIOA3)	22			After reset, the default state is Address Bus.
A12 (GPIOA4)	23			To deactivate the internal pull-up resistor, clear the appropriate GPIO bit in the GPIOA_PUR register.
A13 (GPIOA5)	24			Example: GPIOA0, clear bit 0 in the GPIOA_PUR register.
A14 (GPIOA6)	25			
A15 (GPIOA7)	26			
GPIOB0	33	Schmitt Input/ Output	Input	Port B GPIO — This GPIO pin can be programmed as an input or output pin.
(A16)		Output	Tri-stated	Address Bus — A16 specifies one of the address lines for external program or data memory accesses. Depending upon the state of the DRV bit in the EMI bus control register (BCR), A0–A16 and EMI control signals are tri-stated when the external bus is inactive.
				After reset, the startup state of GPIOB0 (GPIO or address) is determined as a function of EXTBOOT, EMI_MODE and the Flash security setting. See Table 4-4 for further information on when this pin is configured as an address pin at reset. In all cases, this state may be changed by writing to GPIOB_PER.
				To deactivate the internal pull-up resistor, clear bit 0 in the GPIOB_PUR register.

Table 2-2 56F8346 Signal and Package Information for the 144 Pin LQFP

Signal Name	Pin No.	Туре	State During Reset	Signal Description					
D0 (GPIOF9)	59	Input/ Output	Tri-stated	Data Bus — D0 - D6 specify part of the data for external program or data memory accesses. Depending upon the					
D1 (GPIOF10)	60			state of the DRV bit in the SEMI bus control register (BCR), D0-D6 are tri-stated when the external bus is inactive.					
D2 (GPIOF11)	72			Port F GPIO — These four GPIO pins can be individually programmed as input or output pins.					
D3 (GPIOF12)	75			At reset, these pins default to the EMI Data bus function.					
D4 (GPIOF13)	76	appropriate GPIO bit in the GPIOF_PU					To deactivate the internal pull-up resistor, clear the appropriate GPIO bit in the GPIOF_PUR register.		
D5 (GPIOF14)	77				Example: GPIOF9, clear bit 9 in the GPIOF_PUR register.				
D6 (GPIOF15)	78								
D7 (GPIOF0)	28	Input/ Output	Tri-stated	Data Bus — D7 - D14 specify part of the data for external program or data memory accesses.					
D8 (GPIOF1)	29	Input/ Input Output	locut		programmed as input or output pins.	Port F GPIO — These eight GPIO pins can be individually programmed as input or output pins.			
D9 (GPIOF2)	30						Output At reset, these pins default to dat	At reset, these pins default to data bus functionality.	
D10 (GPIOF3)	32					To deactivate the internal pull-up resistor, clear the appropriate GPIO bit in the GPIOF_PUR register.			
D11 (GPIOF4)	133				Example: GPIOF0, clear bit 0 in the GPIOF_PUR register.				
D12 (GPIOF5)	134								
D13 (GPIOF6)	135								
D14 (GPIOF7)	136								

Table 2-2 56F8346 Signal and Package Information for the 144 Pin LQFP

Signal Name	Pin No.	Туре	State During Reset	Signal Description
D15 (GPIOF8)	137	Input/ Output	Tri-stated	Data Bus — D15 specifies part of the data for external program or data memory accesses.
				Port F GPIO — This GPIO pin can be individually programmed as an input or output pin.
				At reset, this pin defaults to the D15 function.
				To deactivate the internal pull-up resistor, clear bit 8 in the GPIOF_PUR register.
RD	45	Output	Tri-stated	Read Enable — RD is asserted during external memory read cycles. When RD is asserted low, pins D0 - D15 become inputs and an external device is enabled onto the data bus. When RD is deasserted high, the external data is latched inside the device. When RD is asserted, it qualifies the A0 - A16, PS, DS, and CSn pins. RD can be connected directly to the OE pin of a Static RAM or ROM. Depending upon the state of the DRV bit in the SEMI bus control register (BCR), RD is tri-stated when the external bus is inactive. To deactivate the internal pull-up resistor, set the CTRL bit in the SIM_PUDR register.
WR	44	Output	Tri-stated	Write Enable — WR is asserted during external memory write cycles. When WR is asserted low, pins D0 - D15 become outputs and the device puts data on the bus. When WR is deasserted high, the external data is latched inside the external device. When WR is asserted, it qualifies the A0 - A16, PS, DS, and CSn pins. WR can be connected directly to the WE pin of a static RAM. Depending upon the state of the DRV bit in the SEMI bus control register (BCR), WR is tri-stated when the external bus is inactive. To deactivate the internal pull-up resistor, set the CTRL bit in the SIM_PUDR register.

Table 2-2 56F8346 Signal and Package Information for the 144 Pin LQFP

Signal Name	Pin No.	Туре	State During Reset	Signal Description
PS (CS0) (GPIOD8)	46	Output	Tri-stated	Program Memory Select — This signal is actually $\overline{\text{CS0}}$ in the EMI, which is programmed at reset for compatibility with the 56F80x $\overline{\text{PS}}$ signal. $\overline{\text{PS}}$ is asserted low for external program memory access. Depending upon the state of the DRV bit in the SEMI bus control register (BCR), $\overline{\text{PS}}$ is tri-stated when the external bus is inactive.
				Port D GPIO — This GPIO pin can be individually programmed as an input or output pin. CSO resets to provide the PS function as defined on the 56F80x devices. To deactivate the internal pull-up resistor, clear bit 8 in the
				GPIOD_PUR register.
OS (CS1) (GPIOD9)	47	Output	Tri-stated	Data Memory Select — This signal is actually $\overline{\text{CS1}}$ in the EMI, which is programmed at reset for compatibility with the 56F80x $\overline{\text{DS}}$ signal. $\overline{\text{DS}}$ is asserted low for external data memory access. Depending upon the state of the DRV bit in the SEMI bus control register (BCR), $\overline{\text{DS}}$ is tri-stated when the external bus is inactive. Port D GPIO — This GPIO pin can be individually programmed as an input or output pin.
				To deactivate the internal pull-up resistor, clear bit 9 in the GPIOD_PUR register.
GPIOD0 (CS2)	48	Input/ Output	Input	Port D GPIO — These two GPIO pins can be individually programmed as input or output pins.
GPIOD1 (CS3)	49	Output		Chip Select — CS2 - CS3 may be programmed within the EMI module to act as chip selects for specific areas of the external memory map. Depending upon the state of the DRV bit in the SEMI bus control register (BCR), CS2 - CS3 is tri-stated when the external bus is inactive. At reset, these pins are configured as GPIO. To deactivate the internal pull-up resistor, clear the appropriate GPIO bit in the GPIOD_PUR register. Example: GPIOD0, clear bit 0 in the GPIOD_PUR register.

Table 2-2 56F8346 Signal and Package Information for the 144 Pin LQFP

Signal Name	Pin No.	Туре	State During Reset	Signal Description
TXD0	4	Output	Input	Transmit Data — SCI0 transmit data output
(GPIOE0)		Input/ Output	Input	Port E GPIO — This GPIO pin can be individually programmed as an input or output pin.
				After reset, the default state is SCI output.
				To deactivate the internal pull-up resistor, clear bit 0 in the GPIOE_PUR register.
RXD0	5	Input	Input	Receive Data — SCI0 receive data input
(GPIOE1)		Input/ Output	Input	Port E GPIO — This GPIO pin can be individually programmed as an input or output pin.
				After reset, the default state is SCI output.
				To deactivate the internal pull-up resistor, clear bit 1 in the GPIOE_PUR register.
TXD1	42	Output	Input	Transmit Data — SCI1 transmit data output
(GPIOD6)		Input/ Output	Input	Port D GPIO — This GPIO pin can be individually programmed as an input or output pin.
				After reset, the default state is SCI output.
				To deactivate the internal pull-up resistor, clear bit 6 in the GPIOD_PUR register.
RXD1	43	Input	Input	Receive Data — SCI1 receive data input
(GPIOD7)		Input/ Output	Input	Port D GPIO — This GPIO pin can be individually programmed as an input or output pin.
				After reset, the default state is SCI input.
				To deactivate the internal pull-up resistor, clear bit 7 in the GPIOD_PUR register.
тск	121	Schmitt Input	Input, pulled low internally	Test Clock Input — This input pin provides a gated clock to synchronize the test logic and shift serial data to the JTAG/EOnCE port. The pin is connected internally to a pull-down resistor.
TMS	122	Schmitt Input	Input, pulled high internally	Test Mode Select Input — This input pin is used to sequence the JTAG TAP controller's state machine. It is sampled on the rising edge of TCK and has an on-chip pull-up resistor.
				To deactivate the internal pull-up resistor, set the JTAG bit in the SIM_PUDR register.

Table 2-2 56F8346 Signal and Package Information for the 144 Pin LQFP

Signal Name	Pin No.	Туре	State During Reset	Signal Description
TDI	123	Schmitt Input	Input, pulled high internally	Test Data Input — This input pin provides a serial input data stream to the JTAG/EOnCE port. It is sampled on the rising edge of TCK and has an on-chip pull-up resistor. To deactivate the internal pull-up resistor, set the JTAG bit
				in the SIM_PUDR register.
TDO	124	Output	Tri-stated	Test Data Output — This tri-stateable output pin provides a serial output data stream from the JTAG/EOnCE port. It is driven in the shift-IR and shift-DR controller states, and changes on the falling edge of TCK.
TRST	120	Schmitt Input	Input, pulled high internally	Test Reset — As an input, a low signal on this pin provides a reset signal to the JTAG TAP controller. To ensure complete hardware reset, TRST should be asserted whenever RESET is asserted. The only exception occurs in a debugging environment when a hardware device reset is required and the EOnCE/JTAG module must not be reset. In this case, assert RESET, but do not assert TRST. To deactivate the internal pull-up resistor, set the JTAG bit in the SIM_PUDR register.
PHASEA0	139	Schmitt Input	Input	Phase A — Quadrature Decoder 0 PHASEA input
(TA0)		Schmitt Input/ Output	Input	TA0 — Timer A Channel 0
(GPIOC4)		Schmitt Input/ Output		Port C GPIO — This GPIO pin can be individually programmed as an input or output pin. After reset, the default state is PHASEA0. To deactivate the internal pull-up resistor, clear bit 4 of the
				To deactivate the internal pull-up resistor, clear bit 4 of the GPIOC_PUR register.

Table 2-2 56F8346 Signal and Package Information for the 144 Pin LQFP

Signal Name	Pin No.	Type	State During Reset	Signal Description
PHASEB0	140	Schmitt Input	Input	Phase B — Quadrature Decoder 0 PHASEB input
(TA1)		Schmitt Input/ Output	Input	TA1 — Timer A Channel
(GPIOC5)		Schmitt Input/ Output		Port C GPIO — This GPIO pin can be individually programmed as an input or output pin. After reset, the default state is PHASEBO.
				To deactivate the internal pull-up resistor, clear bit 5 of the GPIOC_PUR register.
INDEX0	141	Schmitt Input	Input	Index — Quadrature Decoder 0 INDEX input
(TA2)		Schmitt Input/ Output	Input	TA2 — Timer A Channel 2
(GPOPC6)		Schmitt Input/ Output		Port C GPIO — This GPIO pin can be individually programmed as an input or output pin.
		Output		After reset, the default state is INDEX0. To deactivate the internal pull-up resistor, clear bit 6 of the GPIOC_PUR register.
HOME0	142	Schmitt Input	Input	Home — Quadrature Decoder 0 HOME input
(TA3)		Schmitt Input/ Output	Input	TA3 — Timer A Channel 3
(GPIOC7)		Schmitt Input/ Output		Port C GPIO — This GPIO pin can be individually programmed as an input or output pin. After reset, the default state is HOME0.
				To deactivate the internal pull-up resistor, clear bit 7 of the GPIOC_PUR register.

Table 2-2 56F8346 Signal and Package Information for the 144 Pin LQFP

Signal Name	Pin No.	Туре	State During Reset	Signal Description
SCLK0	130	Schmitt Input/ Output	Input	SPI 0 Serial Clock — In the master mode, this pin serves as an output, clocking slaved listeners. In slave mode, this pin serves as the data clock input.
(GPIOE4)		Schmitt Input/ Output	Input	Port E GPIO — This GPIO pin can be individually programmed as an input or output pin. After reset, the default state is SCLK0. To deactivate the internal pull-up resistor, clear bit 4 in the GPIOE_PUR register.
MOSI0	132	Input/ Output	Input	SPI 0 Master Out/Slave In — This serial data pin is an output from a master device and an input to a slave device. The master device places data on the MOSI line a half-cycle before the clock edge the slave device uses to latch the data.
(GPIOE5)		Input/ Output	Input	Port E GPIO — This GPIO pin can be individually programmed as an input or output pin. After reset, the default state is MOSIO. To deactivate the internal pull-up resistor, clear bit 5 in the GPIOE_PUR register.
MISO0 (GPIOE6)	131	Input/ Output	Input	SPI 0 Master In/Slave Out — This serial data pin is an input to a master device and an output from a slave device. The MISO line of a slave device is placed in the high-impedance state if the slave device is not selected. The slave device places data on the MISO line a half-cycle before the clock edge the master device uses to latch the data.
		Input/ Output	Input	Port E GPIO — This GPIO pin can be individually programmed as an input or output pin. After reset, the default state is MISO0. To deactivate the internal pull-up resistor, clear bit 6 in the GPIOE_PUR register.

Table 2-2 56F8346 Signal and Package Information for the 144 Pin LQFP

Signal Name	Pin No.	Туре	State During Reset	Signal Description
SSO	129	Input	Input	SPI 0 Slave Select — SS0 is used in slave mode to indicate to the SPI module that the current transfer is to be received.
(GPIOE7)		Input/ Output	Input	Port E GPIO — This GPIO pin can be individually programmed as input or output pin. After reset, the default state is \$\overline{SSO}\$. To deactivate the internal pull-up resistor, clear bit 7 in the GPIOE_PUR register.
PHASEA1	6	Schmitt Input	Input	Phase A1 — Quadrature Decoder 1 PHASEA input for decoder 1.
(TB0)		Schmitt Input/ Output	Input	TB0 — Timer B Channel 0
(SCLK1)		Schmitt Input/ Output	Input	SPI1 Serial Clock — In the master mode, this pin serves as an output, clocking slaved listeners. In slave mode, this pin serves as the data clock input. To activate the SPI function, set the PHSA_ALT bit in the SIM_GPS register. For details, see Section 6.5.8.
(GPIOC0)		Schmitt Input/ Output	Input	Port C GPIO — This GPIO pin can be individually programmed as an input or output pin. After reset, the default state is PHASEA1. To deactivate the internal pull-up resistor, clear bit 0 in the GPIOC_PUR register.

Table 2-2 56F8346 Signal and Package Information for the 144 Pin LQFP

Signal Name	Pin No.	Туре	State During Reset	Signal Description
PHASEB1	7	Schmitt Input	Input	Phase B1 — Quadrature Decoder 1 PHASEB input for decoder 1.
(TB1)		Schmitt Input/ Output	Input	TB1 — Timer B Channel 1
(MOSI1)		Schmitt Input/ Output	Input	SPI 1 Master Out/Slave In — This serial data pin is an output from a master device and an input to a slave device. The master device places data on the MOSI line a half-cycle before the clock edge the slave device uses to latch the data. To activate the SPI function, set the PHSB_ALT bit in the SIM_GPS register. For details, see Section 6.5.8.
(GPIOC1)		Schmitt Input/ Output	Input	Port C GPIO — This GPIO pin can be individually programmed as an input or output pin. After reset, the default state is PHASEB1. To deactivate the internal pull-up resistor, clear bit 1 in the GPIOC_PUR register.
INDEX1	8	Schmitt Input	Input	Index1 — Quadrature Decoder 1 INDEX input
(TB2)		Schmitt Input/ Output	Input	TB2 — Timer B Channel 2
(MISO1)		Schmitt Input/ Output	Input	SPI1 Master In/Slave Out — This serial data pin is an input to a master device and output from a slave device. The MISO line of a slave device is placed in the high-impedance state if the slave device is not selected. The slave device places data on the MISO line a half-cycle before the clock edge the master device uses to latch the data. To activate the SPI function, set the INDEX_ALT bit in the SIM_GPS register. For details, see Section 6.5.8.
(GPIOC2)		Schmitt Input/ Output	Input	Port C GPIO — This GPIO pin can be individually programmed as an input or output pin. After reset, the default state is INDEX1. To deactivate the internal pull-up resistor, clear bit 2 in the GPIOC_PUR register.

Table 2-2 56F8346 Signal and Package Information for the 144 Pin LQFP

Signal Name	Pin No.	Type	State During Reset	Signal Description
HOME1	9	Schmitt Input	Input	Home — Quadrature Decoder 1 HOME input
(TB3)		Schmitt Input/ Output	Input	TB3 — Timer B Channel 3
(SS1)		Schmitt Input	Input	SPI 1 Slave Select — In the master mode, this pin is used to arbitrate multiple masters. In slave mode, this pin is used to select the slave. To activate the SPI function, set the HOME_ALT bit in the SIM_GPS register. For details, see Section 6.5.8.
(GPIOC3)		Schmitt Input/ Output	Input	Port C GPIO — This GPIO pin can be individually programmed as input or output pin.
		σαιραί		After reset, the default state is HOME1.
				To deactivate the internal pull-up resistor, clear bit 3 in the GPIOC_PUR register.
PWMA0	62	Output	Tri-State	PWMA0 - 5 — These are six PWMA outputs.
PWMA1	64			
PWMA2	65			
PWMA3	67			
PWMA4	68			
PWMA5	70			
ISA0 (GPIOC8)	113	Schmitt Input	Input	ISA0 - 2 — These three input current status pins are use for top/bottom pulse width correction in complementary channel operation for PWMA.
ISA1 (GPIOC9)	114	Schmitt		Port C GPIO — These GPIO pins can be individually
ISA2 (GPIOC10)	115	Input/ Output		programmed as input or output pins. At reset, these pins default to ISA functionality.
				Deactivate pull-up by setting the appropriate bit of the GPIOC_PUR register. For details, see Section 6.5.8 .
FAULTA0	71	Input	Schmitt	FAULTA0 - A2 — These three fault input pins are used for
FAULTtA1	73		Input	disabling selected PWMA outputs in cases where fault conditions originate off-chip.
FAULTA2	74			To deactivate the internal pull-up resistor, set the PWMA0 bit in the SIM_PUDR register. For details, see Section 6.5.8 .

Table 2-2 56F8346 Signal and Package Information for the 144 Pin LQFP

Signal Name	Pin No.	Type	State During Reset	Signal Description	
PWMB0	34	Output	Tri-State	PWMB0 - 5 — Six PWMB output pins.	
PWMB1	35				
PWMB2	36				
PWMB3	39				
PWMB4	40				
PWMB5	41				
ISB0 (GPIOD10)	50	Schmitt Input	Input	ISB0 - 2 — These three input current status pins are used for top/bottom pulse width correction in complementary	
ISB1 (GPIOD11)	52	Schmitt		channel operation for PWMB. Port D GPIO — These GPIO pins can be individually	
ISB2 (GPIOD12)	53	Input/ Output		programmed as input or output pins. At reset, these pins default to ISA functionality.	
				To deactivate the internal pull-up resistor, clear the appropriate bit of the GPIOD_PUR register. For details, see Section 6.5.8 .	
FAULTB0	56	Schmitt	Schmitt Input Input	FAULTB0 - 3 — These four fault input pins are used for disabling selected PWMB outputs in cases where fault conditions originate off-chip.	
FAULTB1	57	iriput			
FAULTB2	58			To deactivate the internal pull-up resistor, set the PWMB	
FAULTB3	61			bit in the SIM_PUDR register. For details, see Section 6.5.8 .	
ANA0	88	Input	Input	ANA0 - 3 — Analog inputs to ADC A, channel 0	
ANA1	89				
ANA2	90				
ANA3	91				
ANA4	92	Input	Input	ANA4 - 7 — Analog inputs to ADC A, channel 1	
ANA5	93				
ANA6	94				
ANA7	95				
V _{REFH}	101	Input	Input	V _{REFH} — Analog reference voltage high. V _{REFH} must be less than or equal to V _{DDA_ADC} .	

Table 2-2 56F8346 Signal and Package Information for the 144 Pin LQFP

Signal Name	Pin No.	Туре	State During Reset	Signal Description
V _{REFP}	100	I/O	I/O	V _{REFP} , V _{REFMID} & V _{REFN} — Internal pins for voltage
V _{REFMID}	99			reference which are brought off-chip so they can be bypassed. Connect to a 0.1µF or low ESR capacitor.
V _{REFN}	98			
V _{REFLO}	97	Input	Input	V _{REFLO} — Analog reference voltage low. This should normally be connected to a low-noise V _{SSA} .
ANB0	104	Input	Input	ANB0 - 3 — Analog inputs to ADC B, channel 0
ANB1	105			
ANB2	106			
ANB3	107			
ANB4	108	Input	Input	ANB4 - 7 — Analog inputs to ADC B, channel 1
ANB5	109			
ANB6	110			
ANB7	111			
Temp_Sense	96	Output	Output	Temp Sense Diode — This signal connects to an on-chip diode that can be connected to one of the ADC inputs and used to monitor the temperature of the die. Must be bypassed with a 0.01 μ F capacitor.
CAN_RX	127	Schmitt Input	Input	CAN Receive Data — This is the CAN input. This pin has an internal pull-up resistor. To deactivate the internal pull-up resistor, set the CAN bit in the SIM_PUDR register.
CAN_TX	126	Open Drain Output	Output	CAN Transmit Data — CAN output
тсо	118	Schmitt Input/ Output	Input	TC0 — Timer C Channel 0
(GPIOE8)		Schmitt Input/ Outpu		Port E GPIO — These GPIO pins can be individually programmed as input or output pins. To deactivate the internal pull-up resistor, clear bit 8 of the GPIOE_PUR register.

Table 2-2 56F8346 Signal and Package Information for the 144 Pin LQFP

Signal Name	Pin No.	Type	State During Reset	Signal Description
TD0 (GPIOE10)	116	Schmitt Input/ Output	Input	TD0 and TD1 — Timer D Channels 0 and 1
TD1 (GPIOE11)	117	Schmitt Input/ Output		Port E GPIO — These GPIO pins can be individually programmed as input or output pins. At reset, these pins default to Timer functionality. To deactivate the internal pull-up resistor, clear the appropriate bit of the GPIOE_PUR register. See Section 6.5.6 for details.
IRQA	54	Schmitt Input	Input	External Interrupt Request A and B — The IRQA and
IRQB	55	iriput		IRQB inputs are asynchronous external interrupt requests during Stop and Wait mode operation. During other operating modes, they are synchronized external interrupt requests, which indicate an external device is requesting service. They can be programmed to be level-sensitive or negative-edge-triggered. To deactivate the internal pull-up resistor, set the IRQ bit in the SIM_PUDR register. See Section 6.5.6 for details.
RESET	86	Schmitt Input	Input	Reset — This input is a direct hardware reset on the processor. When RESET is asserted low, the device is initialized and placed in the reset state. A Schmitt trigger input is used for noise immunity. When the RESET pin is deasserted, the initial chip operating mode is latched from the EXTBOOT pin. The internal reset signal will be deasserted synchronous with the internal clocks after a fixed number of internal clocks. To ensure complete hardware reset, RESET and TRST should be asserted together. The only exception occurs in a debugging environment when a hardware device reset is required and the JTAG/EOnCE module must not be reset. In this case, assert RESET but do not assert TRST. Note: The internal Power-On Reset will assert on initial power-up. To deactivate the internal pull-up resistor, set the RESET bit in the SIM_PUDR register. See Section 6.5.6 for details.
RSTO	85	Output	Output	Reset Output — This output reflects the internal reset state of the chip.

Table 2-2 56F8346 Signal and Package Information for the 144 Pin LQFP

Signal Name	Pin No.	Туре	State During Reset	Signal Description
EXTBOOT	112	Schmitt Input	Input	External Boot — This input is tied to V _{DD} to force the device to boot from off-chip memory (assuming that the on-chip Flash memory is not in a secure state). Otherwise, it is tied to ground. For details, see Table 4-4. Note: When this pin is tied low, the customer boot software should disable the internal pull-up resistor by setting the XBOOT bit of the SIM_PUDR; see Section 6.5.6.
EMI_MODE	143	Schmitt Input	Input	External Memory Mode — The EMI_MODE input is internally tied low (to V _{SS}). This device will boot from internal flash memory under normal operation. This function is also affected by EXTBOOT and the Flash security mode. For details, see Table 4-4. If a 20-bit address bus is not desired, then this pin is tied to ground. Note: When this pin is tied low, the customer boot software should disable the internal pull-up resistor by setting the EMI_MODE bit of the SIM_PUDR; see Section 6.5.6.

Part 3 On-Chip Clock Synthesis (OCCS)

3.1 Introduction

Refer to the OCCS chapter of the **56F8300 Peripheral User Manual** for a full description of the OCCS. The material contained here identifies the specific features of the OCCS design that apply to the 56F8346 part. **Figure 3-1** shows the specific OCCS block diagram to reference from the OCCS chapter in the **56F8300 Peripheral User Manual**.

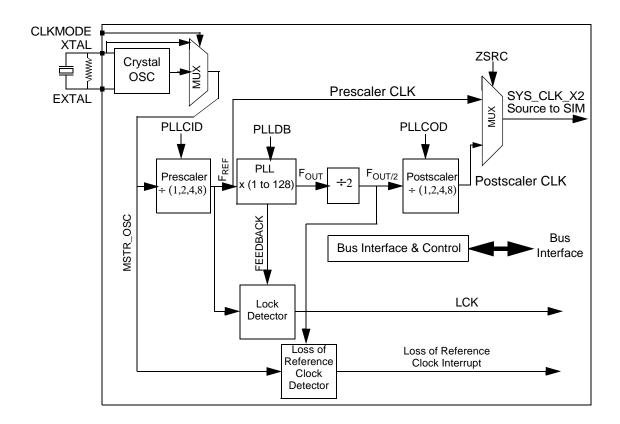


Figure 3-1 OCCS Block Diagram

3.2 External Clock Operation

The 56F8346 system clock can be derived from an external crystal, ceramic resonator, or an external system clock signal. To generate a reference frequency using the internal oscillator, a reference crystal or ceramic resonator, must be connected between the EXTAL and XTAL pins.

3.2.1 Crystal Oscillator

The internal oscillator is designed to interface with a parallel-resonant crystal resonator in the frequency range specified for the external crystal in **Table 10-16**. A recommended crystal oscillator circuit is shown in **Figure 3-2**. Follow the crystal supplier's recommendations when selecting a crystal, since crystal parameters determine the component values required to provide maximum stability and reliable start-up. The crystal and associated components should be mounted as close as possible to the EXTAL and XTAL pins to minimize output distortion and start-up stabilization time.

Crystal Frequency = 4 - 8MHz (optimized for 8MHz)

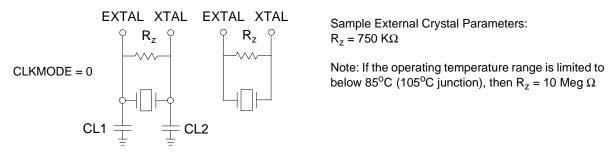


Figure 3-2 Connecting to a Crystal Oscillator

Note: The OCCS_COHL bit should be set to 1 when a crystal oscillator is used. The reset condition on the OCCS_COHL bit is 0. Please see the COHL bit in the Oscillator Control (OSCTL) register, discussed in Section 5 of the **56F8300 Peripheral User Manual**.

3.2.2 Ceramic Resonator (Default)

It is also possible to drive the internal oscillator with a ceramic resonator, assuming the overall system design can tolerate the reduced signal integrity. A typical ceramic resonator circuit is shown in **Figure 3-3**. Refer to supplier's recommendations when selecting a ceramic resonator and associated components. The resonator and components should be mounted as close as possible to the EXTAL and XTAL pins.

Resonator Frequency = 4 - 8MHz (optimized for 8MHz)

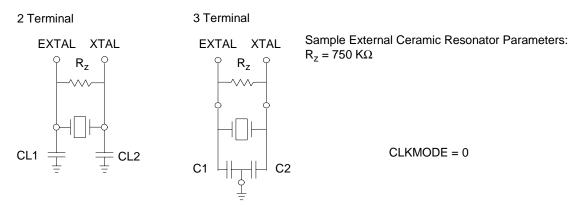
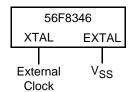


Figure 3-3 Connecting a Ceramic Resonator

Note: The OCCS_COHL bit must set to 0 when a ceramic resonator is used. The reset condition on the OCCS_COHL bit is 0. Please see the COHL bit in the Oscillator Control (OSCTL) register, discussed in Section 5 of the **56F8300 Peripheral User Manual**.

3.2.3 External Clock Source

The recommended method of connecting an external clock is given in **Figure 3-4**. The external clock source is connected to XTAL and the EXTAL pin is grounded. Set OCCS_COHL bit high when using an external clock source as well.



Note: When using an external clocking source with this configuration, the input "CLKMODE" should be high and the COHL bit in the OSCTL register should be set to 1.

Figure 3-4 Connecting an External Clock Signal

3.3 Registers

When referring to the register definitions for the OCCS in the **56F8300 Peripheral User Manual**, use the register definitions **without** the internal Relaxation Oscillator, since the 56F8346 does NOT contain this oscillator.

Part 4 Memory Map

4.1 Introduction

The 56F8346 device is a 16-bit motor-control chip based on the 56800E core. It uses a Harvard-style architecture with two independent memory spaces for data and program. On-chip RAM and Flash memories are used in both spaces.

This section provides memory maps for:

- Program Address Space, including the Interrupt Vector Table
- Data Address Space, including the EOnCE Memory and Peripheral Memory Maps

On-chip memory sizes for each device are summarized in **Table 4-1**. Flash memories' restrictions are identified in the "Use Restrictions" column of **Table 4-1**.

On-Chip Memory	56F8346	Use Restrictions
Program Flash	128KB	Erase/Program via Flash interface unit and word writes to CDBW
Data Flash	8KB	Erase/Program via Flash interface unit and word writes to CDBW. Data Flash can be read via either CDBR or XDB2, but not by both simultaneously
Program RAM	4KB	None
Data RAM	8KB	None
Program Boot Flash	8KB	Erase/Program via Flash Interface unit and word to CDBW

Table 4-1 Chip Memory Configurations

4.2 Program Map

The operating mode control bits (MA and MB) in the Operating Mode Register (OMR) control the Program memory map. At reset, these bits are set as indicated in **Table 4-2**. **Table 4-4** shows the memory map configurations that are possible at reset. After reset, the OMR MA bit can be changed and will have an effect on the P-space memory map, as shown in **Table 4-3**. Changing the OMR MB bit will have no effect.

OMR MB = Flash Secured State ^{1, 2}	OMR MA = EXTBOOT Pin	Chip Operating Mode	
0	0	Mode 0 – Internal Boot; EMI is configured to use 16 address lines; Flash Memory is secured; external P-space is not allowed; the EOnCE is disabled	
0	1	Not valid; cannot boot externally if the Flash is secured and will actually configure to 00 state	
1	0	Mode 0 – Internal Boot; EMI is configured to use 16 address lines	
1	1	Mode 1 – External Boot; Flash Memory is not secured; EMI configuration is determined by the state of the EMI_MODE bit	

Table 4-2 OMR MA/MB Value at Reset

^{1.} This bit is only configured at reset. If the Flash secured state changes, this will not be reflected in MB until the next reset.

^{2.} Changing MB in software will not affect Flash memory security.

Table 4-3 Changing OMR MA Value During Normal Operation

OMR MA	Chip Operating Mode		
0	Use internal P-space memory map configuration		
1	Use external P-space memory map configuration – If MB = 0 at reset, changing this bit has no effect.		

The 56F8346's external memory interface (EMI) can operate much like the 56F80x family's EMI, or it can be operated in a mode similar to that used on other products in the 56800E family. Initially, CS0 and CS1 are configured as PS and DS, in a mode compatible with earlier 56800 devices.

Eighteen address lines are required to shadow the first 192K of internal program space when booting externally for development purposes. Therefore, the entire complement of on-chip memory cannot be accessed using a 16-bit 56800-compatible address bus. To address this situation, the EMI_MODE pin can be used to configure four GPIO pins as Address[19:16] upon reset (only one of these pins [A16] is usable in the 56F8346).

The EMI_MODE pin also affects the reset vector address, as provided in **Table 4-4.** Additional pins must be configured as address or chip select signals to access addresses at P:\$10 0000 and above.

Table 4-4 Program Memory Map at Reset

	Mode 0 (MA = 0)	Mode 1 ¹ (MA = 1) External Boot		
Begin/End Address	Internal Boot			
	Internal Boot 16-Bit External Address Bus	EMI_MODE = 0 ² , ³ 16-Bit External Address Bus	EMI_MODE = 1 ⁴ 20-Bit External Address Bus	
P:\$1F FFFF P:\$10 0000	External Program Memory ⁵	External Program Memory ⁵	External Program Memory ⁵	
P:\$0F FFFF P:\$03 0000			External Program RAM	
P:\$02 FFFF P:\$02 F800	On-Chip Pr 4ł			
P:\$02 F7FF P:\$02 1000	Rese 116			
P:\$02 0FFF P:\$02 0000	Boot Flash 8KB COP Reset Address = 02 0002 Boot Location = 02 0000	Boot Flash 8KB (Not Used for Boot in this Mode)	COP Reset Address = 02 0002 ⁶ Boot Location = 02 0000 ⁶	
P:\$01 FFFF P:\$01 0000	External Program RAM ⁵	Internal Program Flash ⁷ 128KB		
P:\$00 FFFF P:\$00 0000	Internal Program Flash 128KB	External Program RAM COP Reset Address = 00 0002 Boot Location = 00 0000		

^{1.} If Flash Security Mode is enabled EXTBOOT Mode 1 cannot be used. See Security Features, Part 7.

^{2.} This mode provides maximum compatibility with 56F80x parts while operating externally.

^{3. &}quot;EMI_MODE =0" when EMI_MODE pin is tied to ground at boot up.

- 4. "EMI_MODE =1" when EMI_MODE pin is tied to V_{DD} at boot up.
- 5. Not accessible in reset configuration since the address is above P:\$00 FFFF. The higher bit address/GPIO (and/or chip selects) pins must be reconfigured before this external memory is accessible.
- 6. Booting from this external address allows prototyping of the internal Boot Flash.
- 7. The internal Program Flash is relocated in this mode making it accessible.

4.3 Interrupt Vector Table

Table 4-5 provides the reset and interrupt priority structure, including on-chip peripherals. The table is organized with higher-priority vectors at the top and lower-priority interrupts lower in the table. The priority of an interrupt can be assigned to different levels, as indicated, allowing some control over interrupt priorities. All level 3 interrupts will be serviced before level 2, and so on. For a selected priority level, the lowest vector number has the highest priority.

The location of the vector table is determined by the Vector Base Address (VBA) register. Please see **Section 5.6.12** for the reset value of the VBA.

In some configurations, the reset address and COP reset address will correspond to vector 0 and 1 of the interrupt vector table. In these instances, the first two locations in the vector table must contain branch or JMP instructions. All other entries must contain JSR instructions.

Table 4-5 Interrupt Vector Table Contents¹

Peripheral	Vector Number	Priority Level	Vector Base Address +	Interrupt Function
				Reserved for Reset Overlay ²
				Reserved for COP Reset Overlay ²
core	2	3	P:\$04	Illegal Instruction
core	3	3	P:\$06	SW Interrupt 3
core	4	3	P:\$08	HW Stack Overflow
core	5	3	P:\$0A	Misaligned Long Word Access
core	6	1-3	P:\$0C	OnCE Step Counter
core	7	1-3	P:\$0E	OnCE Breakpoint Unit 0
				Reserved
core	9	1-3	P:\$12	OnCE Trace Buffer
core	10	1-3	P:\$14	OnCE Transmit Register Empty
core	11	1-3	P:\$16	OnCE Receive Register Full
				Reserved
				Reserved
core	14	2	P:\$1C	SW Interrupt 2
core	15	1	P:\$1E	SW Interrupt 1
core	16	0	P:\$20	SW Interrupt 0
core	17	0-2	P:\$22	IRQA
core	18	0-2	P:\$24	IRQB

Table 4-5 Interrupt Vector Table Contents¹ (Continued)

Peripheral	Vector Number	Priority Level	Vector Base Address +	Interrupt Function
				Reserved
LVI	20	0-2	P:\$28	Low Voltage Detector (power sense)
PLL	21	0-2	P:\$2A	PLL
FM	22	0-2	P:\$2C	FM Error Interrupt
FM	23	0-2	P:\$2E	FM Command Complete
FM	24	0-2	P:\$30	FM Command, data and address Buffers Empty
				Reserved
FLEXCAN	26	0-2	P:\$34	FLEXCAN Bus Off
FLEXCAN	27	0-2	P:\$36	FLEXCAN Error
FLEXCAN	28	0-2	P:\$38	FLEXCAN Wake Up
FLEXCAN	29	0-2	P:\$3A	FLEXCAN Message Buffer Interrupt
GPIOF	30	0-2	P:\$3C	GPIO F
GPIOE	31	0-2	P:\$3E	GPIO E
GPIOD	32	0-2	P:\$40	GPIO D
GPIOC	33	0-2	P:\$42	GPIO C
GPIOB	34	0-2	P:\$44	GPIO B
GPIOA	35	0-2	P:\$46	GPIO A
				Reserved
				Reserved
SPI1	38	0-2	P:\$4C	SPI 1 Receiver Full
SPI1	39	0-2	P:\$4E	SPI 1 Transmitter Empty
SPI0	40	0-2	P:\$50	SPI 0 Receiver Full
SPI0	41	0-2	P:\$52	SPI 0 Transmitter Empty
SCI1	42	0-2	P:\$54	SCI 1 Transmitter Empty
SCI1	43	0-2	P:\$56	SCI 1Transmitter Idle
				Reserved
SCI1	45	0-2	P:\$5A	SCI 1 Receiver Error
SCI1	46	0-2	P:\$5C	SCI 1 Receiver Full
DEC1	47	0-2	P:\$5E	Quadrature Decoder #1 Home Switch or Watchdog
DEC1	48	0-2	P:\$60	Quadrature Decoder #1 INDEX Pulse
DEC0	49	0-2	P:\$62	Quadrature Decoder #0 Home Switch or Watchdog
DEC0	50	0-2	P:\$64	Quadrature Decoder #0 INDEX Pulse
				Reserved
TMRD	52	0-2	P:\$68	Timer D Channel 0
TMRD	53	0-2	P:\$6A	Timer D Channel 1

Table 4-5 Interrupt Vector Table Contents¹ (Continued)

Peripheral	Vector Number	Priority Level	Vector Base Address +	Interrupt Function
TMRD	54	0-2	P:\$6C	Timer D Channel 2
TMRD	55	0-2	P:\$6E	Timer D Channel 3
TMRC	56	0-2	P:\$70	Timer C Channel 0
TMRC	57	0-2	P:\$72	Timer C Channel 1
TMRC	58	0-2	P:\$74	Timer C Channel 2
TMRC	59	0-2	P:\$76	Timer C Channel 3
TMRB	60	0-2	P:\$78	Timer B Channel 0
TMRB	61	0-2	P:\$7A	Timer B Channel 1
TMRB	62	0-2	P:\$7C	Timer B Channel 2
TMRB	63	0-2	P:\$7E	Timer B Channel 3
TMRA	64	0-2	P:\$80	Timer A Channel 0
TMRA	65	0-2	P:\$82	Timer A Channel 1
TMRA	66	0-2	P:\$84	Timer A Channel 2
TMRA	67	0-2	P:\$86	Timer A Channel 3
SCI0	68	0-2	P:\$88	SCI 0 Transmitter Empty
SCI0	69	0-2	P:\$8A	SCI 0 Transmitter Idle
				Reserved
SCI0	71	0-2	P:\$8E	SCI 0 Receiver Error
SCI0	72	0-2	P:\$90	SCI 0 Receiver Full
ADCB	73	0-2	P:\$92	ADC B Conversion Compete
ADCA	74	0-2	P:\$94	ADC A Conversion Complete
ADCB	75	0-2	P:\$96	ADC B Zero Crossing of Limit Error
ADCA	76	0-2	P:\$98	ADC A Zero Crossing of Limit Error
PWMB	77	0-2	P:\$9A	Reload PWM B
PWMA	78	0-2	P:\$9C	Reload PWM A
PWMB	79	0-2	P:\$9E	PWM B Fault
PWMA	80	0-2	P:\$A0	PWM A Fault
core	81	- 1	P:\$A2	SW Interrupt LP

^{1.} Two words are allocated for each entry in the Vector table. This does not allow the full address range to be referenced from the Vector table, providing only 19 bits of address.

^{2.} If the VBA is set to 0200 (or VBA = 0000 for Mode 1, EMI_MODE = 0), the first two locations of the vector table are the chip reset addresses; therefore, these locations are not interrupt vectors.

4.4 Data Map

Table 4-6 Data Memory Map¹

Begin/End Address	EX = 0 ²	EX = 1
X:\$FF FFFF X:\$FF FF00	EOnCE 256 locations allocated	EOnCE 256 locations allocated
X:\$FF FEFF X:\$01 0000	External Memory	External Memory
X:\$00 FFFF X:\$00 F000	On-Chip Peripherals 4096 location allocated	On-Chip Peripherals 4096 location allocated
X:\$00 EFFF X:\$00 2000	External Memory	External Memory
X:\$00 1FFF X:\$00 1000	On-Chip Data Flash 8KB	
X:\$00 0FFF X:\$00 0000	On-Chip Data RAM 8KB ³	

- 1. All addresses are 16-bit Word addresses, not byte addresses.
- 2. In the Operation Mode Register (OMR).
- 3. The Data RAM is organized as a 2K x 32-bit memory to allow single-cycle long-word operations.

4.5 Flash Memory Map

Figure 4-1 illustrates the Flash Memory (FM) map on the system bus.

The Flash Memory is divided into three functional blocks. The Program and boot memories reside on the Program Memory buses. They are controlled by one set of banked registers. Data Memory Flash resides on the Data Memory buses and is controlled separately, having its own set of banked registers.

The top nine words of the Program Memory Flash are treated as special memory locations. The content of these words is used to control the operation of the Flash Controller. Because these words are part of the Flash Memory content, their state is maintained during power-down and reset. During chip initialization, the content of these memory locations is loaded into Flash Memory control registers, detailed in the Flash Memory chapter of the **56F8300 Peripheral User Manual**. In the 56F8346, these configuration parameters are located between \$00_FFF7 and \$00_FFFF.

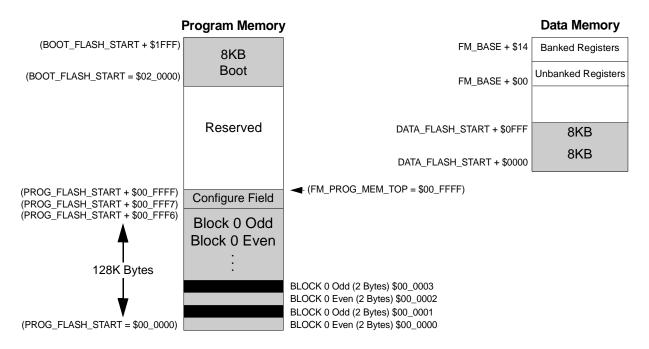


Figure 4-1 Flash Array Memory Maps

Table 4-7 shows the page and sector sizes used within each Flash memory block on the chip.

Table 4-7. Flash Memory Partitions

	Flash Size	Sectors	Sector Size	Page Size
Program Flash	128KB	16	4K x 16 bits	512 x 16 bits
Data Flash	8KB	16	256 x 16 bits	256 x 16 bits
Boot Flash	8KB	4	1K x 16 bits	256 x 16 bits

Please see **56F8300 Peripheral User Manual** for additional Flash information.

4.6 EOnCE Memory Map

Table 4-8 EOnCE Memory Map

Address	Register Acronym	Register Name
		Reserved
X:\$FF FF8A	OESCR	External Signal Control Register
		Reserved
X:\$FF FF8E	OBCNTR	Breakpoint Unit [0] Counter
		Reserved
X:\$FF FF90	OBMSK (32 bits)	Breakpoint 1 Unit [0] Mask Register
X:\$FF FF91	_	Breakpoint 1 Unit [0] Mask Register
X:\$FF FF92	OBAR2 (32 bits)	Breakpoint 2 Unit [0] Address Register
X:\$FF FF93	_	Breakpoint 2 Unit [0] Address Register
X:\$FF FF94	OBAR1 (24 bits)	Breakpoint 1 Unit [0] Address Register
X:\$FF FF95	_	Breakpoint 1 Unit [0] Address Register
X:\$FF FF96	OBCR (24 bits)	Breakpoint Unit [0] Control Register
X:\$FF FF97	_	Breakpoint Unit [0] Control Register
X:\$FF FF98	OTB (21-24 bits/stage)	Trace Buffer Register Stages
X:\$FF FF99	_	Trace Buffer Register Stages
X:\$FF FF9A	OTBPR (8 bits)	Trace Buffer Pointer Register
X:\$FF FF9B	OTBCR	Trace Buffer Control Register
X:\$FF FF9C	OBASE (8 bits)	Peripheral Base Address Register
X:\$FF FF9D	OSR	Status Register
X:\$FF FF9E	OSCNTR (24 bits)	Instruction Step Counter
X:\$FF FF9F	_	Instruction Step Counter
:X:\$FF FFA0	OCR (bits)	Control Register
		Reserved
X:\$FF FFFC	OCLSR (8 bits)	Core Lock/Unlock Status Register
X:\$FF FFFD	OTXRXSR (8 bits)	Transmit and Receive Status and Control Register
X:\$FF FFFE	OTX/ORX (32 bits)	Transmit Register / Receive Register
X:\$FF FFFF	OTX1/ORX1	Transmit Register Upper Word Receive Register Upper Word

4.7 Peripheral Memory Mapped Registers

On-chip peripheral registers are part of the data memory map on the 56800E series. These locations may be accessed with the same addressing modes used for ordinary data memory, except all peripheral registers should be read/written using word accesses only.

Table 4-9 summarizes base addresses for the set of peripherals on the 56F8346 device. Peripherals are listed in order of the base address.

The following tables list all of the peripheral registers required to control or access the peripherals.

Table 4-9 Data Memory Peripheral Base Address Map Summary

Peripheral	Prefix	Base Address	Table Number
External Memory Interface	EMI	X:\$00 F020	4-10
Timer A	TMRA	X:\$00 F040	4-11
Timer B	TMRB	X:\$00 F080	4-12
Timer C	TMRC	X:\$00 F0C0	4-13
Timer D	TMRD	X:\$00 F100	4-14
PWM A	PWMA	X:\$00 F140	4-15
PWM B	PWMB	X:\$00 F160	4-16
Quadrature Decoder 0	DEC0	X:\$00 F180	4-17
Quadrature Decoder 1	DEC1	X:\$00 F190	4-18
ITCN	ITCN	X:\$00 F1A0	4-19
ADC A	ADCA	X:\$00 F200	4-20
ADC B	ADCB	X:\$00 F240	4-21
Temperature Sensor	TSENSOR	X:\$00 F270	4-22
SCI #0	SCI0	X:\$00 F280	4-23
SCI #1	SCI1	X:\$00 F290	4-24
SPI#0	SPI0	X:\$00 F2A0	4-25
SPI #1	SPI1	X:\$00 F2B0	4-26
COP	COP	X:\$00 F2C0	4-27
PLL, OSC	CLKGEN	X:\$00 F2D0	4-28
GPIO Port A	GPIOA	X:\$00 F2E0	4-29
GPIO Port B	GPIOB	X:\$00 F300	4-30
GPIO Port C	GPIOC	X:\$00 F310	4-31
GPIO Port D	GPIOD	X:\$00 F320	4-32
GPIO Port E	GPIOE	X:\$00 F330	4-33
GPIO Port F	GPIOF	X:\$00 F340	4-34
SIM	SIM	X:\$00 F350	4-35
Power Supervisor	LVI	X:\$00 F360	4-36
FM	FM	X:\$00 F400	4-37
FlexCAN	FC	X:\$00 F800	4-38

Table 4-10 External Memory Integration Registers Address Map (EMI_BASE = \$00F020)

Register Acronym	Address Offset	Register Description	Reset Value
CSBAR 0	\$0	Chip Select Base Address Register 0	
CSBAR 1	\$1	Chip Select Base Address Register 1	
CSBAR 2	\$2	Chip Select Base Address Register 2	
CSBAR 3	\$3	Chip Select Base Address Register 3	
CSBAR 4	\$4	Chip Select Base Address Register 4	
CSBAR 5	\$5	Chip Select Base Address Register 5	
CSBAR 6	\$6	Chip Select Base Address Register 6	
CSBAR 7	\$7	Chip Select Base Address Register 7	
CSOR 0	\$8	Chip Select Option Register 0	0x5FCB programmed for chip select for program space, word wide, read and write, 11 waits
CSOR 1	\$9	Chip Select Option Register 1	0x5FAB programmed for chip select for data space, word wide, read and write, 11 waits
CSOR 2	\$A	Chip Select Option Register 2	
CSOR 3	\$B	Chip Select Option Register 3	
CSOR 4	\$C	Chip Select Option Register 4	
CSOR 5	\$D	Chip Select Option Register 5	
CSOR 6	\$E	Chip Select Option Register 6	
CSOR 7	\$F	Chip Select Option Register 7	
CSTC 0	\$10	Chip Select Timing Control Register 0	
CSTC 1	\$11	Chip Select Timing Control Register 1	
CSTC 2	\$12	Chip Select Timing Control Register 2	
CSTC 3	\$13	Chip Select Timing Control Register 3	
CSTC 4	\$14	Chip Select Timing Control Register 4	
CSTC 5	\$15	Chip Select Timing Control Register 5	
CSTC 6	\$16	Chip Select Timing Control Register 6	
CSTC 7	\$17	Chip Select Timing Control Register 7	
BCR	\$18	Bus Control Register	0x016B sets the default number of wait states to 11 for both read and write accesses

Table 4-11 Quad Timer A Registers Address Map (TMRA_BASE = \$00F040)

Register Acronym	Address Offset	Register Description
TMRA0_CMP1	\$0	
_	•	Compare Register 1
TMRA0_CMP2	\$1 	Compare Register 2
TMRA0_CAP	\$2	Capture Register
TMRA0_LOAD	\$3	Load Register
TMRA0_HOLD	\$4	Hold Register
TMRA0_CNTR	\$5	Counter Register
TMRA0_CTRL	\$6	Control Register
TMRA0_SCR	\$7	Status and Control Register
TMRA0_CMPLD1	\$8	Comparator Load Register 1
TMRA0_CMPLD2	\$9	Comparator Load Register 2
TMRA0_COMSCR	\$A	Comparator Status and Control Register
		Reserve
TMRA1_CMP1	\$10	Compare Register 1
TMRA1_CMP2	\$11	Compare Register 2
TMRA1_CAP	\$12	Capture Register
TMRA1_LOAD	\$13	Load Register
TMRA1_HOLD	\$14	Hold Register
TMRA1_CNTR	\$15	Counter Register
TMRA1_CTRL	\$16	Control Register
TMRA1_SCR	\$17	Status and Control Register
TMRA1_CMPLD1	\$18	Comparator Load Register 1
TMRA1_CMPLD2	\$19	Comparator Load Register 2
TMRA1_COMSCR	\$1A	Comparator Status and Control Register
		Reserved
TMRA2_CMP1	\$20	Compare Register 1
TMRA2_CMP2	\$21	Compare Register 2
TMRA2_CAP	\$22	Capture Register
TMRA2_LOAD	\$23	Load Register
TMRA2_HOLD	\$24	Hold Register
TMRA2_CNTR	\$25	Counter Register
TMRA2_CTRL	\$26	Control Register
TMRA2_SCR	\$27	Status and Control Register
TMRA2_CMPLD1	\$28	Comparator Load Register 1
TMRA2_CMPLD2	\$29	Comparator Load Register 2
TMRA2_COMSCR	\$2A	Comparator Status and Control Register

Table 4-11 Quad Timer A Registers Address Map (TMRA_BASE = \$00F040) (Continued)

Register Acronym	Address Offset	Register Description
		Reserved
TMRA3_CMP1	\$30	Compare Register 1
TMRA3_CMP2	\$31	Compare Register 2
TMRA3_CAP	\$32	Capture Register
TMRA3_LOAD	\$33	Load Register
TMRA3_HOLD	\$34	Hold Register
TMRA3_CNTR	\$35	Counter Register
TMRA3_CTRL	\$36	Control Register
TMRA3_SCR	\$37	Status and Control Register
TMRA3_CMPLD1	\$38	Comparator Load Register 1
TMRA3_CMPLD2	\$39	Comparator Load Register 2
TMRA3_COMSC	\$3A	Comparator Status and Control Register

Table 4-12 Quad Timer B Registers Address Map (TMRB_BASE = \$00F080)

Register Acronym	Address Offset	Register Description
TMRB0_CMP1	\$0	Compare Register 1
TMRB0_CMP2	\$1	Compare Register 2
TMRB0_CAP	\$2	Capture Register
TMRB0_LOAD	\$3	Load Register
TMRB0_HOLD	\$4	Hold Register
TMRB0_CNTR	\$5	Counter Register
TMRB0_CTRL	\$6	Control Register
TMRB0_SCR	\$7	Status and Control Register
TMRB0_CMPLD1	\$8	Comparator Load Register 1
TMRB0_CMPLD2	\$9	Comparator Load Register 2
TMRB0_COMSCR	\$A	Comparator Status and Control Register
		Reserved
TMRB1_CMP1	\$10	Compare Register 1
TMRB1_CMP2	\$11	Compare Register 2
TMRB1_CAP	\$12	Capture Register
TMRB1_LOAD	\$13	Load Register
TMRB1_HOLD	\$14	Hold Register
TMRB1_CNTR	\$15	Counter Register
TMRB1_CTRL	\$16	Control Register
TMRB1_SCR	\$17	Status and Control Register

Table 4-12 Quad Timer B Registers Address Map (TMRB_BASE = \$00F080) (Continued)

Register Acronym	Address Offset	Register Description
TMRB1_CMPLD1	\$18	Comparator Load Register 1
TMRB1_CMPLD2	\$19	Comparator Load Register 2
TMRB1_COMSCR	\$1A	Comparator Status and Control Register
		Reserved
TMRB2_CMP1	\$20	Compare Register 1
TMRB2_CMP2	\$21	Compare Register 2
TMRB2_CAP	\$22	Capture Register
TMRB2_LOAD	\$23	Load Register
TMRB2_HOLD	\$24	Hold Register
TMRB2_CNTR	\$25	Counter Register
TMRB2_CTRL	\$26	Control Register
TMRB2_SCR	\$27	Status and Control Register
TMRB2_CMPLD1	\$28	Comparator Load Register 1
TMRB2_CMPLD2	\$29	Comparator Load Register 2
TMRB2_COMSCR	\$2A	Comparator Status and Control Register
		Reserved
TMRB3_CMP1	\$30	Compare Register 1
TMRB3_CMP2	\$31	Compare Register 2
TMRB3_CAP	\$32	Capture Register
TMRB3_LOAD	\$33	Load Register
TMRB3_HOLD	\$34	Hold Register
TMRB3_CNTR	\$35	Counter Register
TMRB3_CTRL	\$36	Control Register
TMRB3_SCR	\$37	Status and Control Register
TMRB3_CMPLD1	\$38	Comparator Load Register 1
TMRB3_CMPLD2	\$39	Comparator Load Register 2
TMRB3_COMSCR	\$3A	Comparator Status and Control Register

Table 4-13 Quad Timer C Registers Address Map (TMRC_BASE = \$00F0C0)

B	\	, T
Register Acronym	Address Offset	Register Description
TMRC0_CMP1	\$0	Compare Register 1
TMRC0_CMP2	\$1	Compare Register 2
TMRC0_CAP	\$2	Capture Register
TMRC0_LOAD	\$3	Load Register
TMRC0_HOLD	\$4	Hold Register
TMRC0_CNTR	\$5	Counter Register
TMRC0_CTRL	\$6	Control Register
TMRC0_SCR	\$7	Status and Control Register
TMRC0_CMPLD1	\$8	Comparator Load Register 1
TMRC0_CMPLD2	\$9	Comparator Load Register 2
TMRC0_COMSCR	\$A	Comparator Status and Control Register
		Reserved
TMRC1_CMP1	\$10	Compare Register 1
TMRC1_CMP2	\$11	Compare Register 2
TMRC1_CAP	\$12	Capture Register
TMRC1_LOAD	\$13	Load Register
TMRC1_HOLD	\$14	Hold Register
TMRC1_CNTR	\$15	Counter Register
TMRC1_CTRL	\$16	Control Register
TMRC1_SCR	\$17	Status and Control Register
TMRC1_CMPLD1	\$18	Comparator Load Register 1
TMRC1_CMPLD2	\$19	Comparator Load Register 2
TMRC1_COMSCR	\$1A	Comparator Status and Control Register
		Reserved
TMRC2_CMP1	\$20	Compare Register 1
TMRC2_CMP2	\$21	Compare Register 2
TMRC2_CAP	\$22	Capture Register
TMRC2_LOAD	\$23	Load Register
TMRC2_HOLD	\$24	Hold Register
TMRC2_CNTR	\$25	Counter Register
TMRC2_CTRL	\$26	Control Register
TMRC2_SCR	\$27	Status and Control Register
TMRC2_CMPLD1	\$28	Comparator Load Register 1
TMRC2_CMPLD2	\$29	Comparator Load Register 2
<u> </u>	i	

Table 4-13 Quad Timer C Registers Address Map (TMRC_BASE = \$00F0C0) (Continued)

Register Acronym	Address Offset	Register Description
TMRC2_COMSCR	\$2A	Comparator Status and Control Register
		Reserved
TMRC3_CMP1	\$30	Compare Register 1
TMRC3_CMP2	\$31	Compare Register 2
TMRC3_CAP	\$32	Capture Register
TMRC3_LOAD	\$33	Load Register
TMRC3_HOLD	\$34	Hold Register
TMRC3_CNTR	\$35	Counter Register
TMRC3_CTRL	\$36	Control Register
TMRC3_SCR	\$37	Status and Control Register
TMRC3_CMPLD1	\$38	Comparator Load Register 1
TMRC3_CMPLD2	\$39	Comparator Load Register 2
TMRC3_COMSCR	\$3A	Comparator Status and Control Register

Table 4-14 Quad Timer D Registers Address Map (TMRD_BASE = \$00F100)

Register Acronym	Address Offset	Register Description
TMRD0_CMP1	\$0	Compare Register 1
TMRD0_CMP2	\$1	Compare Register 2
TMRD0_CAP	\$2	Capture Register
TMRD0_LOAD	\$3	Load Register
TMRD0_HOLD	\$4	Hold Register
TMRD0_CNTR	\$5	Counter Register
TMRD0_CTRL	\$6	Control Register
TMRD0_SCR	\$7	Status and Control Register
TMRD0_CMPLD1	\$8	Comparator Load Register 1
TMRD0_CMPLD2	\$9	Comparator Load Register 2
TMRD0_COMSCR	\$A	Comparator Status and Control Register
		Reserved
TMRD1_CMP1	\$10	Compare Register 1
TMRD1_CMP2	\$11	Compare Register 2
TMRD1_CAP	\$12	Capture Register
TMRD1_LOAD	\$13	Load Register
TMRD1_HOLD	\$14	Hold Register
TMRD1_CNTR	\$15	Counter Register
TMRD1_CTRL	\$16	Control Register

Table 4-14 Quad Timer D Registers Address Map (TMRD_BASE = \$00F100) (Continued)

Register Acronym	Address Offset	Register Description
TMRD1_SCR	\$17	Status and Control Register
TMRD1_CMPLD1	\$18	Comparator Load Register 1
TMRD1_CMPLD2	\$19	Comparator Load Register 2
TMRD1_COMSCR	\$1A	Comparator Status and Control Register
		Reserved
TMRD2_CMP1	\$20	Compare Register 1
TMRD2_CMP2	\$21	Compare Register 2
TMRD2_CAP	\$22	Capture Register
TMRD2_LOAD	\$23	Load Register
TMRD2_HOLD	\$24	Hold Register
TMRD2_CNTR	\$25	Counter Register
TMRD2_CTRL	\$26	Control Register
TMRD2_SCR	\$27	Status and Control Register
TMRD2_CMPLD1	\$28	Comparator Load Register 1
TMRD2_CMPLD2	\$29	Comparator Load Register 2
TMRD2_COMSCR	\$2A	Comparator Status and Control Register
		Reserved
TMRD3_CMP1	\$30	Compare Register 1
TMRD3_CMP2	\$31	Compare Register 2
TMRD3_CAP	\$32	Capture Register
TMRD3_LOAD	\$33	Load Register
TMRD3_HOLD	\$34	Hold Register
TMRD3_CNTR	\$35	Counter Register
TMRD3_CTRL	\$36	Control Register
TMRD3_SCR	\$37	Status and Control Register
TMRD3_CMPLD1	\$38	Comparator Load Register 1
TMRD3_CMPLD2	\$39	Comparator Load Register 2
TMRD3_COMSCR	\$3A	Comparator Status and Control Register

Table 4-15 Pulse Width Modulator A Registers Address Map (PWMA_BASE = \$00F140)

Register Acronym	Address Offset	Register Description
PWMA_PMCTL	\$0	Control Register
PWMA_PMFCTL	\$1	Fault Control Register
PWMA_PMFSA	\$2	Fault Status Acknowledge Register
PWMA_PMOUT	\$3	Output Control Register
PWMA_PMCNT	\$4	Counter Register
PWMA_PWMCM	\$5	Counter Modulo Register
PWMA_PWMVAL0	\$6	Value Register 0
PWMA_PWMVAL1	\$7	Value Register 1
PWMA_PWMVAL2	\$8	Value Register 2
PWMA_PWMVAL3	\$9	Value Register 3
PWMA_PWMVAL4	\$A	Value Register 4
PWMA_PWMVAL5	\$B	Value Register 5
PWMA_PMDEADTM	\$C	Dead Time Register
PWMA_PMDISMAP1	\$D	Disable Mapping Register 1
PWMA_PMDISMAP2	\$E	Disable Mapping Register 2
PWMA_PMCFG	\$F	Configure Register
PWMA_PMCCR	\$10	Channel Control Register
PWMA_PMPORT	\$11	Port Register
PWMA_PMICCR	\$12	PWM Internal Correction Control Register

Table 4-16 Pulse Width Modulator B Registers Address Map (PWMB_BASE = \$00F160)

Register Acronym	Address Offset	Register Description
PWMB_PMCTL	\$0	Control Register
PWMB_PMFCTL	\$1	Fault Control Register
PWMB_PMFSA	\$2	Fault Status Acknowledge Register
PWMB_PMOUT	\$3	Output Control Register
PWMB_PMCNT	\$4	Counter Register
PWMB_PWMCM	\$5	Counter Modulo Register
PWMB_PWMVAL0	\$6	Value Register 0
PWMB_PWMVAL1	\$7	Value Register 1
PWMB_PWMVAL2	\$8	Value Register 2
PWMB_PWMVAL3	\$9	Value Register 3
PWMB_PWMVAL4	\$A	Value Register 4
PWMB_PWMVAL5	\$B	Value Register 5
PWMB_PMDEADTM	\$C	Dead Time Register
PWMB_PMDISMAP1	\$D	Disable Mapping Register 1
PWMB_PMDISMAP2	\$E	Disable Mapping Register 2
PWMB_PMCFG	\$F	Configure Register
PWMB_PMCCR	\$10	Channel Control Register
PWMB_PMPORT	\$11	Port Register
PWMB_PMICCR	\$12	PWM Internal Correction Control Register

Table 4-17 Quadrature Decoder 0 Registers Address Map (DEC0_BASE = \$00F180)

Register Acronym	Address Offset	Register Description
DEC0_DECCR	\$0	Decoder Control Register
DEC0_FIR	\$1	Filter Interval Register
DEC0_WTR	\$2	Watchdog Timeout Register
DEC0_POSD	\$3	Position Difference Counter Register
DEC0_POSDH	\$4	Position Difference Counter Hold Register
DEC0_REV	\$5	Revolution Counter Register
DEC0_REVH	\$6	Revolution Hold Register
DEC0_UPOS	\$7	Upper Position Counter Register
DEC0_LPOS	\$8	Lower Position Counter Register
DEC0_UPOSH	\$9	Upper Position Hold Register
DEC0_LPOSH	\$A	Lower Position Hold Register
DEC0_UIR	\$B	Upper Initialization Register
DEC0_LIR	\$C	Lower Initialization Register
DEC0_IMR	\$D	Input Monitor Register

Table 4-18 Quadrature Decoder 1 Registers Address Map (DEC1_BASE = \$00F190)

Register Acronym	Address Offset	Register Description
DEC1_DECCR	\$0	Decoder Control Register
DEC1_FIR	\$1	Filter Interval Register
DEC1_WTR	\$2	Watchdog Timeout Register
DEC1_POSD	\$3	Position Difference Counter Register
DEC1_POSDH	\$4	Position Difference Counter Hold Register
DEC1_REV	\$5	Revolution Counter Register
DEC1_REVH	\$6	Revolution Hold Register
DEC1_UPOS	\$7	Upper Position Counter Register
DEC1_LPOS	\$8	Lower Position Counter Register
DEC1_UPOSH	\$9	Upper Position Hold Register
DEC1_LPOSH	\$A	Lower Position Hold Register
DEC1_UIR	\$B	Upper Initialization Register
DEC1_LIR	\$C	Lower Initialization Register
DEC1_IMR	\$D	Input Monitor Register

Table 4-19 Interrupt Control Registers Address Map (ITCN_BASE = \$00F1A0)

Register Acronym	Address Offset	Register Description
IPR 0	\$0	Interrupt Priority Register 0
IPR 1	\$1	Interrupt Priority Register 1
IPR 2	\$2	Interrupt Priority Register 2
IPR 3	\$3	Interrupt Priority Register 3
IPR 4	\$4	Interrupt Priority Register 4
IPR 5	\$5	Interrupt Priority Register 5
IPR 6	\$6	Interrupt Priority Register 6
IPR 7	\$7	Interrupt Priority Register 7
IPR 8	\$8	Interrupt Priority Register 8
IPR 9	\$9	Interrupt Priority Register 9
VBA	\$A	Vector Base Address Register
FIM0	\$B	Fast Interrupt Match Register 0
FIVAL0	\$C	Fast Interrupt Vector Address Low 0 Register
FIVAH0	\$D	Fast Interrupt Vector Address High 0 Register
FIM1	\$E	Fast Interrupt Match Register 1
FIVAL1	\$F	Fast Interrupt Vector Address Low 1 Register
FIVAH1	\$10	Fast Interrupt Vector Address High 1 Register
IRQP 0	\$11	IRQ Pending Register 0
IRQP 1	\$12	IRQ Pending Register 1
IRQP 2	\$13	IRQ Pending Register 2
IRQP 3	\$14	IRQ Pending Register 3
IRQP 4	\$15	IRQ Pending Register 4
IRQP 5	\$16	IRQ Pending Register 5
	\$17	Reserved
	\$18	Reserved
	\$19	Reserved
	\$1A	Reserved
	\$1B	Reserved
	\$1C	Reserved
ICTL	\$1D	Interrupt Control Register

Table 4-20 Analog to Digital Converter Registers Address Map (ADCA_BASE = \$00F200)

Register Acronym	Address Offset	Register Description
ADCA_CR 1	\$0	Control Register 1
ADCA_CR 2	\$1	Control Register 2
ADCA_ZCC	\$2	Zero Crossing Control Register
ADCA_LST 1	\$3	Channel List Register 1
ADCA_LST 2	\$4	Channel List Register 2
ADCA_SDIS	\$5	Sample Disable Register
ADCA_STAT	\$6	Status Register
ADCA_LSTAT	\$7	Limit Status Register
ADCA_ZCSTAT	\$8	Zero Crossing Status Register
ADCA_RSLT 0	\$9	Result Register 0
ADCA_RSLT 1	\$A	Result Register 1
ADCA_RSLT 2	\$B	Result Register 2
ADCA_RSLT 3	\$C	Result Register 3
ADCA_RSLT 4	\$D	Result Register 4
ADCA_RSLT 5	\$E	Result Register 5
ADCA_RSLT 6	\$F	Result Register 6
ADCA_RSLT 7	\$10	Result Register 7
ADCA_LLMT 0	\$11	Low Limit Register 0
ADCA_LLMT 1	\$12	Low Limit Register 1
ADCA_LLMT 2	\$13	Low Limit Register 2
ADCA_LLMT 3	\$14	Low Limit Register 3
ADCA_LLMT 4	\$15	Low Limit Register 4
ADCA_LLMT 5	\$16	Low Limit Register 5
ADCA_LLMT 6	\$17	Low Limit Register 6
ADCA_LLMT 7	\$18	Low Limit Register 7
ADCA_HLMT 0	\$19	High Limit Register 0
ADCA_HLMT 1	\$1A	High Limit Register 1
ADCA_HLMT 2	\$1B	High Limit Register 2
ADCA_HLMT 3	\$1C	High Limit Register 3
ADCA_HLMT 4	\$1D	High Limit Register 4
ADCA_HLMT 5	\$1E	High Limit Register 5
ADCA_HLMT 6	\$1F	High Limit Register 6
ADCA_HLMT 7	\$20	High Limit Register 7
ADCA_OFS 0	\$21	Offset Register 0

Table 4-20 Analog to Digital Converter Registers Address Map (ADCA_BASE = \$00F200) (Continued)

Register Acronym	Address Offset	Register Description
ADCA_OFS 1	\$22	Offset Register 1
ADCA_OFS 2	\$23	Offset Register 2
ADCA_OFS 3	\$24	Offset Register 3
ADCA_OFS 4	\$25	Offset Register 4
ADCA_OFS 5	\$26	Offset Register 5
ADCA_OFS 6	\$27	Offset Register 6
ADCA_OFS 7	\$28	Offset Register 7
ADCA_POWER	\$29	Power Control Register
ADCA_CAL	\$2A	ADC Calibration Register

Table 4-21 Analog to Digital Converter Registers Address Map (ADCB_BASE = \$00F240)

Register Acronym	Address Offset	Register Description
ADCB_CR 1	\$0	Control Register 1
ADCB_CR 2	\$1	Control Register 2
ADCB_ZCC	\$2	Zero Crossing Control Register
ADCB_LST 1	\$3	Channel List Register 1
ADCB_LST 2	\$4	Channel List Register 2
ADCB_SDIS	\$5	Sample Disable Register
ADCB_STAT	\$6	Status Register
ADCB_LSTAT	\$7	Limit Status Register
ADCB_ZCSTAT	\$8	Zero Crossing Status Register
ADCB_RSLT 0	\$9	Result Register 0
ADCB_RSLT 1	\$A	Result Register 1
ADCB_RSLT 2	\$B	Result Register 2
ADCB_RSLT 3	\$C	Result Register 3
ADCB_RSLT 4	\$D	Result Register 4
ADCB_RSLT 5	\$E	Result Register 5
ADCB_RSLT 6	\$F	Result Register 6
ADCB_RSLT 7	\$10	Result Register 7
ADCB_LLMT 0	\$11	Low Limit Register 0
ADCB_LLMT 1	\$12	Low Limit Register 1
ADCB_LLMT 2	\$13	Low Limit Register 2
ADCB_LLMT 3	\$14	Low Limit Register 3
ADCB_LLMT 4	\$15	Low Limit Register 4

Table 4-21 Analog to Digital Converter Registers Address Map (ADCB_BASE = \$00F240) (Continued)

Register Acronym	Address Offset	Register Description
ADCB_LLMT 5	\$16	Low Limit Register 5
ADCB_LLMT 6	\$17	Low Limit Register 6
ADCB_LLMT 7	\$18	Low Limit Register 7
ADCB_HLMT 0	\$19	High Limit Register 0
ADCB_HLMT 1	\$1A	High Limit Register 1
ADCB_HLMT 2	\$1B	High Limit Register 2
ADCB_HLMT 3	\$1C	High Limit Register 3
ADCB_HLMT 4	\$1D	High Limit Register 4
ADCB_HLMT 5	\$1E	High Limit Register 5
ADCB_HLMT 6	\$1F	High Limit Register 6
ADCB_HLMT 7	\$20	High Limit Register 7
ADCB_OFS 0	\$21	Offset Register 0
ADCB_OFS 1	\$22	Offset Register 1
ADCB_OFS 2	\$23	Offset Register 2
ADCB_OFS 3	\$24	Offset Register 3
ADCB_OFS 4	\$25	Offset Register 4
ADCB_OFS 5	\$26	Offset Register 5
ADCB_OFS 6	\$27	Offset Register 6
ADCB_OFS 7	\$28	Offset Register 7
ADCB_POWER	\$29	Power Control Register
ADCB_CAL	\$2A	ADC Calibration Register

Table 4-22 Temperature Sensor Register Address Map (TSENSOR_BASE = \$00F270)

Register Acronym	Address Offset	Register Description
TSENSOR_CNTL	\$0	Control Register

Table 4-23 Serial Communication Interface 0 Registers Address Map (SCI0_BASE = \$00F280)

Register Acronym	Address Offset	Register Description
SCI0_SCIBR	\$0	Baud Rate Register
SCI0_SCICR	\$1	Control Register
		Reserved
SCI0_SCISR	\$3	Status Register
SCI0_SCIDR	\$4	Data Register

Table 4-24 Serial Communication Interface 1 Registers Address Map (SCI1_BASE = \$00F290)

Register Acronym	Address Offset	Register Description
SCI1_SCIBR	\$0	Baud Rate Register
SCI1_SCICR	\$1	Control Register
		Reserved
SCI1_SCISR	\$3	Status Register
SCI1_SCIDR	\$4	Data Register

Table 4-25 Serial Peripheral Interface 0 Registers Address Map (SPI0_BASE = \$00F2A0)

Register Acronym	Address Offset	Register Description
SPI0_SPSCR	\$0	Status and Control Register
SPI0_SPDSR	\$1	Data Size Register
SPI0_SPDRR	\$2	Data Receive Register
SPI0_SPDTR	\$3	Data Transmitter Register

Table 4-26 Serial Peripheral Interface 1 Registers Address Map (SPI1_BASE = \$00F2B0)

Register Acronym	Address Offset	Register Description
SPI1_SPSCR	\$0	Status and Control Register
SPI1_SPDSR	\$1	Data Size Register
SPI1_SPDRR	\$2	Data Receive Register
SPI1_SPDTR	\$3	Data Transmitter Register

Table 4-27 Computer Operating Properly Registers Address Map (COP_BASE = \$00F2C0)

Register Acronym	Address Offset	Register Description
COPCTL	\$0	Control Register
СОРТО	\$1	Time Out Register
COPCTR	\$2	Counter Register

Table 4-28 Clock Generation Module Registers Address Map (CLKGEN_BASE = \$00F2D0)

Register Acronym	Address Offset	Register Description
PLLCR	\$0	Control Register
PLLDB	\$1	Divide-By Register
PLLSR	\$2	Status Register
		Reserved
SHUTDOWN	\$4	Shutdown Register
OSCTL	\$5	Oscillator Control Register

Table 4-29 GPIOA Registers Address Map (GPIOA_BASE = \$00F2E0)

Register Acronym	Address Offset	Register Description	Reset Value
GPIOA_PUR	\$0	Pull-up Enable Register	0 x 3FFF
GPIOA_DR	\$1	Data Register	0 x 0000
GPIOA_DDR	\$2	Data Direction Register	0 x 0000
GPIOA_PER	\$3	Peripheral Enable Register	0 x 3FFF
GPIOA_IAR	\$4	Interrupt Assert Register	0 x 0000
GPIOA_IENR	\$5	Interrupt Enable Register	0 x 0000
GPIOA_IPOLR	\$6	Interrupt Polarity Register	0 x 0000
GPIOA_IPR	\$7	Interrupt Pending Register	0 x 0000
GPIOA_IESR	\$8	Interrupt Edge-Sensitive Register	0 x 0000
GPIOA_PPMODE	\$9	Push-Pull Mode Register	0 x 3FFF
GPIOA_RAWDATA	\$A	Raw Data Input Register	-

Table 4-30 GPIOB Registers Address Map (GPIOB_BASE = \$00F300)

Register Acronym	Address Offset	Register Description	Reset Value
GPIOB_PUR	\$0	Pull-up Enable Register	0 x 00FF
GPIOB_DR	\$1	Data Register	0 x 0000
GPIOB_DDR	\$2	Data Direction Register	0 x 0000
GPIOB_PER	\$3	Peripheral Enable Register	0 x 0000 or 0 x 000F ¹
GPIOB_IAR	\$4	Interrupt Assert Register	0 x 0000
GPIOB_IENR	\$5	Interrupt Enable Register	0 x 0000
GPIOB_IPOLR	\$6	Interrupt Polarity Register	0 x 0000
GPIOB_IPR	\$7	Interrupt Pending Register	0 x 0000
GPIOB_IESR	\$8	Interrupt Edge-Sensitive Register	0 x 0000
GPIOB_PPMODE	\$9	Push-Pull Mode Register	0 x 00FF
GPIOB_RAWDATA	\$A	Raw Data Input Register	-

^{1.} Determined by EMI_MODE and EXTBOOT. Can be 0x00 or 0x0F, depending on address pin configuration. See Table 4-4.

Table 4-31 GPIOC Registers Address Map (GPIOC_BASE = \$00F310)

Register Acronym	Address Offset	Register Description	Reset Value
GPIOC_PUR	\$0	Pull-up Enable Register	0 x 07FF
GPIOC_DR	\$1	Data Register	0 x 0000
GPIOC_DDR	\$2	Data Direction Register	0 x 0000
GPIOC_PER	\$3	Peripheral Enable Register	0 x 07FF
GPIOC_IAR	\$4	Interrupt Assert Register	0 x 0000
GPIOC_IENR	\$5	Interrupt Enable Register	0 x 0000
GPIOC_IPOLR	\$6	Interrupt Polarity Register	0 x 0000
GPIOC_IPR	\$7	Interrupt Pending Register	0 x 0000
GPIOC_IESR	\$8	Interrupt Edge-Sensitive Register	0 x 0000
GPIOC_PPMODE	\$9	Push-Pull Mode Register	0 x 07FF
GPIOC_RAWDATA	\$A	Raw Data Input Register	-

Table 4-32 GPIOD Registers Address Map (GPIOD_BASE = \$00F320)

Register Acronym	Address Offset	Register Description	Reset Value
GPIOD_PUR	\$0	Pull-up Enable Register	0 x 1FFF
GPIOD_DR	\$1	Data Register	0 x 0000
GPIOD_DDR	\$2	Data Direction Register	0 x 0000
GPIOD_PER	\$3	Peripheral Enable Register	0 x 1FC0
GPIOD_IAR	\$4	Interrupt Assert Register	0 x 0000
GPIOD_IENR	\$5	Interrupt Enable Register	0 x 0000
GPIOD_IPOLR	\$6	Interrupt Polarity Register	0 x 0000
GPIOD_IPR	\$7	Interrupt Pending Register	0 x 0000
GPIOD_IESR	\$8	Interrupt Edge-Sensitive Register	0 x 0000
GPIOD_PPMODE	\$9	Push-Pull Mode Register	0 x 1FFF
GPIOD_RAWDATA	\$A	Raw Data Input Register	-

Table 4-33 GPIOE Registers Address Map (GPIOE_BASE = \$00F330)

Register Acronym	Address Offset	Register Description	Reset Value
GPIOE_PUR	\$0	Pull-up Enable Register	0 x 3FFF
GPIOE_DR	\$1	Data Register	0 x 0000
GPIOE_DDR	\$2	Data Direction Register	0 x 0000
GPIOE_PER	\$3	Peripheral Enable Register	0 x 3FFF
GPIOE_IAR	\$4	Interrupt Assert Register	0 x 0000
GPIOE_IENR	\$5	Interrupt Enable Register	0 x 0000
GPIOE_IPOLR	\$6	Interrupt Polarity Register	0 x 0000
GPIOE_IPR	\$7	Interrupt Pending Register	0 x 0000
GPIOE_IESR	\$8	Interrupt Edge-Sensitive Register	0 x 0000
GPIOE_PPMODE	\$9	Push-Pull Mode Register	0 x 3FFF
GPIOE_RAWDATA	\$A	Raw Data Input Register	-

Table 4-34 GPIOF Registers Address Map (GPIOF_BASE = \$00F340)

Register Acronym	Address Offset	Register Description	Reset Value
GPIOF_PUR	\$0	Pull-up Enable Register	0 x FFFF
GPIOF_DR	\$1	Data Register	0 x 0000
GPIOF_DDR	\$2	Data Direction Register	0 x 0000
GPIOF_PER	\$3	Peripheral Enable Register	0 x FFFF
GPIOF_IAR	\$4	Interrupt Assert Register	0 x 0000
GPIOF_IENR	\$5	Interrupt Enable Register	0 x 0000
GPIOF_IPOLR	\$6	Interrupt Polarity Register	0 x 0000
GPIOF_IPR	\$7	Interrupt Pending Register	0 x 0000
GPIOF_IESR	\$8	Interrupt Edge-Sensitive Register	0 x 0000
GPIOF_PPMODE	\$9	Push-Pull Mode Register	0 x FFFF
GPIOF_RAWDATA	\$A	Raw Data Input Register	-

Table 4-35 System Integration Module Registers Address Map (SIM_BASE = \$00F350)

Register Acronym	Address Offset	Register Description				
SIM_CONTROL	\$0	Control Register				
SIM_RSTSTS	\$1	Reset Status Register				
SIM_SCR0	\$2	Software Control Register 0				
SIM_SCR1	\$3	Software Control Register 1				
SIM_SCR2	\$4	Software Control Register 2				
SIM_SCR3	\$5	Software Control Register 3				
SIM_MSH_ID	\$6	Most Significant Half JTAG ID				
SIM_LSH_ID	\$7	Least Significant Half JTAG ID				
SIM_PUDR	\$8	Pull-up Disable Register				
		Reserved				
SIM_CLKOSR	\$A	Clock Out Select Register				
SIM_GPS	\$B	Quad Decoder 1 / Timer B / SPI 1 Select Register				
SIM_PCE	\$C	Peripheral Clock Enable Register				
SIM_ISALH	\$D	I/O Short Address Location High Register				
SIM_ISALL	\$E	I/O Short Address Location Low Register				

Table 4-36 Power Supervisor Registers Address Map (LVI_BASE = \$00F360)

Register Acronym	Address Offset	Register Description
LVI_CONTROL	\$0	Control Register
LVI_STATUS	\$1	Status Register

Table 4-37 Flash Module Registers Address Map (FM_BASE = \$00F400)

Register Acronym	Address Offset	Register Description							
FMCLKD	\$0	Clock Divider Register							
FMMCR	\$1	Module Control Register							
		Reserved							
FMSECH	\$3	Security High Half Register							
FMSECL	\$4	Security Low Half Register							
FMMNTR	\$5	Monitor Data Register							
		Reserved							
FMPROT	\$10	Protection Register (Banked)							
FMPROTB	\$11	Protection Boot Register (Banked)							
		Reserved							
FMUSTAT	\$13	User Status Register (Banked)							
FMCMD	\$14	Command Register (Banked)							
FMCTL	\$15	Control Register (Banked)							
		Reserved							
FMIFROPT 0	\$1A	16-Bit Information Option Register 0 Hot temperature ADC reading of Temp Sense; value set during factory test							
FMIFROPT 1	\$1B	16-Bit Information Option Register 1 Not used							
FMIFROPT 2	\$1C	16-Bit Information Option Register 2 Room temperature ADC reading of Temp Sense; value set during factory test							

Table 4-38 FlexCAN Registers Address Map (FC_BASE = \$00F800)

Register Acronym	Address Offset	Register Description					
FCMCR	\$0	Module Configuration Register					
		Reserved					
FCCTL0	\$3	Control Register 0 Register					
FCCTL1	\$4	Control Register 1 Register					
FCTMR	\$5	Free Running Timer Register					
FCMAXMB	\$6	Maximum Message Buffer Configuration Register					
FCIMASK2	\$7	Interrupt Masks 2 Register					
FCRXGMASK_H	\$8	Receive Global Mask High Register					
FCRXGMASK_L	\$9	Receive Global Mask Low Register					
FCRX14MASK_H	\$A	Receive Buffer 14 Mask High Register					
FCRX14MASK_L	\$B	Receive Buffer 14 Mask Low Register					
FCRX15MASK_H	\$C	Receive Buffer 15 Mask High Register					
FCRX15MASK_L	\$D	Receive Buffer 15 Mask Low Register					
		Reserved					
FCSTATUS	\$10	Error and Status Register					
FCIMASK1	\$11	Interrupt Masks 1 Register					
FCIFLAG1	\$12	Interrupt Flags 1 Register					
FCR/T_ERROR_CNTRS	\$13	Receive and Transmit Error Counters Register					
		Reserved					
FCIFLAG 2	\$1B	Interrupt Flags 2 Register					
		Reserved					
FCMB0_CONTROL	\$40	Message Buffer 0 Control/Status Register					
FCMB0_ID_HIGH	\$41	Message Buffer 0 ID High Register					
FCMB0_ID_LOW	\$42	Message Buffer 0 ID Low Register					
FCMB0_DATA	\$43	Message Buffer 0 Data Register					
FCMB0_DATA	\$44	Message Buffer 0 Data Register					
FCMB0_DATA	\$45	Message Buffer 0 Data Register					
FCMB0_DATA	\$46	Message Buffer 0 Data Register					
		Reserved					
FCMSB1_CONTROL	\$48	Message Buffer 1 Control/Status Register					
FCMSB1_ID_HIGH	\$49	Message Buffer 1 ID High Register					
FCMSB1_ID_LOW	\$4A	Message Buffer 1 ID Low Register					
FCMB1_DATA	\$4B	Message Buffer 1 Data Register					
FCMB1_DATA	\$4C	Message Buffer 1 Data Register					
FCMB1_DATA	\$4D	Message Buffer 1 Data Register					
FCMB1_DATA	\$4E	Message Buffer 1 Data Register					

Table 4-38 FlexCAN Registers Address Map (FC_BASE = \$00F800) (Continued)

Register Acronym	Address Offset	Register Description
		Reserved
FCMB2_CONTROL	\$50	Message Buffer 2 Control/Status Register
FCMB2_ID_HIGH	\$51	Message Buffer 2 ID High Register
FCMB2_ID_LOW	\$52	Message Buffer 2 ID Low Register
FCMB2_DATA	\$53	Message Buffer 2 Data Register
FCMB2_DATA	\$54	Message Buffer 2 Data Register
FCMB2_DATA	\$55	Message Buffer 2 Data Register
FCMB2_DATA	\$56	Message Buffer 2 Data Register
		Reserved
FCMB3_CONTROL	\$58	Message Buffer 3 Control/Status Register
FCMB3_ID_HIGH	\$59	Message Buffer 3 ID High Register
FCMB3_ID_LOW	\$5A	Message Buffer 3 ID Low Register
FCMB3_DATA	\$5B	Message Buffer 3 Data Register
FCMB3_DATA	\$5C	Message Buffer 3 Data Register
FCMB3_DATA	\$5D	Message Buffer 3 Data Register
FCMB3_DATA	\$5E	Message Buffer 3 Data Register
		Reserved
FCMB4_CONTROL	\$60	Message Buffer 4 Control/Status Register
FCMB4_ID_HIGH	\$61	Message Buffer 4 ID High Register
FCMB4_ID_LOW	\$62	Message Buffer 4 ID Low Register
FCMB4_DATA	\$63	Message Buffer 4 Data Register
FCMB4_DATA	\$64	Message Buffer 4 Data Register
FCMB4_DATA	\$65	Message Buffer 4 Data Register
FCMB4_DATA	\$66	Message Buffer 4 Data Register
		Reserved
FCMB5_CONTROL	\$68	Message Buffer 5 Control/Status Register
FCMB5_ID_HIGH	\$69	Message Buffer 5 ID High Register
FCMB5_ID_LOW	\$6A	Message Buffer 5 ID Low Register
FCMB5_DATA	\$6B	Message Buffer 5 Data Register
FCMB5_DATA	\$6C	Message Buffer 5 Data Register
FCMB5_DATA	\$6D	Message Buffer 5 Data Register
FCMB5_DATA	\$6E	Message Buffer 5 Data Register
		Reserved
FCMB6_CONTROL	\$70	Message Buffer 6 Control/Status Register
FCMB6_ID_HIGH	\$71	Message Buffer 6 ID High Register

Table 4-38 FlexCAN Registers Address Map (FC_BASE = \$00F800) (Continued)

Register Acronym	Address Offset	Register Description
FCMB6_ID_LOW	\$72	Message Buffer 6 ID Low Register
FCMB6_DATA	\$73	Message Buffer 6 Data Register
FCMB6_DATA	\$74	Message Buffer 6 Data Register
FCMB6_DATA	\$75	Message Buffer 6 Data Register
FCMB6_DATA	\$76	Message Buffer 6 Data Register
		Reserved
FCMB7_CONTROL	\$78	Message Buffer 7 Control/Status Register
FCMB7_ID_HIGH	\$79	Message Buffer 7 ID High Register
FCMB7_ID_LOW	\$7A	Message Buffer 7 ID Low Register
FCMB7_DATA	\$7B	Message Buffer 7 Data Register
FCMB7_DATA	\$7C	Message Buffer 7 Data Register
FCMB7_DATA	\$7D	Message Buffer 7 Data Register
FCMB7_DATA	\$7E	Message Buffer 7 Data Register
		Reserved
FCMB8_CONTROL	\$80	Message Buffer 8 Control/Status Register
FCMB8_ID_HIGH	\$81	Message Buffer 8 ID High Register
FCMB8_ID_LOW	\$82	Message Buffer 8 ID Low Register
FCMB8_DATA	\$83	Message Buffer 8 Data Register
FCMB8_DATA	\$84	Message Buffer 8 Data Register
FCMB8_DATA	\$85	Message Buffer 8 Data Register
FCMB8_DATA	\$86	Message Buffer 8 Data Register
		Reserved
FCMB9_CONTROL	\$88	Message Buffer 9 Control/Status Register
FCMB9_ID_HIGH	\$89	Message Buffer 9 ID High Register
FCMB9_ID_LOW	\$8A	Message Buffer 9 ID Low Register
FCMB9_DATA	\$8B	Message Buffer 9 Data Register
FCMB9_DATA	\$8C	Message Buffer 9 Data Register
FCMB9_DATA	\$8D	Message Buffer 9 Data Register
FCMB9_DATA	\$8E	Message Buffer 9 Data Register
		Reserved
FCMB10_CONTROL	\$90	Message Buffer 10 Control/Status Register
FCMB10_ID_HIGH	\$91	Message Buffer 10 ID High Register
FCMB10_ID_LOW	\$92	Message Buffer 10 ID Low Register
FCMB10_DATA	\$93	Message Buffer 10 Data Register

Table 4-38 FlexCAN Registers Address Map (FC_BASE = \$00F800) (Continued)

Register Acronym	Address Offset	Register Description
FCMB10_DATA	\$95	Message Buffer 10 Data Register
FCMB10_DATA	\$96	Message Buffer 10 Data Register
		Reserved
FCMB11_CONTROL	\$98	Message Buffer 11 Control/Status Register
FCMB11_ID_HIGH	\$99	Message Buffer 11 ID High Register
FCMB11_ID_LOW	\$9A	Message Buffer 11 ID Low Register
FCMB11_DATA	\$9B	Message Buffer 11 Data Register
FCMB11_DATA	\$9C	Message Buffer 11 Data Register
FCMB11_DATA	\$9D	Message Buffer 11 Data Register
FCMB11_DATA	\$9E	Message Buffer 11 Data Register
		Reserved
FCMB12_CONTROL	\$A0	Message Buffer 12 Control/Status Register
FCMB12_ID_HIGH	\$A1	Message Buffer 12 ID High Register
FCMB12_ID_LOW	\$A2	Message Buffer 12 ID Low Register
FCMB12_DATA	\$A3	Message Buffer 12 Data Register
FCMB12_DATA	\$A4	Message Buffer 12 Data Register
FCMB12_DATA	\$A5	Message Buffer 12 Data Register
FCMB12_DATA	\$A6	Message Buffer 12 Data Register
		Reserved
FCMB13_CONTROL	\$A8	Message Buffer 13 Control/Status Register
FCMB13_ID_HIGH	\$A9	Message Buffer 13 ID High Register
FCMB13_ID_LOW	\$AA	Message Buffer 13 ID Low Register
FCMB13_DATA	\$AB	Message Buffer 13 Data Register
FCMB13_DATA	\$AC	Message Buffer 13 Data Register
FCMB13_DATA	\$AD	Message Buffer 13 Data Register
FCMB13_DATA	\$AE	Message Buffer 13 Data Register
		Reserved
FCMB14_CONTROL	\$B0	Message Buffer 14 Control/Status Register
FCMB14_ID_HIGH	\$B1	Message Buffer 14 ID High Register
FCMB14_ID_LOW	\$B2	Message Buffer 14 ID Low Register
FCMB14_DATA	\$B3	Message Buffer 14 Data Register
FCMB14_DATA	\$B4	Message Buffer 14 Data Register
FCMB14_DATA	\$B5	Message Buffer 14 Data Register
FCMB14_DATA	\$B6	Message Buffer 14 Data Register
		Reserved

Table 4-38 FlexCAN Registers Address Map (FC_BASE = \$00F800) (Continued)

Register Acronym	Address Offset	Register Description
FCMB15_CONTROL	\$B8	Message Buffer 15 Control/Status Register
FCMB15_ID_HIGH	\$B9	Message Buffer 15 ID High Register
FCMB15_ID_LOW	\$BA	Message Buffer 15 ID Low Register
FCMB15_DATA	\$BB	Message Buffer 15 Data Register
FCMB15_DATA	\$BC	Message Buffer 15 Data Register
FCMB15_DATA	\$BD	Message Buffer 15 Data Register
FCMB15_DATA	\$BE	Message Buffer 15 Data Register
		Reserved

Part 5 Interrupt Controller (ITCN)

5.1 Introduction

The Interrupt Controller (ITCN) module is used to arbitrate between various interrupt requests (IRQs) and to signal to the 56800E core when an interrupt of sufficient priority exists and to what address to jump in order to service this interrupt.

5.2 Features

The ITCN module design includes these distinctive features:

- Programmable priority levels for each IRQ
- Two programmable Fast Interrupts
- Notification to SIM module to restart clocks out of Wait and Stop modes
- Drives initial address on the address bus after reset

For further information, see **Table 4-5**, Interrupt Vector Table Contents.

5.3 Functional Description

The Interrupt Controller is a slave on the IPBus. It contains registers allowing each of the 82 interrupt sources to be set to one of four priority levels, excluding certain interrupts of fixed priority. Next, all of the interrupt requests of a given level are priority encoded to determine the lowest numerical value of the active interrupt requests for that level. Within a given priority level, zero is the highest priority, while number 81 is the lowest.

5.3.1 Normal Interrupt Handling

Once the ITCN has determined that an interrupt is to be serviced and which interrupt has the highest priority, an interrupt vector address is generated. Normal interrupt handling concatenates the VBA and the vector number to determine the vector address. In this way, an offset is generated into the vector table for each interrupt.

5.3.2 Interrupt Nesting

Interrupt exceptions may be nested to allow an IRQ of higher priority than the current exception to be serviced. The following tables define the nesting requirements for each priority level.

Table 5-1 Interrupt Mask Bit Definition

SR[9] ¹	SR[8] ¹	Permitted Exceptions	Masked Exceptions
0	0	Priorities 0, 1, 2, 3	None
0	1	Priorities 1, 2, 3	Priority 0
1	0	Priorities 2, 3	Priorities 0, 1
1	1	Priority 3	Priorities 0, 1, 2

^{1.} Core status register bits indicating current interrupt mask within the core.

Table 5-2 Interrupt Priority Encoding

IPIC_LEVEL[1:0] ¹	Current Interrupt Priority Level	Required Nested Exception Priority
00	No Interrupt or SWILP	Priorities 0, 1, 2, 3
01	Priority 0	Priorities 1, 2, 3
10	Priority 1	Priorities 2, 3
11	Priorities 2 or 3	Priority 3

^{1.} See IPIC field definition in Section 5.6.30.2.

5.3.3 Fast Interrupt Handling

Fast interrupts are described in the **DSP56800E Reference Manual**. The interrupt controller recognizes fast interrupts before the core does.

A fast interrupt is defined (to the ITCN) by:

- 1. Setting the priority of the interrupt as level 2, with the appropriate field in the IPR registers.
- 2. Setting the FIMn register to the appropriate vector number.
- 3. Setting the FIVALn and FIVAHn registers with the address of the code for the fast interrupt.

When an interrupt occurs, its vector number is compared with the FIM0 and FIM1 register values. If a match occurs, and it is a level 2 interrupt, the ITCN handles it as a fast interrupt. The ITCN takes the vector address from the appropriate FIVALn and FIVAHn registers, instead of generating an address that is an offset from the VBA.

The core then fetches the instruction from the indicated vector adddress and if it is not a JSR, the core starts its fast interrupt handling.

5.4 Block Diagram

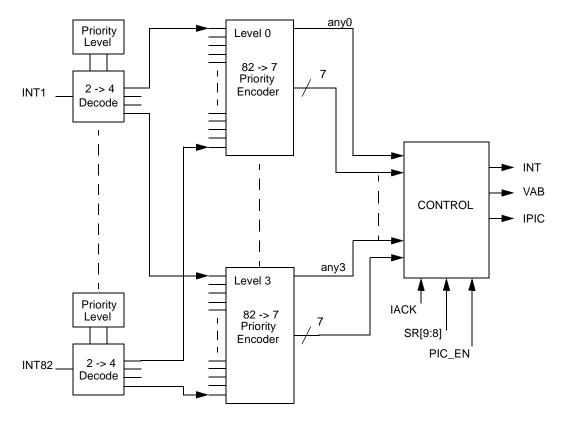


Figure 5-1 Interrupt Controller Block Diagram

5.5 Operating Modes

The ITCN module design contains two major modes of operation:

Functional Mode

The ITCN is in this mode by default.

Wait and Stop Modes

During Wait and Stop modes, the system clocks and the 56800E core are turned off. The ITCN will signal a pending IRQ to the System Integration Module (SIM) to restart the clocks and service the IRQ. An IRQ can only wake up the core if the IRQ is enabled prior to entering the Wait or Stop mode. Also, the IRQA and IRQB signals automatically become low-level sensitive in these modes even if the control register bits are set to make them falling-edge sensitive. This is because there is no clock available to detect the falling edge.

Peripheral which require a clock to generate interrupts will not be able to generate interrupts during STOP mode. The FlexCAN module can wake the device from STOP, and a reset will do just that, or IRQA and IRQB can wake it up.

5.6 Register Descriptions

A register address is the sum of a base address and an address offset. The base address is defined at the system level and the address offset is defined at the module level. The ITCN peripheral has 24 registers.

Table 5-3 ITCN Register Summary (ITCN_BASE = \$00F1A0)

Register Acronym	Base Address +	Register Name	Section Location
IPR0	\$0	Interrupt Priority Register 0	5.6.1
IPR1	\$1	Interrupt Priority Register 1	5.6.2
IPR2	\$2	Interrupt Priority Register 2	5.6.3
IPR3	\$3	Interrupt Priority Register 3	5.6.4
IPR4	\$4	Interrupt Priority Register 4	5.6.5
IPR5	\$5	Interrupt Priority Register 5	5.6.6
IPR6	\$6	Interrupt Priority Register 6	5.6.7
IPR7	\$7	Interrupt Priority Register 7	5.6.8
IPR8	\$8	Interrupt Priority Register 8	5.6.9
IPR9	\$9	Interrupt Priority Register 9	5.6.10
VBA	\$A	Vector Base Address Register	5.6.11
FIM0	\$B	Fast Interrupt 0 Match Register	5.6.12
FIVAL0	\$C	Fast Interrupt 0 Vector Address Low Register	5.6.13
FIVAH0	\$D	Fast Interrupt 0 Vector Address High Register	5.6.14
FIM1	\$E	Fast Interrupt 1 Match Register	5.6.15
FIVAL1	\$F	Fast Interrupt 1 Vector Address Low Register	5.6.16
FIVAH1	\$10	Fast Interrupt 1 Vector Address High Register	5.6.17
IRQP0	\$11	IRQ Pending Register 0	5.6.18
IRQP1	\$12	IRQ Pending Register 1	5.6.19
IRQP2	\$13	IRQ Pending Register 2	5.6.20
IRQP3	\$14	IRQ Pending Register 3	5.6.21
IRQP4	\$15	IRQ Pending Register 4	5.6.22
IRQP5	\$16	IRQ Pending Register 5	5.6.23
Reserved	\$17		
ICTL		Interrupt Control Register	5.6.30



Figure 5-2 ITCN Register Map Summary

5.6.1 Interrupt Priority Register 0 (IPR0)

Base + \$0	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	DVDT	U0 IPL	STPCNT IPL		0	0	0	0	0	0	0	0	0	0
Write			DKF1_	OUIFL	STEC	NIIFL										
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-3 Interrupt Priority Register 0 (IPR0)

5.6.1.1 Reserved—Bits 15–14

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.1.2 EOnCE Breakpoint Unit 0 Interrupt Priority Level (BKPT_U0 IPL)— Bits13–12

This field is used to set the interrupt priority levels for IRQs. This IRQ is limited to priorities 1 through 3. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 1
- 10 = IRQ is priority level 2
- 11 = IRQ is priority level 3

5.6.1.3 EOnCE Step Counter Interrupt Priority Level (STPCNT IPL)—Bits 11–10

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 1 through 3. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 1
- 10 = IRQ is priority level 2
- 11 = IRQ is priority level 3

5.6.1.4 Reserved—Bits 9-0

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.2 Interrupt Priority Register 1 (IPR1)

Base + \$1	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	0	0	0	DV DI	EG IPL	TX_REG IPL		TRBUF IPL	
Write											KA_KI	EG IFL				
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-4 Interrupt Priority Register 1 (IPR1)

5.6.2.1 Reserved—Bits 15-6

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.2.2 EOnCE Receive Register Full Interrupt Priority Level (RX_REG IPL)—Bits 5–4

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 1 through 3. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 1
- 10 = IRQ is priority level 2
- 11 = IRQ is priority level 3

5.6.2.3 EOnCE Transmit Register Empty Interrupt Priority Level (TX_REG IPL)—Bits 3–2

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 1 through 3. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 1
- 10 = IRQ is priority level 2
- 11 = IRQ is priority level 3

5.6.2.4 EOnCE Trace Buffer Interrupt Priority Level (TRBUF IPL)— Bits 1–0

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 1 through 3. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 1
- 10 = IRQ is priority level 2
- 11 = IRQ is priority level 3

5.6.3 Interrupt Priority Register 2 (IPR2)

Base + \$2	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	- FMCBE IPL		FMCC IPL		FMERR IPL		LOCK IPL		LVI IPL		0	0	IRQB IPL		IRQA IPL	
Write																
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-5 Interrupt Priority Register 2 (IPR2)

5.6.3.1 Flash Memory Command, Data, Address Buffers Empty Interrupt Priority Level (FMCBE IPL)—Bits 15–14

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.3.2 Flash Memory Command Complete Priority Level (FMCC IPL)—Bits 13–12

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.3.3 Flash Memory Error Interrupt Priority Level (FMERR IPL)—Bits 11–10

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.3.4 PLL Loss of Lock Interrupt Priority Level (LOCK IPL)—Bits 9–8

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.3.5 Low Voltage Detector Interrupt Priority Level (LVI IPL)—Bits 7–6

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 1 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.3.6 Reserved—Bits 5–4

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.3.7 External IRQ B Interrupt Priority Level (IRQB IPL)—Bits 3–2

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.3.8 External IRQ A Interrupt Priority Level (IRQA IPL)—Bits 1–0

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. It is disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.4 Interrupt Priority Register 3 (IPR3)

Base + \$3	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	GDIC	DIPL	GPIO	E IDI	GPIC	EIDI	FCMSG	DI IE IDI	FCWK	I ID IDI	FCER	D IDI	ECBO	FF IPL	0	0
Write	GFIC	DIFL	GFIO	LIFL	GFIC	/I IF L	1 CIVISG	BOI IFL	1 CWK	OFIFL	ICLN	KIFL	1 CBO	II IFL		
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-6 Interrupt Priority Register 3 (IPR3)

5.6.4.1 GPIO D Interrupt Priority Level (GPIOD IPL)—Bits 15–14

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.4.2 GPIO E Interrupt Priority Level (GPIOE IPL)—Bits 13-12

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.4.3 GPIO F Interrupt Priority Level (GPIOF IPL)—Bits 11–10

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2two. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.4.4 FlexCAN Message Buffer Interrupt Priority Level (FCMSGBUF IPL)—Bits 9–8

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.4.5 FlexCAN Wake Up Interrupt Priority Level (FCWKUP IPL)— Bits 7–6

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRO is priority level 2

5.6.4.6 FlexCAN Error Interrupt Priority Level (FCERR IPL)— Bits 5–4

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.4.7 FlexCAN Bus Off Interrupt Priority Level (FCBOFF IPL)— Bits 3–2

- 00 = IRO disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.4.8 Reserved—Bits 1–0

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.5 Interrupt Priority Register 4 (IPR4)

Base + \$4	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read		_RCV	SPI1_	XMIT	SPI1	_RCV	0	0	0	0	GPIO	A IDI	GPIO	D IDI	GPIO	C IDI
Write	IF	PL	IF	SPI1_XMIT IPL		PL					GFIO	AIFL	GFIO	DIFL	GFIO	CIFL
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-7 Interrupt Priority Register 4 (IPR4)

5.6.5.1 SPI0 Receiver Full Interrupt Priority Level (SPI0_RCV IPL)— Bits 15–14

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.5.2 SPI1 Transmit Empty Interrupt Priority Level (SPI1_XMIT IPL)—Bits 13–12

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.5.3 SPI1 Receiver Full Interrupt Priority Level (SPI1_RCV IPL)— Bits 11–10

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.5.4 Reserved—Bits 9–6

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.5.5 GPIO A Interrupt Priority Level (GPIOA IPL)—Bits 5-4

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.5.6 GPIO B Interrupt Priority Level (GPIOB IPL)—Bits 3–2

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.5.7 GPIO C Interrupt Priority Level (GPIOC IPL)—Bits 1–0

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.6 Interrupt Priority Register 5 (IPR5)

Base + \$5	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	DEC1	_XIRQ	DEC1_HIRQ IPL		SCI1	_RCV	SCI1_	RERR	0	0	SCI1_	_TIDL	SCI1_	_XMIT	SPI0_	XMIT
Write	IF	L			IF	PL	IP	L			IF	PL	IF	PL	IP	PL
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-8 Interrupt Priority Register 5 (IPR5)

5.6.6.1 Quadrature Decoder 1 INDEX Pulse Interrupt Priority Level (DEC1_XIRQ IPL)—Bits 15–14

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.6.2 Quadrature Decoder 1 HOME Signal Transition or Watchdog Timer Interrupt Priority Level (DEC1_HIRQ IPL)—Bits 13–12

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.6.3 SCI 1 Receiver Full Interrupt Priority Level (SCI1_RCV IPL)— Bits 11–10

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.6.4 SCI 1 Receiver Error Interrupt Priority Level (SCI1_RERR IPL)— Bits 9–8

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.6.5 Reserved—Bits 7-6

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.6.6 SCI 1 Transmitter Idle Interrupt Priority Level (SCI1_TIDL IPL)— Bits 5–4

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.6.7 SCI 1 Transmitter Empty Interrupt Priority Level (SCI1_XMIT IPL)— Bits 3–2

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.6.8 SPI 0 Transmitter Empty Interrupt Priority Level (SPI0_XMIT IPL)— Bits 1–0

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.7 Interrupt Priority Register 6 (IPR6)

Base + \$6	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	TMRC	וםו חי	TMRE	J2 IDI	TMRE	וםו כנ	TMRE	11 IDI	TMDF	00 IPL	0	0	DEC0	_XIRQ	DEC0	_HIRQ
Write	TIVING	JU IFL	TIVIKL	J3 IFL	TIVIKL	02 IFL	TIVIKL	/I IFL	TIVIKL	JU IPL			IF	PL	IF	PL
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-9 Interrupt Priority Register 6 (IPR6)

5.6.7.1 Timer C Channel 0 Interrupt Priority Level (TMRC0 IPL)— Bits 15–14

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.7.2 Timer D Channel 3 Interrupt Priority Level (TMRD3 IPL)— Bits 13–12

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.7.3 Timer D Channel 2 Interrupt Priority Level (TMRD2 IPL)— Bits 11–10

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.7.4 Timer D Channel 1 Interrupt Priority Level (TMRD1 IPL)— Bits 9–8

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.7.5 Timer D Channel 0 Interrupt Priority Level (TMRD0 IPL)— Bits 7–6

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.7.6 Reserved—Bits 5-4

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.7.7 Quadrature Decoder 0 INDEX Pulse Interrupt Priority Level (DEC0_XIRQ IPL)—Bits 3–2

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.7.8 Quadrature Decoder 0 HOME Signal Transition or Watchdog Timer Interrupt Priority Level (DEC0 HIRQ IPL)—Bits 1–0

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.8 Interrupt Priority Register 7 (IPR7)

Base + \$7	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	TMD	A0 IPL	TMDE			32 IPL	TMRE	וחו מו	TMRE	וחו	TMRC	וחו מי	TMRC	ים וחו	TMDC	C1 IPL
Write	TIVIKA	AU IFL	TIVIKE	TMRB3 IPL		DZ IFL	TIVINE	DITE	I IVINE	OU IFL	TIVIKC) IFL	TIVIKC	Z IFL	TIVING) I IFL
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-10 Interrupt Priority Register (IPR7)

5.6.8.1 Timer A Channel 0 Interrupt Priority Level (TMRA0 IPL)—Bits 15–14

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRO is priority level 2

5.6.8.2 Timer B Channel 3 Interrupt Priority Level (TMRB3 IPL)— Bits 13–12

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.8.3 Timer B Channel 2 Interrupt Priority Level (TMRB2 IPL)— Bits 11–10

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.8.4 Timer B Channel 1 Interrupt Priority Level (TMRB1 IPL)—Bits 9–8

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.8.5 Timer B Channel 0 Interrupt Priority Level (TMRB0 IPL)—Bits 7–6

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.8.6 Timer C Channel 3 Interrupt Priority Level (TMRC3 IPL)—Bits 5–4

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.8.7 Timer C Channel 2 Interrupt Priority Level (TMRC2 IPL)—Bits 3–2

- 00 = IRO disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.8.8 Timer C Channel 1 Interrupt Priority Level (TMRC1 IPL)—Bits 1–0

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.9 Interrupt Priority Register 8 (IPR8)

Base + \$8	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	SCI0_	_RCV	SCIO_RERR IPL		0	0	SCI0_	_TIDL	SCI0_	_XMIT	TMRA	2 IDI	TMRA	2 IDI	TMRA	\1 IDI
Write	IF	L					IF	L	IF	L	TIVIRA	IS IFL	TIVIKA	12 IFL	TIVIRA	AT IFL
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-11 Interrupt Priority Register 8 (IPR8)

5.6.9.1 SCI0 Receiver Full Interrupt Priority Level (SCI0_RCV IPL)— Bits 15–14

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.9.2 SCI0 Receiver Error Interrupt Priority Level (SCI0_RERR IPL)— Bits 13–12

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.9.3 Reserved—Bits 11–10

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.9.4 SCI0 Transmitter Idle Interrupt Priority Level (SCI0_TIDL IPL)— Bits 9–8

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.9.5 SCI0 Transmitter Empty Interrupt Priority Level (SCI0_XMIT IPL)— Bits 7–6

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.9.6 Timer A Channel 3 Interrupt Priority Level (TMRA3 IPL)—Bits 5–4

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.9.7 Timer A Channel 2 Interrupt Priority Level (TMRA2 IPL)—Bits 3–2

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.9.8 Timer A Channel 1 Interrupt Priority Level (TMRA1 IPL)—Bits 1–0

- 00 = IRO disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.10 Interrupt Priority Register 9 (IPR9)

Base + \$9	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	DIAMA	FIPL	DWWB	PWMB_F IPL		A_RL	DWW	DI IDI	۸۵۵۸	ZC IPL	ARCR	7C IDI	ADC	A_CC	ADCE	B_CC
Write	FVVIVIA	_F IFL	FVVIVID	PWMB_F IPL		L	FVVIVI_	KLIFL	ADCA_	_ZC IFL	ADCD_	ZC IFL	IF	PL	IF	PL PL
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-12 Interrupt Priority Register 9 (IPR9)

5.6.10.1 PWM A Fault Interrupt Priority Level (PWMA_F IPL)—Bits 15–14

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.10.2 PWM B Fault Interrupt Priority Level (PWMB_F IPL)—Bits 13–12

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRO disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.10.3 Reload PWM A Interrupt Priority Level (PWMA_RL IPL)— Bits 11–10

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.10.4 Reload PWM B Interrupt Priority Level (PWMB_RL IPL)—Bits 9–8

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.10.5 ADC A Zero Crossing Interrupt Priority Level (ADCA_ZC IPL)— Bits 7–6

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.10.6 ADC B Zero Crossing Interrupt Priority Level (ADCB_ZC IPL)— Bits 5–4

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.10.7 ADC A Conversion Complete Interrupt Priority Level (ADCA_CC IPL)—Bits 3–2

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.10.8 ADC B Conversion Complete Interrupt Priority Level (ADCB_CC IPL)—Bits 1–0

This field is used to set the interrupt priority level for IRQs. This IRQ is limited to priorities 0 through 2. They are disabled by default.

- 00 = IRQ disabled (default)
- 01 = IRQ is priority level 0
- 10 = IRQ is priority level 1
- 11 = IRQ is priority level 2

5.6.11 Vector Base Address Register (VBA)

Base + \$A	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0					\/	ECTOR	BASE A	DDDES	c	-			
Write								V	LOTOR	DAGE A	IDDINES	3				
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-13 Vector Base Address Register (VBA)

5.6.11.1 Reserved—Bits 15–13

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.11.2 Interrupt Vector Base Address (VECTOR BASE ADDRESS)— Bits 12–0

The contents of this register determine the location of the Vector Address Table. The value in this register is used as the upper 13 bits of the interrupt Vector Address Bus (VAB[20:0]). The lower eight bits are determined based upon the highest-priority interrupt. They are then appended onto VBA before presenting the full VAB to the 56800E core; see Section 5.3.1 for details.

5.6.12 Fast Interrupt 0 Match Register (FIM0)

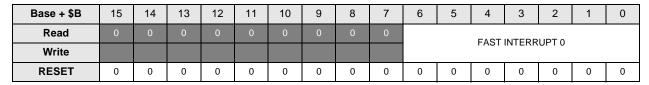


Figure 5-14 Fast Interrupt 0 Match Register (FIM0)

5.6.12.1 Reserved—Bits 15–7

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.12.2 Fast Interrupt 0 Vector Number (FAST INTERRUPT 0)—Bits 6-0

This value determines which IRQ will be a Fast Interrupt 0. Fast interrupts vector directly to a service routine based on values in the Fast Interrupt Vector Address registers without having to go to a jump table first; see Section 5.3.3. IRQs used as fast interrupts *must* be set to priority level two. Unexpected results will occur if a fast interrupt vector is set to any other priority. Fast interrupts automatically become the highest priority level 2 interrupt regardless of their location in the interrupt table, prior to being declared as fast interrupt. Fast Interrupt 0 has priority over Fast Interrupt 1. To determine the vector number of each IRQ, refer to Table 4-5.

5.6.13 Fast Interrupt 0 Vector Address Low Register (FIVAL0)

Base + \$C	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read						FAST IN	ITEDDI	IDT 0 \/E	CTOP	۸۵۵۵	SSIOW					
Write						IASTIN	VILNIC	IF I U VL	LOTOK /	HUUNL	33 LOW					
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-15 Fast Interrupt 0 Vector Address Low Register (FIVAL0)

5.6.13.1 Fast Interrupt 0 Vector Address Low (FIVAL0)—Bits 15–0

The lower 16 bits of the vector address used for fast interrupt 0. This register is combined with FIVAH0 to form the 21-bit vector address for Fast Interrupt 0 defined in the FIM0 register.

5.6.14 Fast Interrupt 0 Vector Address High Register (FIVAH0)

Base + \$D	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	0	0	0	0	FA	ST INTE	RRUPT	0 VECT	OR
Write													ADD	RESS F	lIGH	
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-16 Fast Interrupt 0 Vector Address High Register (FIVAH0)

5.6.14.1 Reserved—Bits 15-5

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.14.2 Fast Interrupt 0 Vector Address High (FIVAH0)—Bits 4–0

The upper five bits of the vector address used for Fast Interrupt 0. This register is combined with FIVAL0 to form the 21-bit vector address for Fast Interrupt 0 defined in the FIM0 register.

5.6.15 Fast Interrupt 1 Match Register (FIM1)

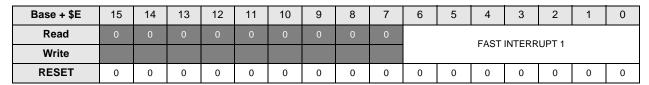


Figure 5-17 Fast Interrupt 1 Match Register (FIM1)

5.6.15.1 Reserved—Bits 15–7

This bit field is reserved or not implemented. It is read as 0, but cannot be modified by writing.

5.6.15.2 Fast Interrupt 1 Vector Number (FAST INTERRUPT 1)—Bits 6–0

This value determines which IRQ will be a Fast Interrupt 1. Fast interrupts vector directly to a service routine based on values in the Fast Interrupt Vector Address registers without having to go to a jump table first; see Section 5.3.3. IRQs used as fast interrupts *must* be set to priority level 2. Unexpected results will occur if a fast interrupt vector is set to any other priority. Fast interrupts automatically become the highest-priority level 2 interrupt regardless of their location in the interrupt table prior to being declared as fast interrupt. Fast Interrupt 0 has priority over Fast Interrupt 1. To determine the vector number of each IRO, refer to Table 4-5.

5.6.16 Fast Interrupt 1 Vector Address Low Register (FIVAL1)

Base + \$F	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read							FAST II	NTERRI	JPT 1 VI	ECTOR						
Write								ADDRE	SS LOW							
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 5-18 Fast Interrupt 1 Vector Address Low Register (FIVAL1)

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5.6.16.1 Fast Interrupt 1 Vector Address Low (FIVAL1)—Bits 15–0

The lower 16 bits of vector address are used for Fast Interrupt 1. This register is combined with FIVAL1 to form the 21-bit vector address for Fast Interrupt 1 defined in the FIM1 register.

5.6.17 Fast Interrupt 1 Vector Address High Register (FIVAH1)

Base + \$10	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
Read	0	0	0	0	0	0	0	0	0	0	0	FA	ST INTE	RRUPT	1 VECT	OR	
Write													FAST INTERRUPT 1 VECTOR ADDRESS HIGH				
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	

Figure 5-19 Fast Interrupt 1 Vector Address High Register (FIVAH1)

5.6.17.1 Reserved—Bits 15-5

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

5.6.17.2 Fast Interrupt 1 Vector Address High (FIVAH1)—Bits 4–0

The upper five bits of the vector address used for Fast Interrupt 1. This register is combined with FIVAH1 to form the 21-bit vector address for Fast Interrupt 1 defined in the FIM1 register.

5.6.18 IRQ Pending 0 Register (IRQP0)

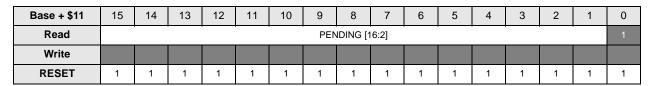


Figure 5-20 IRQ Pending 0 Register (IRQP0)

5.6.18.1 IRQ Pending (PENDING)—Bits 15–1

This register combines with the other five to represent the pending IRQs for interrupt vector numbers 2 through 81.

- 0 = IRQ pending for this vector number
- 1 = No IRQ pending for this vector number

5.6.18.2 Reserved—Bit 0

This bit is reserved or not implemented. It is read as 1 and cannot be modified by writing.

5.6.19 IRQ Pending 1 Register (IRQP1)

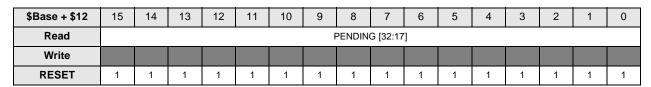


Figure 5-21 IRQ Pending 1 Register (IRQP1)

5.6.19.1 IRQ Pending (PENDING)—Bits 32-17

This register combines with the other five to represent the pending IRQs for interrupt vector numbers 2 through 81.

- 0 = IRQ pending for this vector number
- 1 = No IRQ pending for this vector number

5.6.20 IRQ Pending 2 Register (IRQP2)

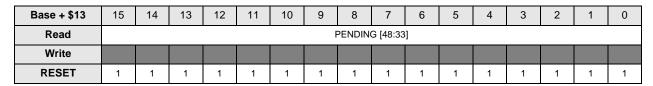


Figure 5-22 IRQ Pending 2 Register (IRQP2)

5.6.20.1 IRQ Pending (PENDING)—Bits 48-33

This register combines with the other five to represent the pending IRQs for interrupt vector numbers 2 through 81.

- 0 = IRQ pending for this vector number
- 1 = No IRQ pending for this vector number

5.6.21 IRQ Pending 3 Register (IRQP3)

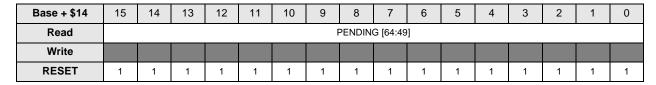


Figure 5-23 IRQ Pending 3 Register (IRQP3)

5.6.21.1 IRQ Pending (PENDING)—Bits 64–49

This register combines with the other five to represent the pending IRQs for interrupt vector numbers 2 through 81.

- 0 = IRQ pending for this vector number
- 1 = No IRQ pending for this vector number

5.6.22 IRQ Pending 4 Register (IRQP4)

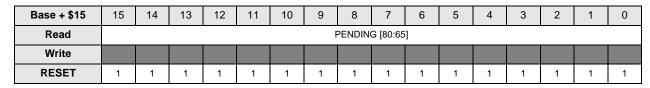


Figure 5-24 IRQ Pending 4 Register (IRQP4)

5.6.22.1 IRQ Pending (PENDING)—Bits 80-65

This register combines with the other five to represent the pending IRQs for interrupt vector numbers 2 through 81.

- 0 = IRQ pending for this vector number
- 1 = No IRQ pending for this vector number

5.6.23 IRQ Pending 5 Register (IRQP5)

Base + \$16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	PEND- ING [81]
Write																
RESET	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1

Figure 5-25 IRQ Pending Register 5 (IRQP5)

5.6.23.1 Reserved—Bits 96-82

This bit field is reserved or not implemented. The bits are read as 1 and cannot be modified by writing.

5.6.23.2 IRQ Pending (PENDING)—Bit 81

This register combines with the other five to represent the pending IRQs for interrupt vector numbers 2 through 81.

- 0 = IRQ pending for this vector number
- 1 = No IRQ pending for this vector number
- 5.6.24 Reserved—Base + 17
- 5.6.25 Reserved—Base + 18
- 5.6.26 Reserved—Base + 19
- 5.6.27 Reserved—Base + 1A
- 5.6.28 Reserved—Base + 1B
- 5.6.29 Reserved—Base + 1C

5.6.30 ITCN Control Register (ICTL)

Base + \$1D	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	INT	IP	IC				VAB				INT_DIS	1	IRQB STATE	IRQA STATE	ĪRQB	ĪRQA
Write											IINI_DIS				EDG	EDG
RESET	0	0	0	1	0	0	0	0	0	0	0	1	1	1	0	0

Figure 5-26 ITCN Control Register (ICTL)

5.6.30.1 Interrupt (INT)—Bit 15

This read-only bit reflects the state of the interrupt to the 56800E core.

- 0 = No interrupt is being sent to the 56800E core
- 1 = An interrupt is being sent to the 56800E core

5.6.30.2 Interrupt Priority Level (IPIC)—Bits 14–13

These *read-only* bits reflect the state of the new interrupt priority level bits being presented to the 56800E core at the time the last IRQ was taken. This field is only updated when the 56800E core jumps to a new interrupt service routine.

Note: Nested interrupts may cause this field to be updated before the original interrupt service routine can read it.

- 00 = Required nested exception priority levels are 0, 1, 2, or 3
- 01 = Required nested exception priority levels are 1, 2, or 3
- 10 = Required nested exception priority levels are 2 or 3
- 11 = Required nested exception priority level is 3

5.6.30.3 Vector Number - Vector Address Bus (VAB)—Bits 12–6

This *read-only* field shows the vector number (VAB[7:1]) used at the time the last IRQ was taken. This field is only updated when the 56800E core jumps to a new interrupt service routine.

Note: Nested interrupts may cause this field to be updated before the original interrupt service routine can read it.

5.6.30.4 Interrupt Disable (INT_DIS)—Bit 5

This bit allows all interrupts to be disabled.

- 0 = Normal operation (default)
- 1 = All interrupts disabled

5.6.30.5 Reserved—Bit 4

This bit field is reserved or not implemented. It is read as 1 and cannot be modified by writing.

5.6.30.6 IRQB State Pin (IRQB STATE)—Bit 3

This *read-only* bit reflects the state of the external \overline{IRQB} pin.

5.6.30.7 IRQA State Pin (IRQA STATE)—Bit 2

This *read-only* bit reflects the state of the external \overline{IRQA} pin.

5.6.30.8 IRQB Edge Pin (IRQB Edg)—Bit 1

This bit controls whether the external \overline{IRQB} interrupt is edge or level sensitive. During Stop and Wait modes, it is automatically level sensitive.

- $0 = \overline{IRQB}$ interrupt is a low-level sensitive (default)
- $1 = \overline{IRQB}$ interrupt is falling-edge sensitive.

5.6.30.9 IRQA Edge Pin (IRQA Edg)—Bit 0

This bit controls whether the external \overline{IRQA} interrupt is edge or level sensitive. During Stop and Wait modes, it is automatically level sensitive.

- $0 = \overline{IRQA}$ interrupt is a low-level sensitive (default)
- $1 = \overline{IRQA}$ interrupt is falling-edge sensitive.

5.7 Resets

5.7.1 Reset Handshake Timing

The ITCN provides the 56800E core with a reset vector address whenever \overline{RESET} is asserted. The reset vector will be presented until the second rising clock edge after \overline{RESET} is released.

5.7.2 ITCN After Reset

After reset, all of the ITCN registers are in their default states. This means all interrupts are disabled, except the core IRQs with fixed priorities: Illegal Instruction; SW Interrupt 3; HW Stack Overflow; Misaligned Long Word Access; SW Interrupt 2; SW Interrupt 1; SW Interrupt 0; and SW Interrupt LP. These interrupts are enabled at their fixed priority levels.

Part 6 System Integration Module (SIM)

6.1 Overview

The SIM module is a system catchall for the glue logic that ties together the system-on-chip. It controls distribution of resets and clocks and provides a number of control features. The system integration module is responsible for the following functions:

- Reset sequencing
- Clock generation & distribution
- Stop/Wait control
- Pull-up enables for selected peripherals
- System status registers
- Registers for software access to the JTAG ID of the chip
- Enforcing Flash security

6.2 Features

The SIM has the following features:

- Flash security feature prevents unauthorized access to code/data contained in on-chip Flash memory
- · Power saving clock gating for peripheral
- Three power modes (Run, Wait, Stop) to control power utilization
 - Stop mode shuts down the 56800E core, system clock, peripheral clock, and PLL operation
 - Stop mode entry can optionally disable PLL and Oscillator (low power vs. fast restart); must be done explicitly
 - Wait mode shuts down the 56800E core and unnecessary system clock operation
 - Run mode supports full part operation
- Controls to enable/disable the 56800E core WAIT and STOP instructions
- Calculates base delay for reset extension based upon POR and RESET values. Reset delay will be either 3 x 32 clocks (phased release of reset) or 2^21 clock cycles.
- Controls Reset sequencing after reset
- Software-initiated reset
- Four 16-bit registers reset only by a Power-On Reset usable for general purpose software control
- System Control Register
- Registers for software access to the JTAG ID of the chip

6.3 Operating Modes

Since the SIM is responsible for distributing clocks and resets across the chip, it must understand the various chip operating modes and take appropriate action. These are:

• **Reset Mode,** which has two submodes:

Hardware Reset Mode
 56800E Core and all peripherals are reset. This occurs when the internal POR is asserted, the RESET pin is asserted or when the COP timer times out.

— Software Reset Mode Software reset occurs when a 1 is written into the software RESET (SWRST) bit in the SIM Control Register (SIM_CONTROL). This reset mode is identical to the H/W RESET mode except since the EMI_MODE and EXTBOOT pins are ignored at reset, EXTBOOT is ignored, and the state of the mA bit is conserved.

Run Mode

This is the primary mode of operation for this device. In this mode, the 56800E controls chip operation.

Debug Mode

The 56800E is controlled via JTAG/EOnCE when in debug mode. All peripherals continue to run except the COP and PWMs. COP is disabled and PWM outputs are optionally switched off to disable any motor from being driven; see the PWM chapter in the **56F8300 Peripheral User Manual** for details.

Wait Mode

In Wait mode, the core clock and memory clocks are disabled. Optionally, the COP can be stopped. Similarly, it is an option to switch off PWM outputs to disable any motor from being driven. All other peripherals continue to run.

Stop Mode

When in Stop mode, the 56800E core, memory, and most peripheral clocks are shut down. Optionally, the COP and CAN can be stopped. For lowest power consumption in Stop mode, the PLL can be shut down. This must be done explicitly before entering Stop mode, since there is no automatic mechanism for this. The CAN (along with any non-gated interrupt) is capable of waking the chip up from Stop mode, but is not fully functional in Stop mode.

6.4 Operation Mode Register

Bit	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	NL							СМ	XP	SD	R	SA	EX	0	MB	MA
Туре	R/W							R/W	R/W	R/W	R/W	R/W	R/W		R/W	R/W
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 6-1 OMR

See Section 4.2 for detailed information on how the Operating Mode Register (OMR) MA and MB bits operate in this device. Additional information on the EX bit see Section 4.4. For all other bits see, Section 8.2.1 of the DSP56800E Reference Manual.

Note: The OMR is not a Memory Map register; it is directly accessible in code through the acronym OMR.

6.5 Register Descriptions

Table 6-1 SIM Registers (SIM_BASE = \$00F350)

Address Acronym	Address Offset	Register Name	Section Location
SIM_CONTROL	Base + \$0	Control Register	6.5.1
SIM_RSTSTS	Base + \$1	Reset Status Register	6.5.2
SIM_SCR0	Base + \$2	Software Control Register 0	6.5.3
SIM_SCR1	Base + \$3	Software Control Register 1	6.5.3
SIM_SCR2	Base + \$4	Software Control Register 2	6.5.3
SIM_SCR3	Base + \$5	Software Control Register 3	6.5.3
SIM_MSH_ID	Base + \$6	Most Significant Half of JTAG ID	6.5.4
SIM_LSH_ID	Base + \$7	Least Significant Half of JTAG ID	6.5.5
SIM_PUDR	Base + \$8	Pull-up Disable Register	6.5.6
		Reserved	
SIM_CLKOSR	Base + \$A	CLKO Select Register	6.5.7
SIM_GPS	Base + \$B	GPIO Peripheral Select Register	6.5.7
SIM_PCE	Base + \$C	Peripheral Clock Enable Register	6.5.8
SIM_ISALH	Base + \$D	I/O Short Address Location High Register	6.5.9
SIM_ISALL	Base + \$E	I/O Short Address Location Low Register	6.5.10

Add. Offset	Register Name		15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
\$0	SIM_ CONTROL	R W	0	0	0	0	0	0	0	0	0	0	Once Ebl	SW Rst	stop_	disable	wait_c	lisable
	SIM	R	0	0	0	0	0	0	0	0	0	0					0	0
\$1	RSTSTS	W											SWR	COPR	EXTR	POR		
\$2	SIM_SCR0	R W								FIE	LD							
\$3	SIM_SCR1	R W								FIE	LD							
\$4	SIM_SCR2	R W								FIE	LD							
\$5	SIM_SCR3	R W								FIE	LD							
\$6	SIM_MSH_	R	0	0	0	0	0	0	0	1	1	1	1	1	0	1	0	0
	ID	W																
\$7	SIM_LSH_ID	R W	0	1	0	0	0	0	0	0	0	0	0	1	1	1	0	1
\$8	SIM PUDR	R	0	PWMA 1	CAN	EMI_ MODE	RESET	IRQ	XBOOT	PWMB	PWMA 0	0	CTRL	0	JTAG	0	0	0
ΨΟ		W	0	PWMA 1	CAN	EMI_ MODE	RESET	IRQ	XBOOT	PWMB	PWMA 0		CTRL		JTAG			
	Reserved												211/212					
\$A	SIM_ CLKOSR	R W	0	0	0	0	0	0	A23 A23	A22 A22	A21 A21	A20 A20	CLKDIS			CLKOSEI		
		R	0	0	0	0	0	0	A23	A22	0 0	A20	OLKDIS 0	0	HOME	INDEX		PHA
\$B	SIM_GPS	W								0					_ALT	_ALT	_ALT	_ALT
\$C	SIM_PCE	R W	EMI	ADCB	ADCA	CAN	DEC1	DEC0	TMRD	TMRC	TMRB	TMRA	SCI1	SCI0	SPI1	SPI0	PWM B	PWM
\$D	SIM_ISALH	R W	1	1	1	1	1	1	1	1	1	1	1	1	1	1	ISAL[23:22]
\$E	SIM_ISALL	R W								ISAL	[21:6]							

 R
 0
 = Read as 0

 W
 = Reserved

Figure 6-2 SIM Register Map Summary

6.5.1 SIM Control Register (SIM_CONTROL)

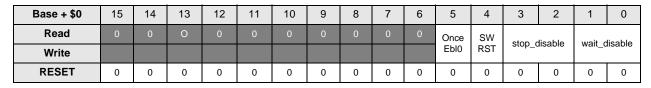


Figure 6-3 SIM Control Register (SIM_CONTROL)

6.5.1.1 Reserved—Bits 15-6

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

6.5.1.2 OnCE Enable (OnCEEBL)—Bit 5

- 0 = OnCE clock to 56800E core enabled when core TAP is enabled
- 1 = OnCE clock to 56800E core is always enabled

6.5.1.3 Software Reset (SWRST)—Bit 4

Writing 1 to this field will cause the part to reset.

6.5.1.4 Stop Disable (STOP_DISABLE)—Bits 3–2

- 00 STOP mode will be entered when the 56800E core executes a STOP instruction
- 01 The 56800E STOP instruction will not cause entry into Stop mode; stop_disable can be reprogrammed in the future
- 10 The 56800E STOP instruction will not cause entry into Stop mode; stop_disable can then only be changed by resetting the device
- 11 Same operation as 10

6.5.1.5 Wait Disable (WAIT_DISABLE)—Bits 1–0

- 00 WAIT mode will be entered when the 56800E core executes a WAIT instruction
- 01 The 56800E WAIT instruction will not cause entry into Wait mode; wait_disable can be reprogrammed in the future
- 10 The 56800E WAIT instruction will not cause entry into Wait mode; wait_disable can then only be changed by resetting the device
- 11 Same operation as 10

6.5.2 SIM Reset Status Register (SIM_RSTSTS)

Bits in this register are set upon any system reset and are initialized only by a Power-On Reset (POR). A reset (other than POR) will only set bits in the register; bits are not cleared. Software should only clear this register.

Base + \$1	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	0	0	0	SWR	COPR	EXTR	POR	0	0
Write											SWK	COPK	EXIK	FUR		
RESET	0	0	0	0	0	0	0	0	0	0					0	0

Figure 6-4 SIM Reset Status Register (SIM RSTSTS)

6.5.2.1 Reserved—Bits 15–6

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

6.5.2.2 Software Reset (SWR)—Bit 5

When 1, this bit indicates that the previous reset occurred as a result of a software reset (write to SWRST bit in the SIM_CONTROL register). This bit will be cleared by any hardware reset or by software. Writing a 0 to this bit position will set the bit, while writing a 1 to the bit will clear it.

6.5.2.3 COP Reset (COPR)—Bit 4

When 1, the COPR bit indicates the Computer Operating Properly (COP) timer-generated reset has occurred. This bit will be cleared by a Power-On Reset or by software. Writing a 0 to this bit position will set the bit, while writing a 1 to the bit will clear it.

6.5.2.4 External Reset (EXTR)—Bit 3

If 1, the EXTR bit indicates an external system reset has occurred. This bit will be cleared by a Power-On Reset or by software. Writing a 0 to this bit position will set the bit, while writing a 1 to the bit position will clear it. Basically, when the EXTR bit is 1, the previous system reset was caused by the external RESET pin being asserted low.

6.5.2.5 Power on Reset (POR)—Bit 2

When 1, the POR bit indicates a Power-On Reset occurred some time in the past. This bit can only be cleared by software or by another type of reset. Writing a 0 to this bit will set the bit, while writing a 1 to the bit position will clear the bit. In summary, if the bit is 1, the previous system reset was due to a Power-On Reset.

6.5.2.6 Reserved—Bits 1–0

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

6.5.3 SIM Software Control Registers (SIM_SCR0, SIM_SCR1, SIM_SCR2, and SIM_SCR3)

Only SIM_SCR0 is shown below. SIM_SCR1, SIM_SCR2, and SIM_SCR3 are identical in functionality.

Base + \$2	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read								FIEL	<u> </u>							<u>, </u>
Write								FIEL	D							
POR	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 6-5 SIM Software Control Register 0 (SIM_SCR0)

6.5.3.1 Software Control Data 1 (FIELD)—Bits 15–0

This register is reset only by the Power-On Reset (POR). It has no part-specific functionality and is intended for use by software developers to contain data that will be unaffected by the other reset sources (reset pin, software reset, and COP reset).

6.5.4 Most Significant Half of JTAG ID (SIM_MSH_ID)

This read-only register displays the most significant half of the JTAG ID for the chip. This register reads \$01F4.

Base + \$6	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	1	1	1	1	1	0	1	0	0
Write																
RESET	0	0	0	0	0	0	0	1	1	1	1	1	0	1	0	0

Figure 6-6 Most Significant Half of JTAG ID (SIM_MSH_ID)

6.5.5 Least Significant Half of JTAG ID (SIM_LSH_ID)

This read-only register displays the least significant half of the JTAG ID for the chip. This register reads \$401D.

Base + \$7	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	1	0	0	0	0	0	0	0	0	0	1	1	1	0	1
Write																
RESET	0	1	0	0	0	0	0	0	0	0	0	1	1	1	0	1

Figure 6-7 Least Significant Half of JTAG ID (SIM_LSH_ID)

6.5.6 SIM Pull-up Disable Register (SIM_PUDR)

Most of the pins on the chip have on-chip pull-up resistors. Pins which can operate as GPIO can have these resistors disabled via the GPIO function. Non-GPIO pins can have their pull-ups disabled by setting the appropriate bit in this register. Disabling pull-ups is done on a peripheral-by-peripheral basis (for pins not muxed with GPIO). Each bit in the register (see **Figure 6-8**) corresponds to a functional group of pins. See **Table 2-2** to identify which pins can deactivate the internal pull-up resistor.

Base + \$8	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	PWMA1	CAN	EMI_	RESET	IRQ	XBOOT	PWMB	PWMA0	0	CTRL	0	JTAG	0	0	0
Write		1 WIVIA1	CAN	MODE	KLOLI	IIIQ	ABOOT	1 WIVID	1 WWAO		OTKL		3170			
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 6-8 SIM Pull-up Disable Register (SIM_PUDR)

6.5.6.1 PWMA1

This bit controls the pull-up resistors on the FAULTA3 pin.

6.5.6.2 CAN

This bit controls the pull-up resistors on the CAN_RX pin.

6.5.6.3 **EMI MODE**

This bit controls the pull-up resistors on the EMI_MODE pin.

6.5.6.4 RESET

This bit controls the pull-up resistors on the \overline{RESET} pin.

6.5.6.5 IRQ

This bit controls the pull-up resistors on the \overline{IRQA} and \overline{IRQB} pins.

6.5.6.6 XBOOT

This bit controls the pull-up resistors on the EXTBOOT pin.

6.5.6.7 PWMB

This bit controls the pull-up resistors on the FAULTB0, FAULTB1, FAULTB2, and FAULTB3 pins.

6.5.6.8 PWMA0

This bit controls the pull-up resistors on the FAULTA0, FAULTA1, and FAULTA2 pins.

6.5.6.9 CTRL

This bit controls the pull-up resistors on the \overline{WR} and \overline{RD} pins.

6.5.6.10 JTAG

This bit controls the pull-up resistors on the \overline{TRST} , TMS and TDI pins.

6.5.7 CLKO Select Register (SIM_CLKOSR)

The CLKO select register can be used to multiplex out any one of the clocks generated inside the clock generation and SIM modules. The default value is SYS_CLK. All other clocks primarily muxed out are for test purposes only, and are subject to significant unspecified latencies at high frequencies.

The upper four bits of the GPIO B register can function as GPIO, A[23:20], or as additional clock output signals. GPIO has priority and is enabled/disabled via the GPIOB_PER. If GPIO B[7:4] are programmed to operate as peripheral outputs, then the choice between A[23:20] and additional clock outputs is done here in the CLKOSR. The default state is for the peripheral function of GPIO B[7:4] to be programmed as A[23:20]. This can be changed by altering A23 through A20 below.

Base + \$A	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	A23	A22	A21	A20	CLK		C	LKOSEI		
Write							AZS	AZZ	AZI	A20	DIS		C	LNOSLI	-	
RESET	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0

Figure 6-9 CLKO Select Register (SIM_CLKOSR)

6.5.7.1 Reserved—Bits 15-10

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

6.5.7.2 GPIO B[7] Peripheral Function Select (A23)—Bit 9

- 0 = Peripheral output function of GPIO B[7] is defined to be A[23]
- 1 = Peripheral output function of GPIO B[7] is defined to be the oscillator clock (MSTR_OSC, see Figure 3-4)

6.5.7.3 GPIO B[6] Peripheral Function Select (A22)—Bit 8

- 0 = Peripheral output function of GPIO B[6] is defined to be A[22]
- 1 = Peripheral output function of GPIO B[6] is defined to be SYS_CLK_X2

6.5.7.4 GPIO B[5] Peripheral Function Select (A21)—Bit 7

- 0 = Peripheral output function of GPIO B[5] is defined to be A[21]
- 1 = Peripheral output function of GPIO B[5] is defined to be sys clk

6.5.7.5 GPIO B[4] Peripheral Function Select (A20)—Bit 6

- 0 = Peripheral output function of GPIO B[4] is defined to be A[20]
- 1 = Peripheral output function of GPIO B[4] is defined to be the prescaler clock (FREF, see Figure 3-4)

6.5.7.6 Clockout Disable (CLKDIS)—Bit 5

- 0 = CLKOUT output is enabled and will output the signal indicated by CLKOSEL
- 1 = CLKOUT is tri-stated

6.5.7.7 CLockout Select (CLKOSEL)—Bits 4–0

Selects clock to be muxed out on the CLKO pin.

- 00000 = SYS CLK (from OCCS DEFAULT)
- 00001 = Reserved for factory test—56800E clock
- 00010 = Reserved for factory test—XRAM clock
- 00011 = Reserved for factory test—PFLASH odd clock
- 00100 = Reserved for factory test—PFLASH even clock
- 00101 = Reserved for factory test—BFLASH clock
- 00110 = Reserved for factory test—DFLASH clock
- 00111 = Oscillator output
- 01000 = Fout (from OCCS)
- 01001 = Reserved for factory test—IPB clock
- 01010 = Reserved for factory test—Feedback (from OCCS, this is path to PLL)
- 01011 = Reserved for factory test—Prescaler Clk (from OCCS)
- 01100 = Reserved for factory test—Postscaler Clk (from OCCS)
- 01101 = Reserved for factory test—SYS_CLK_x2 (from OCCS)
- 01110 = Reserved for factory test—SYS_CLK_DIV2
- 01111 = Reserved for factory test—SYS_CLK_D
- 10000 = ADCA Clk
- 10001 = ADCB Clk

6.5.8 GPIO Peripheral Select Register (SIM_GPS)

The GPIO Peripheral Select register can be used to multiplex out any one of the three alternate peripherals for GPIOC. The default peripheral is Quad Decoder 1 and Quad Timer B; these peripherals work together.

The four I/O pins associated with GPIO C can function as GPIO, Quad Decoder 1/Quad Timer B or as SPI 1 signals. GPIO is not the default and is enabled/disabled via the GPIOC_PER, as shown in **Figure 6-10** and **Table 6-2**. When GPIO C[3:0] are programmed to operate as peripheral I/O, then the choice between decoder/timer and SPI inputs/outputs is made in the SIM_GPS register and in conjunction with the Quad Timer Status and Control Registers (SCR). The default state is for the peripheral function of GPIO C[3:0] to be programmed as decoder functions. This can be changed by altering the appropriate controls in the indicated registers.

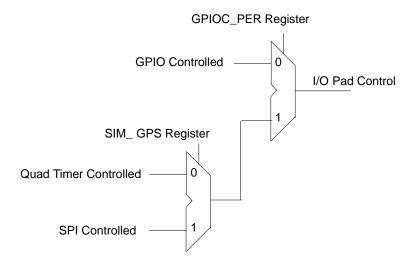


Figure 6-10 Overall Control of Pads Using SIM_GPS Control

Table 6-2 Control of Pads Using SIM_GPS Control ¹

		Contro	ol Registers		
Pin Function	GPIOC_PER	GPIOC_DTR	SIM_GPS	Quad Timer SCR register OEN bits	Comments
GPIO Input	0	0	_	_	
GPIO Output	0	1	_	_	
Quad Timer Input/Quad Decoder Input ²	1	_	0	0	See Table 11-1 in the 56F8300 Peripheral User Manual for the definition of the timer inputs based on the Quad Decoder Mode
Quad Timer Output / Quad Decoder Input ³	1	_	0	1	inputs based on the Quad Decoder Mode
SPI input	1	_	1	_	See SPI controls for determining the direction
SPI output	1	_	1	_	of each of the SPI pins.

^{1.} This applies to the four pins that serve as Quad Decoder / Quad Timer / SPI / GPIOC functions. A separate set of control bits is used for each pin.

^{2.} Reset configuration

^{3.} Quad Decoder pins are always inputs and function in conjunction with the Quad Timer pins.

Base + \$B	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	0	0	0	0	0	0	0	0	0	0	0	0	C3	C2	C1	C0
Write													CS	02	Ci	Cu
RESET	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Figure 6-11 GPIO Peripheral Select Register (SIM_GPS)

6.5.8.1 Reserved—Bits 15–4

This bit field is reserved or not implemented. It is read as 0 and cannot be modified by writing.

6.5.8.2 GPIO C3 (C3)—Bit 3

This bit selects the alternate function for GPIOC3.

- 0 = HOME1/TB3 (default see "Switch Matrix Mode" bits of the Quad Decoder DECCR register)
- $1 = SS_B1$

6.5.8.3 GPIO C2 (C2)—Bit 2

This bit selects the alternate function for GPIOC2.

- 0 = INDEX1/TB2 (default)
- 1 = MISO1

6.5.8.4 GPIO C1 (C1)—Bit 1

This bit selects the alternate function for GPIOC1.

- 0 = PHASEB1/TB1 (default)
- 1 = MOSI1

6.5.8.5 GPIO C0 (C0)—Bit 0

This bit selects the alternate function for GPIOC0.

- 0 = PHASEA1/TB0 (default)
- 1 = SCLK1

6.5.9 Peripheral Clock Enable Register (SIM_PCE)

The Peripheral Clock Enable register is used to enable or disable clocks to the peripherals as a power savings feature. The clocks can be individually controlled for each peripheral on the chip.

Base + \$C	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	EMI	ADCB	ADCA	CAN	DEC1	DEC0	TMRD	TMRC	TMRB	TMRA	SCI 1	SCI 0	SPI 1	SPI 0	PWMB	PWMA
Write	EIVII	ADCB	ADCA	CAN	DECT	DECO	TIVIKU	TIVIKC	TIVIND	TIVIKA	3011	3010	SFII	3710	FVVIVID	FVVIVIA
RESET	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1

Figure 6-12 Peripheral Clock Enable Register (SIM_PCE)

6.5.9.1 External Memory Interface Enable (EMI)—Bit 15

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 =The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.2 Analog-to-Digital Converter B Enable (ADCB)—Bit 14

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 =The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.3 Analog-to-Digital Converter A Enable (ADCA)—Bit 13

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 =The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.4 FlexCAN Enable (CAN)—Bit 12

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 =The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.5 Decoder 1 Enable (DEC1)—Bit 11

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 =The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.6 Decoder 0 Enable (DEC0)—Bit 10

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 =The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.7 Quad Timer D Enable (TMRD)—Bit 9

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 =The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.8 Quad Timer C Enable (TMRC)—Bit 8

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 =The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.9 Quad Timer B Enable (TMRB)—Bit 7

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 =The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.10 Quad Timer A Enable (TMRA)—Bit 6

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 =The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.11 Serial Communications Interface 1 Enable (SCI1)—Bit 5

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 =The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.12 Serial Communications Interface 0 Enable (SCI0)—Bit 4

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 =The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.13 Serial Peripheral Interface 1 Enable (SPI1)—Bit 3

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 =The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.14 Serial Peripheral Interface 0 Enable (SPI0)—Bit 2

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 =The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.15 Pulse Width Modulator B Enable (PWMB)—1

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 =The clock is not provided to the peripheral (the peripheral is disabled)

6.5.9.16 Pulse Width Modulator A Enable (PWMA)—0

Each bit controls clocks to the indicated peripheral.

- 1 = Clocks are enabled
- 0 =The clock is not provided to the peripheral (the peripheral is disabled)

6.5.10 I/O Short Address Location Register (SIM_ISALH and SIM_ISALL)

The I/O Short Address Location registers are used to specify the memory referenced via the I/O short address mode. The I/O short address mode allows the instruction to specify the lower six bits of address and the upper address bits are not directly controllable. This register set allows limited control of the full address, as shown in **Figure 6-13**.

Note:

If this register is set to something other than the top of memory (EOnCE register space) and the EX bit in the OMR is set to 1, the JTAG port cannot access the on-chip EOnCE registers, and debug functions will be affected.

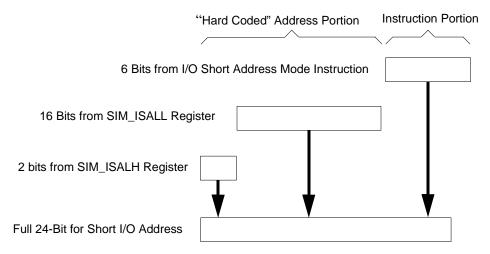


Figure 6-13 I/O Short Address Determination

With this register set, an interrupt driver can set the SIM_ISAL register pair to point to its peripheral registers and then use the I/O Short addressing mode to reference them. The ISR should restore this register to its previous contents prior to returning from interrupt.

Note: The default value of this register set points to the EOnCE registers.

Note: The pipeline delay between setting this register set and using short I/O addressing with the

new value is three cycles.

Base + \$D	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read	1	1	1	1	1	1	1	1	1	1	1	1	1	1	ISAL[:	22.221
Write															юлц	23.22]
RESET	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1

Figure 6-14 I/O Short Address Location High Register (SIM_ISALH)

6.5.10.1 Input/Output Short Address Low (ISAL[23:22])—Bit 1-0

This field represents the upper two address bits of the "hard coded" I/O short address.

Base + \$E	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Read		ISAL[21:6]														
Write								ISAL	_[21.0]							
RESET	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1

Figure 6-15 I/O Short Address Location Low Register (SIM_ISALL)

6.5.10.2 Input/Output Short Address Low (ISAL[21:6])—Bit 15–0

This field represents the lower 16 address bits of the "hard coded" I/O short address.

6.6 Clock Generation Overview

The SIM uses an internal master clock from the OCCS (CLKGEN) module to produce the peripheral and system (core and memory) clocks. The maximum master clock frequency is 120Mhz. Peripheral and system clocks are generated at half the master clock frequency and therefore at a maximum 60Mhz. The SIM provides power modes (STOP, WAIT) and clock enables (SIM_PCE register, CLK_DIS, ONCE_EBL) to control which clocks are in operation. The OCCS, power modes, and clock enables provide a flexible means to manage power consumption.

Power utilization can be minimized in several ways. In the OCCS, crystal oscillator, and PLL may be shut down when not in use. When the PLL is in use, its prescaler and postscaler can be used to limit PLL and master clock frequency. Power modes permit system and/or peripheral clocks to be disabled when unused. Clock enables provide the means to disable individual clocks. Some peripherals provide further controls to disable unused sub-functions. Refer to the Part 3 On-Chip Clock Synthesis (OCCS) and the 56F8300 Peripheral User Manual for further details.

6.7 Power-Down Modes Overview

The 56F8346 operates in one of three power-down modes, as shown in Table 6-3.

Table 6-3 Clock Operation in Power-Down Modes

Mode	Core Clocks	Peripheral Clocks	Description
Run	Active	Active	Device is fully functional
Wait	Core and memory clocks disabled	Active	Peripherals are active and can product interrupts if they have not been masked off. Interrupts will cause the core to come out of its suspended state and resume normal operation. Typically used for power-conscious applications.
Stop	System clocks continued the SIM, but most arreaching memory, continued the system of t		The only possible recoveries from Stop mode are: 1. CAN traffic (1st message will be lost) 2. Non-clocked interrupts 3. COP reset 4. External reset 5. Power-on reset

All peripherals, except the COP/watchdog timer, run off the IPbus clock frequency, which is the same as the main processor frequency in this architecture. The maximum frequency of operation is SYS_CLK = 60MHz.

Refer to the PCE register in **Section 6.5.9** and ADC power modes. Power is a function of the system frequency which can be controlled through the OCCS.

6.8 Stop and Wait Mode Disable Function

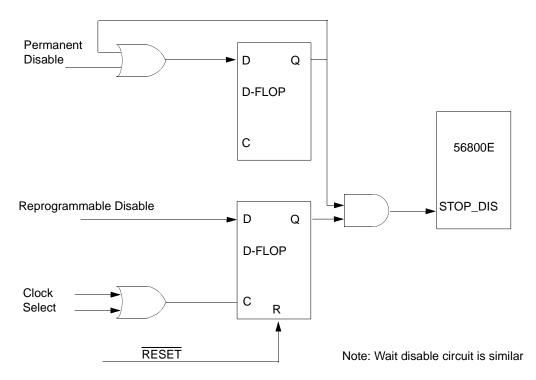


Figure 6-16 Internal Stop Disable Circuit

The 56800E core contains both STOP and WAIT instructions. Both put the CPU to sleep. For lowest power consumption in Stop mode, the PLL can be shut down. This must be done explicitly before entering Stop mode, since there is no automatic mechanism for this. When the PLL is shut down, the 56800E system clock must be set equal to the prescaler output.

Some applications require the 56800E STOP/WAIT instructions be disabled. To disable those instructions, write to the SIM control register (SIM_CONTROL) described in **Section 6.5.1**. This procedure can be on either a permanent or temporary basis. Permanently assigned applications last only until their next reset.

6.9 Resets

The SIM supports four sources of reset. The two asynchronous sources are the external reset pin and the Power-On Reset (POR). The two synchronous sources are the software reset, which is generated within the SIM itself by writting to the SIM_CONTROL register, and the COP reset.

Using an 8MHz crystal, the longest reset time is roughly 1/4 second. The first mode is designed to allow sufficient time for the crystal frequency to stabilize before enabling the rest of the chip. In all other cases, the default delays are set to 64 clock cycles. Alternately, an external reset generation chip may be used. Resets may be asserted asynchronously, but they are always released internally on a rising edge of the system clock.

Part 7 Security Features

The 56F8346 offers security features intended to prevent unauthorized users from reading the contents of the FM array. The 56F8346's Flash security consists of several hardware interlocks that block the means by which an unauthorized user could gain access to the Flash array.

However, part of the security must lie with the user's code. An extreme example would be user's code that dumps the contents of the internal program, as this code would defeat the purpose of security. At the same time, the user may also wish to put a "backdoor" in his program. As an example, the user downloads a security key through the SCI, allowing access to a programming routine that updates parameters stored in another section of the Flash.

7.1 Operation with Security Enabled

Once the user has programmed the Flash with his application code, the 56F8346 can be secured by programming the security bytes located in the FM configuration field, which occupies a portion of the FM array. These non-volatile bytes will keep the part secured through reset and through power-down of the device. Only two bytes within this field are used to enable or disable security. Refer to the Flash Memory section in the **56F8300 Peripheral User Manual** for the state of the security bytes and the resulting state of security. When Flash security mode is enabled in accordance with the method described in the Flash Memory module specification, the 56F8346 will disable external P-space accesses restricting code execution to internal memory, disable EXTBOOT=1 mode, and disable the core EOnCE debug capabilities. Normal program execution is otherwise unaffected.

7.2 Flash Access Blocking Mechanisms

The 56F8346 has several operating functional and test modes. Effective Flash security must address operating mode selection and anticipate modes in which the on-chip Flash can be compromised and read without explicit user permission. Blocking these are outlined in the next subsections.

7.2.1 Forced Operating Mode Selection

At boot time, the SIM determines in which functional modes the 56F8346 will operate. These are:

- Internal Boot Mode
- External Boot Mode
- Secure Mode

When Flash security is enabled as described in the Flash Memory module specification, the 56F8346 will boot in internal boot mode, disable all access to external P-space, and start executing code from the Boot Flash at address 0x02_0000.

This security affords protection only to applications in which the 56F8346 operates in internal Flash security mode. Therefore, the security feature cannot be used unless all executing code resides on-chip.

When security is enabled, any attempt to override the default internal operating mode by asserting the EXTBOOT pin in conjunction with reset will be ignored.

7.2.2 Disabling EOnCE Access

On-chip Flash can be <u>read by</u> issuing commands across the EOnCE port, which is the debug interface for the 56800E core. The TRST, TCLK, TMS, TDO, and TDI pins comprise a JTAG interface onto which the EOnCE port functionality is mapped. When the 56F8346 boots, the chip-level JTAG TAP (Test Access Port) is active and provides the chip's boundary scan capability and access to the ID register.

Proper implementation of Flash security requires that no access to the EOnCE port is provided when security is enabled. The 56800E core has an input which disables reading of internal memory via the EOnCE/JTAG. The FM sets this input at reset to a value determined by the contents of the FM security bytes.

7.2.3 Flash LOCKOUT_RECOVERY

If a user inadvertently enables security on the 56F8346, a lockout recovery mechanism is provided which allows the complete erasure of the internal Flash contents, including the configuration field, and thus disables security (the protection register is cleared). This does not compromise security, as the entire contents of the user's secured code stored in Flash are erased before security is disabled on the 56F8346 on the next reset or power-up sequence. To start the lockout recovery sequence, the JTAG public instruction (LOCKOUT_RECOVERY) must first be shifted into the chip-level TAP controller's instruction register.

The LOCKOUT_RECOVERY instruction has an associated 7-bit Data Register (DR) that is used to control the clock divider circuit within the FM module. This divider, FM_CLKDIV[6:0], is used to control the period of the clock used for timed events in the FM erase algorithm. This register must be set with appropriate values before the lockout sequence can begin. Refer to the JTAG section of the **56F8300 Peripheral User Manual** for more details on setting this register value.

The value of the JTAG FM_CLKDIV[6:0] will replace the value of the FM register FMCLKD that divides down the system clock for timed events, as illustrated in **Figure 7-1**. FM_CLKDIV[6] will map to the PRDIV8 bit, and FM_CLKDIV[5:0] will map to the DIV[5:0] bits. The combination of PRDIV8 and DIV must divide the FM input clock down to a frequency of 150kHz-200kHz. The "Writing the FMCLKD Register" section in the Flash Memory chapter of the **56F8300 Peripheral User Manual** gives specific equations for calculating the correct values.

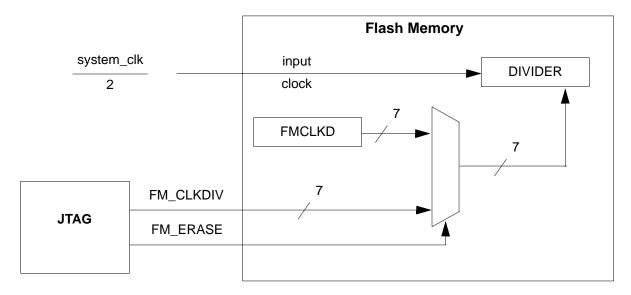


Figure 7-1 JTAG to FM Connection for LOCKOUT_RECOVERY

Two examples of FM_CLKDIV calculations follow.

EXAMPLE 1: If the system clock is the 8MHz crystal frequency because the PLL has not been set up, the input clock will be below 12.8MHz, so PRDIV8 = HFM_CLKDIV[6] = 0. Using the following equation yields a DIV value of 19 for a clock of 200kHz, and a DIV value of 20 for a clock of 190kHz. This translates into an HFM_CLKDIV[6:0] value of \$13 or \$14, respectively.

$$\frac{150[\text{kHz}]}{\text{(DIV}+1)} < \frac{\left(\frac{\text{system_clk}}{(2)}\right)}{(\text{DIV}+1)} < 200[\text{kHz}]$$

EXAMPLE 2: In this example, the system clock has been set up with a value of 32MHz, making the FM input clock 16MHz. Because that is greater than 12.8MHz, PRDIV8 = FM_CLKDIV[6] = 1. Using the following equation yields a DIV value of 9 for a clock of 200kHz, and a DIV value of 10 for a clock of 181kHz. This translates to an FM_CLKDIV[6:0] value of \$49 or \$4A, respectively.

$$150[\text{kHz}] < \frac{\left(\frac{\text{system_clk}}{(2)(8)}\right)}{(\text{DIV} + 1)} < 200[\text{kHz}]$$

Once the LOCKOUT_RECOVERY instruction has been shifted into the instruction register, the clock divider value must be shifted into the corresponding 7-bit data register. After the data register has been updated, the user must transition the TAP controller into the RUN-TEST/IDLE state for the lockout sequence to commence. The controller must remain in this state until the erase sequence has completed. For details, see the JTAG Section in the **56F8300 Peripheral User Manual**.

Note:

Once the lockout recovery sequence has completed, the user must reset both the JTAG TAP controller (by asserting \overline{TRST}) and the 56F8346 (by asserting external chip reset) to return to normal unsecured operation.

7.2.4 Product Analysis

The recommended method of unsecuring a programmed 56F8346 for product analysis of field failures is via the backdoor key access. The customer would need to supply Motorola with the backdoor key and the protocol to access the backdoor routine in the Flash. Additionally, the KEYEN bit that allows backdoor key access must be set.

An alternative method for performing analysis on a secured hybrid controller would be to mass-erase and reprogram the Flash with the original code, but modify the security bytes.

To insure that a customer does not inadvertently lock himself out of the 56F8346 during programming, it is recommended that he program the backdoor access key first, his application code second, and the security bytes within the FM configuration field last.

Part 8 General Purpose Input/Output (GPIO)

8.1 Introduction

This section is intended to supplement the GPIO information found in the 56F8300 Peripheral User Manual and contains only chip-specific information. Any information contained here supercedes the generic information in the 56F8300 Peripheral User Manual.

8.2 Configuration

There are six GPIO ports defined on the 56F8346. The width of each port and the associated peripheral function is shown in **Table 8-1**. The specific mapping of GPIO port pins is shown in **Table 8-2**.

Table 8-1 GPIO Ports Configuration

GPIO Port	Port Width	Available Pins in 56F8346	Peripheral Function	Reset Function
Α	14	14	14 pins - EMI Address pins	EMI Address
В	8	1	1 pin - EMI Address pin 7 pins - EMI Address pins - Not available in this package	EMI Address N/A
С	11	11	4 pins -DEC1 / TMRB / SPI1 4 pins -DEC0 / TMRA 3 pins -PWMA current sense	DEC1 / TMRB DEC0 / TMRA PWMA current sense
D	13	9	2 pins - EMI CSn 4 pins - EMI CSn - Not available in this package 2 pins - SCI1 2 pins - EMI CSn 3 pins -PWMB current sense	EMI Chip Selects N/A SCI1 EMI Chip Selects PWMB current sense
E	14	11	2 pins - SCI0 2 pins - EMI Address pins 4 pins - SPI0 1 pin - TMRC 1 pin - TMRC 2 pins - TMRD 2 pins - TMRD	SCI0 EMI Address SPI0 TMRC N/A TMRD N/A
F	16	16	16 pins - EMI Data	EMI Data

Table 8-2 GPIO External Signals Map

GPIO Port	GPIO Bit	Reset Function	Functional Signal
	0	Peripheral	A8
	1	Peripheral	A9
	2	Peripheral	A10
	3	Peripheral	A11
	4	Peripheral	A12
	5	Peripheral	A13
GPIOA	6	Peripheral	A14
GFIOA	7	Peripheral	A15
	8	Peripheral	A0
	9	Peripheral	A1
	10	Peripheral	A2
	11	Peripheral	A3
	12	Peripheral	A4
	13	Peripheral	A5
	0	GPIO	A16
	1	NA	NA
	2	NA	NA
GPIOB	3	NA	NA
GFIOD	4	NA	NA
	5	NA	NA
	6	NA	NA
	7	NA	NA

Table 8-2 GPIO External Signals Map (Continued)

GPIO Port	GPIO Bit	Reset Function	Functional Signal
	0	Peripheral	PhaseA1 / TB0 / SCLK1 ¹
	1	Peripheral	PhaseB1 / TB1 / MOSI1 ¹
	2	Peripheral	Index1 / TB2 / MISO1 ¹
	3	Peripheral	Home1 / TB3 / SS11
	4	Peripheral	PHASEA0 / TA0
GPIOC	5	Peripheral	PHASEB0 / TA1
	6	Peripheral	Index0 / TA2
	7	Peripheral	Home0 / TA3
	8	Peripheral	ISA0
	9	Peripheral	ISA1
	10	Peripheral	ISA2
	0	GPIO	CS2
	1	GPIO	CS3
	2	NA	NA
	3	NA	NA
	4	NA	NA
	5	NA	NA
GPIOD	6	Peripheral	TXD1
	7	Peripheral	RXD1
	8	Peripheral	PS / CS0
	9	Peripheral	DS / CS1
	10	Peripheral	ISB0
	11	Peripheral	ISB1
	12	Peripheral	ISB2

Table 8-2 GPIO External Signals Map (Continued)

GPIO Port	GPIO Bit	Reset Function	Functional Signal
	0	Peripheral	TXD0
	1	Peripheral	RXD0
	2	Peripheral	A6
	3	Peripheral	A7
	4	Peripheral	SCLK0
	5	Peripheral	MOSI0
GPIOE	6	Peripheral	MISO0
GPIOE	7	Peripheral	SS0
	8	Peripheral	TC0
	9	NA	NA
	10	Peripheral	TD0
	11	Peripheral	TD1
	12	NA	NA
	13	NA	NA
	0	Peripheral	D7
	1	Peripheral	D8
	2	Peripheral	D9
	3	Peripheral	D10
	4	Peripheral	D11
	5	Peripheral	D12
	6	Peripheral	D13
GPIOF	7	Peripheral	D14
GFIOF	8	Peripheral	D15
	9	Peripheral	D0
	10	Peripheral	D1
	11	Peripheral	D2
	12	Peripheral	D3
	13	Peripheral	D4
	14	Peripheral	D5
	15	Peripheral	D6

^{1.} See Section 6.5.8 to determine how to select peripherals from this set; DEC1 is the selected peripheral at reset .

8.3 Memory Maps

The width of the GPIO port defines how many bits are implemented in each of the GPIO registers. Based on this and the default function of each of the GPIO pins, the reset values of the GPIOx_PUR and GPIOx_PER registers change from chip to chip. Tables 4-29 through 4-34 define the actual reset values of these registers for the 56F8346.

Part 9 Joint Test Action Group (JTAG)

9.1 56F8346 Information

Please contact your Motorola marketing representative for device/package-specific BSDL information.

Part 10 Specifications

10.1 General Characteristics

The 56F8346 is fabricated in high-density CMOS with 5V-tolerant TTL-compatible digital inputs. The term "5V-tolerant" refers to the capability of an I/O pin, built on a 3.3V-compatible process technology, to withstand a voltage up to 5.5V without damaging the device. Many systems have a mixture of devices designed for 3.3V and 5V power supplies. In such systems, a bus may carry both 3.3V- and 5V-compatible I/O voltage levels (a standard 3.3V I/O is designed to receive a maximum voltage of 3.3V \pm 10% during normal operation without causing damage). This 5V-tolerant capability therefore offers the power savings of 3.3V I/O levels combined with the ability to receive 5V levels without damage.

Absolute maximum ratings in **Table 10-1** are stress ratings only, and functional operation at the maximum is not guaranteed. Stress beyond these ratings may affect device reliability or cause permanent damage to the device.

Note: All specification meet both Automotive and Industrial requirements unless individual specifications are listed.

CAUTION

This device contains protective circuitry to guard against damage due to high static voltage or electrical fields. However, normal precautions are advised to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate voltage level.

Table 10-1 Absolute Maximum Ratings

 $(V_{SS} = V_{SSA ADC} = 0)$

Characteristic	Symbol	Notes	Min	Max	Unit
Supply voltage	V _{DD_IO}		- 0.3	4.0	V
ADC Supply Voltage	V _{DDA_ADC} , V _{REFH}	V _{REFH} must be less than or equal to V _{DDA_ADC}	- 0.3	4.0	V
Oscillator/PLL Supply Voltage	V _{DDA_OSC_PLL}		- 0.3	4.0	V
Internal Logic Core Supply Voltage	V _{DDA_CORE}	OCR_DIS is High	- 0.3	3.0	V
Input Voltage (digital)	V _{IN}	Pin Groups 1, 2, 5, 6, 9, 10, 14	-0.3	6.0	V
Input Voltage (analog)	V_{INA}	Pin Groups 11, 12, 13	-0.3	4.0	V
Output Voltage	V _{OUT}	Pin Groups 1, 2, 3, 4, 5, 6, 7, 8	-0.3	4.0	V
Output Voltage (open drain)	V _{OD}	Pin Groups 4, 14	-0.3	6.0	V
Ambient Temperature (Automotive)	T _A		-40	125	°C
Ambient Temperature (Industrial)	T _A		-40	105	°C
Junction Temperature (Automotive)	T _J		-40	150	°C
Junction Temperature (Industrial)	T _J		-40	125	°C
Storage Temperature (Automotive)	T _{STG}		-55	150	°C
Storage Temperature (Industrial)	T _{STG}		-55	150	°C

Pin Group 1: TXD0-1, RXD0-1, \$\overline{SS0}\$, MISO0, MOSI0 Pin Group 2: PHASEA0-1, PHASEB0-1, INDEX0-1, HOME0-1, ISB0-2, RSTO, ISA0-2, TC0, SCLK0

Pin Group 3: RSTO, TDO Pin Group 4: CAN_TX

Pin Group 5: A0-5, D0-15, GPIOD0-1, \overline{PS} , \overline{DS}

Pin Group 6: A6-15, GPIOB0, TD0-1 Pin Group 7: CLKO, WR, RD Pin Group 8: PWMA0-5, PWMB0-5

Pin Group 9: IRQA, IRQB, RESET, EXTBOOT, TRST, TMS, TDI, CAN_RX, EMI_MODE, FAULTA0-3, FAULTB0-3

Pin Group 10: TCK

Pin Group 11: XTAL, EXTAL Pin Group 12: ANA0-7, ANB0-7 Pin Group 13: OCR_DIS, CLKMODE

Pin Group 14: DE

Although the 56F8346 is specified to operate correctly over the full -40° C to 125° C ambient temperature range, it is assumed not to be at the extremes of this range 100% of the time.

Table 10-2 Junction Temperature Profile

Temperature	Hours of Operation
40°C	99,000
80°C	27,000
110°C	5,400
125°C	2,700
150°C	900
Total	135,000

Table 10-3 Electrostatic Discharge Protection

Characteristic	Min	Тур	Max	Unit
ESD for Human Body Model (HBM)	2000	_		V
ESD for Machine Model (MM)	200	_	_	V
ESD for Charge Device Model (CDM)	500	_	_	V

Table 10-4 Thermal Characteristics⁶

Characteristic	Comments	Symbol	Value	Unit	Notes	
Characteristic	Comments	Symbol	128-pin LQFP	Oilit	Notes	
Junction to ambient Natural convection		$R_{\theta JA}$	50.8	°C/W	2	
Junction to ambient (@1m/sec)		$R_{\theta JMA}$	46.5	°C/W	2	
Junction to ambient Natural convection	Four layer board (2s2p)	R _{θJMA} (2s2p)	43.9	°C/W	1,2	
Junction to ambient (@1m/sec)	Four layer board (2s2p)	$R_{\theta JMA}$	41.7	°C/W	1,2	
Junction to case		$R_{ heta JC}$	13.9	°C/W	3	
Junction to center of case		Ψ_{JT}	1.2	°C/W	4	
I/O pin power dissipation		P _{I/O}	User Determined	W		
Power dissipation		P _D	$P_D = (I_{DD} \times V_{DD} + P_{I/O})$	W		
Junction to center of case		P _{DMAX}	(TJ - TA) /θJA	°C		

Notes:

- 1. Theta-JA determined on 2s2p test boards is frequently lower than would be observed in an application. Determined on 2s2p thermal test board.
- 2. Junction to ambient thermal resistance, Theta-JA (R_{0,JA}) was simulated to be equivalent to the JEDEC specification JESD51-2 in a horizontal configuration in natural convection. Theta-JA was also simulated on a thermal test board with two internal planes (2s2p where "s" is the number of signal layers and "p" is the number of planes) per JESD51-6 and JESD51-7. The correct name for Theta-JA for forced convection or with the non-single layer boards is Theta-JMA.
- 3. Junction to case thermal resistance, Theta-JC (R_{0JC}), was simulated to be equivalent to the measured values using the cold plate technique with the cold plate temperature used as the "case" temperature. The basic cold plate measurement technique is described by MIL-STD 883D, Method 1012.1. This is the correct thermal metric to use to calculate thermal performance when the package is being used with a heat sink.
- 4. Thermal Characterization Parameter, Psi-JT (Ψ_{JT}), is the "resistance" from junction to reference point thermocouple on top center of case as defined in JESD51-2. Ψ_{JT} is a useful value to use to estimate junction temperature in steady state customer environments.
- 5. Junction temperature is a function of on-chip power dissipation, package thermal resistance, mounting site (board) temperature, ambient temperature, air flow, power dissipation of other components on the board, and board thermal resistance.
- 6. See Section 12.1 for more details on thermal design considerations.

Table 10-5 Recommended Operating Conditions

 $(V_{REFLO} = 0V, V_{SS} = V_{SSA_ADC} = 0V, V_{DDA} = V_{DDA_ADC} = V_{DDA_OSC_PLL})$

Characteristic	Symbol	Notes	Min	Тур	Max	Unit
Supply voltage	V _{DD_IO}		3	3.3	3.6	V
ADC Supply Voltage	V _{DDA_ADC} , V _{REFH}	V _{REFH} must be less than or equal to V _{DDA_ADC}	3	3.3	3.6	V
Oscillator/PLL Supply Voltage	V _{DDA_OSC} _PLL		3	3.3	3.6	V
Internal Logic Core Supply Voltage	V_{DD_CORE}	OCR_DIS is High	2.25	2.5	2.75	V
Device Clock Frequency	FSYSCLK		0	_	60	MHz
Input High Voltage (digital)	V _{IN}	Pin Groups 1, 2, 5, 6, 9, 10, 14	2	_	5.5	V
Input High Voltage (analog)	V _{IHA}	Pin Group13	2	_	V _{DDA} +0.3	V
Input High Voltage (XTAL/EXTAL, XTAL is not driven by an external clock)	V _{IHC}	Pin Group11	V _{DDA} -0.8	_	V _{DDA} +0.3	V
Input high voltage (XTAL/EXTAL, XTAL is driven by an external clock)	V _{IHC}	Pin Group 11	2	_	V _{DDA} +0.3	V
Input Low Voltage	V _{IL}	Pin Groups 1, 2, 5, 6, 9, 10, 11, 13, 14	-0.3	_	0.8	V
Output High Source Current ¹	I _{OH}	Pin Groups 1,2,3		_	-4	mA
$V_{OH} = 2.4V (V_{OH} min.)$		Pin Groups 5,6,7		_	-8	
		Pin Groups 8		_	-12	
Output Low Sink Current ¹ V _{OL} = 0.4V (V _{OL} max)	l _{OL}	Pin Groups 1,2,3,4,14		_	4	mA
GE - (GE -)		Pin Groups 5,6,7		_	8	
		Pin Groups 8		_	12	
Ambient Operating Temperature (Automotive)	T _A		-40	_	125 - (R _{θJA} X P _D)	°C
Ambient Operating Temperature (Industrial)	T _A		-40	_	105 - (R _{θJA} X P _D)	°C
Flash Endurance (Automotive) (Program Erase Cycles)	N _F	T _A = -40°C to 125°C	10,000	_	_	Cycles
Flash Endurance (Industrial) (Program Erase Cycles)	N _F	T _A = -40°C to 105°C	10,000	_	_	Cycles
Flash Data Retention	T _R	T _J <= 70°C avg	15	_	_	Years

Note 1. Total chip source or sink current cannot exceed 200 mA

Pin Group 1: TXD0-1, RXD0-1, $\overline{\text{SS0}}$, MISO0, MOSI0

Pin Group 2: PHASEA0-1, PHASEB0-1, INDEX0-1, HOME0-1, ISB0-2, RSTO, ISA0-2, TC0,

SCLK0

Pin Group 3: RSTO, TDO

Pin Group 4: CAN_TX

Pin Group 5: A0-5, D0-15, GPIOD0-1, \overline{PS} , \overline{DS}

Pin Group 6: A6-15, GPIOB0, TD0-1

Pin Group 7: CLKO, WR, RD

Pin Group 8: PWMA0-5, PWMB0-5

Pin Group 9: IRQA, IRQB, RESET, EXTBOOT, TRST,

TMS, TDI, CAN_RX, EMI_MODE,

FAULTA0-3, FAULTB0-3

Pin Group 10: TCK

Pin Group 11: XTAL, EXTAL

Pin Group 12: ANA0-7, ANB0-7

Pin Group 13: OCR_DIS, CLKMODE

Pin Group 14: DE

10.2 DC Electrical Characteristics

Table 10-6 DC Electrical Characteristics

Over Recommended Operating Conditions, $V_{DDA} = V_{DDA_ADC,_}V_{DDA_OSC_PLL}$

Characteristic	Symbol	Notes	Min	Тур	Max	Unit	Test Conditions
Output High Voltage	V _{OH}		2.4	_	_	V	I _{OH} =I _{OHmax}
Output Low Voltage	V _{OL}		_	_	0.4	V	I _{OL} =I _{OLmax}
Digital Input Current High pull-up enabled or disabled	I _{IH}	Pin Groups 1, 2, 5, 6, 9	_	0	+/- 2.5	μА	V _{IN} = 3.0V to 5.5V
Digital Input Current High with pull-down	I _{IH}	Pin Group10	40	80	160	μΑ	V _{IN} = 3.0V to 5.5V
Analog Input Current High	I _{IHA}	Pin Group13	_	0	+/- 2.5	μА	$V_{IN} = V_{DDA}$
ADC Input Current High	I _{IHADC}	Pin Group12	_	0	+/- 3.5	μΑ	$V_{IN} = V_{DDA}$
Digital Input Current Low pull-up enabled	I _{IL}	Pin Groups 1,2,5,6,9	-50	-100	-200	μΑ	V _{IN} = 0V
Digital Input Current Low pull-up disabled	I _{IL}	Pin Groups 1,2,5,6,9	_	0	+/- 2.5	μΑ	V _{IN} = 0V
Digital Input Current Low with pull-down	I _{IL}	Pin Group10	_	0	+/- 2.5	μА	V _{IN} = 0V
Analog Input Current Low	I _{ILA}	Pin Group13	_	0	+/- 2.5	μΑ	V _{IN} = 0V
ADC Input Current Low	I _{ILADC}	Pin Group12	_	0	+/- 3.5	μΑ	V _{IN} = 0V
EXTAL Input Current Low clock input	I _{EXTAL}		_	0	+/- 2.5	μΑ	V _{IN} = V _{DDA} or 0V
XTAL Input Current Low clock input	I _{XTAL}	CKLMODE = High	_	0	+/- 2.5	μΑ	V _{IN} = V _{DDA} or 0V
		CKLMODE = Low	_	_	200	μΑ	V _{IN} = V _{DDA} or 0V
Output Current High Impedance State	l _{OZ}	Pin Groups 1, 2, 3, 4, 5, 6, 7, 8,14	_	0	+/- 2.5	μА	V _{OUT} = 3.0V to 5.5V or 0V
Schmitt Trigger Input Hysteresis	V _{HYS}	Pin Groups 2, 6, 9,10	_	0.3	_	V	
Input Capacitance (EXTAL/XTAL)	C _{INC}		_	4.5	_	pF	
Output Capacitance (EXTAL/XTAL)	C _{OUTC}		_	5.5	_	pF	
Input Capacitance	C _{IN}			6	_	pF	
Output Capacitance	C _{OUT}		_	6	_	pF	

See Pin Groups in Table 10-5

Table 10-7 Power on Reset Low Voltage Parameters

Characteristic	Symbol	Min	Тур	Max	Units
POR Trip Point	POR	1.75	1.8	1.9	V
LVI, 2.5 volt Supply, trip point ¹	V _{EI2.5}	2.05	2.14	2.25	V
LVI, 3.3 volt supply, trip point ²	V _{EI3.3}	2.6	2.7	2.8	V
Bias Current	I bias		110	130	uA

^{1.} When V_{DD} drops below V_{El2.5}, an interrupt is generated.

Table 10-8 Current Consumption per Power Supply Pin (Typical)
On-Chip Regulator Enabled (OCR_DIS = Low)

Mode	I _{DD_IO} 1	I _{DD_ADC}	I _{DD_OSC_PLL}	Test Conditions
RUN1_MAC	125mA	50mA	2.5mA	60MHz Device Clock
				All peripheral clocks are enabled
				Continuous MAC instructions with fetches from Data RAM
				ADC powered on and clocked
Wait3	73mA	0uA	2.5mA	60MHz Device Clock
				All peripheral clocks are enabled
				ADC powered off
Stop1	5mA	0uA	200uA	8MHz Device Clock
				All peripheral clocks are off
				ADC powered off
				PLL powered off
Stop2	5mA	0uA	150uA	External Clock is off
				All peripheral clocks are off
				ADC powered off
				PLL powered off

^{1.} No Output Switching

^{2.} When V_{DD} drops below $V_{El3.3}$, an interrupt is generated.

Table 10-9 Current Consumption per Power Supply Pin (Typical)
On-Chip Regulator Disabled (OCR_DIS = High)

Mode	I _{DD_Core}	I _{DD_IO} 1	I _{DD_ADC}	I _{DD_OSC_PLL}	Test Conditions
RUN1_MAC	120 mA	13μΑ	50mA	2.5mA	60MHz Device Clock All peripheral clocks are enabled Continuous MAC instructions with fetches from Data RAM ADC powered on and clocked
Wait3	68mA	13μΑ	OμA	2.5mA	60MHz Device ClockAll peripheral clocks are enabledADC powered off
Stop1	500μΑ	13uA	ОμΑ	200uA	 8MHz Device Clock All peripheral clocks are off ADC powered off PLL powered off
Stop2	100μΑ	13μΑ	ОμΑ	150µА	 External Clock is off All peripheral clocks are off ADC powered off PLL powered off

^{1.} No Output Switching

Table 10-10. Regulator Parameters

Characteristic	Symbol	Min	Typical	Max	Unit
Unloaded Output Voltage (0mA Load)	V _{RNL}	2.25	_	2.75	V
Loaded Output Voltage (250mA load)	V_{RL}	2.25	_	2.75	V
Line Regulation @ 250mA load (V _{DD} 33 ranges from 3.0V to 3.6V)	V _R	2.25	_	2.75	V
Short Circuit Current (output shorted to ground)	Iss	_	_	700	mA
Bias Current	I _{bias}	_	5.8	7	mA
Power-down Current	I _{pd}	_	0	2	μΑ
Short-Circuit Tollerance (output shorted to ground)	T _{RSC}	30	_	_	minutes

Table 10-11. PLL Parameters

Characteristics	Symbol	Min	Typical	Max	Unit
PLL Startup time	T _{PS}	0.3	0.5	10	ms
Resonator Startup time	T _{RS}	0.1	0.18	1	ms
Min-Max Period Variation	T _{PV}	120	_	200	ps
Peak-to-Peak Jitter	T _{PJ}	_	_	175	ps
Bias Current	I _{BIAS}	_	1.5	2	mA
Quiescent Current, power-down mode	I _{PD}	_	100	150	μΑ

Table 10-12 Temperature Sense Parametrics

Characteristics	Symbol	Min	Typical	Max	Unit
K-factor ¹	K	7	7.2		mV/°C
Supply Voltage	V_{DDA}	3.0	3.3	3.6	V
Supply Current - OFF	I _{DD-OFF}	_	_	10	μΑ
Supply Current - ON	I _{DD-ON}	_	_	250	μΑ
Accuracy	T _{ACC}	-2	_	+2	°C
Resolution	R _{ES}	_	_	1	°C / bit ²

^{1.} This is the inverse of the parameter "m" in Figure 14-1 of the 56F8300 Peripheral User Manual.

10.3 AC Electrical Characteristics

Tests are conducted using the input levels specified in **Table 10-6**. Unless otherwise specified, propagation delays are measured from the 50% to the 50% point, and rise and fall times are measured between the 10% and 90% points, as shown in **Figure 10-1**.



Note: The midpoint is $V_{IL} + (V_{IH} - V_{IL})/2$.

Figure 10-1 Input Signal Measurement References

^{2.} Assuming a 10-bit range from 0V to 3.6V.

Figure 10-2 shows the definitions of the following signal states:

- Active state, when a bus or signal is driven, and enters a low impedance state
- Tri-stated, when a bus or signal is placed in a high impedance state
- Data Valid state, when a signal level has reached V_{OL} or V_{OH}
- Data Invalid state, when a signal level is in transition between $V_{\mbox{\scriptsize OL}}$ and $V_{\mbox{\scriptsize OH}}$

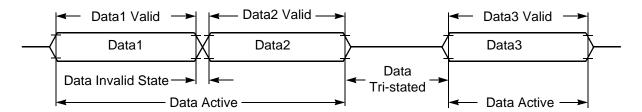


Figure 10-2 Signal States

10.4 Flash Memory Characteristics

Table 10-13 Flash Timing Parameters

Characteristic	Symbol	Min	Тур	Max	Unit
Program time ^{1, 2}	Tprog	20	_	_	us
Erase time ^{3, 4}	Terase	20	_	_	ms
Mass erase time ⁵	Tme	100	_	_	ms

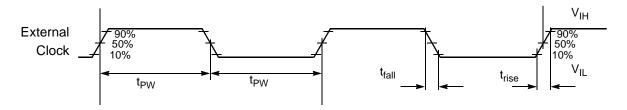
- 1. Program specification guaranteed from TA = 0°C to 85°C
- 2. There is additional overhead which is part of the programming sequence. See the **56F8300 Peripheral User Manual** for details. Program time is per 16-bit word in Flash memory. Two words at a time can be programmed within the Program Flash Module, as it contains two interleaved memories.
- 3. Erase specification guaranteed from TA = 0°C to 85°C
- 4. Specifies page erase time. There are 512 bytes per page in the Data and Boot Flash memories. The Program Flash Module uses two interleaved Flash memories, increasing the effective page size to 1024 bytes.
- 5. Mass erase specification guaranteed from TA = 0°C to 85°C

10.5 External Clock Operation Timing

Table 10-14 External Clock Operation Timing Requirements¹

Characteristic	Symbol	Min	Тур	Max	Unit
Frequency of operation (external clock driver) ²	f _{osc}	0		240	MHz
Clock Pulse Width ³	t _{PW}	2.0	_	_	ns
External clock input rise time ⁴	t _{rise}	_	_	10	ns
External clock input fall time ⁵	t _{fall}	_	_	10	ns

- 1. Parameters listed are guaranteed by design.
- 2. See Figure 10-3 for details on using the recommended connection of an external clock driver.
- 3. The high or low pulse width must be no smaller than 8.0ns or the chip will not function.
- 4. External clock input rise time is measured from 10% to 90%.
- 5. External clock input fall time is measured from 90% to 10%.



Note: The midpoint is $V_{IL} + (V_{IH} - V_{IL})/2$.

Figure 10-3 External Clock Timing

10.6 Phase Locked Loop Timing

Table 10-15 PLL Timing

Characteristic	Symbol	Min	Тур	Max	Unit
External reference crystal frequency for the PLL ¹	f _{osc}	4	8	8	MHz
PLL output frequency ² (f _{OUT} /2)	f _{op}	160	_	260	MHz
PLL stabilization time ³ 0° to +85°C	t _{plls}	_	1	10	ms

^{1.} An externally supplied reference clock should be as free as possible from any phase jitter for the PLL to work correctly. The PLL is optimized for 8MHz input crystal.

^{2.} ZCLK may not exceed 60MHz. For additional information on ZCLK and (f_{OUT})/2, please refer to the OCCS chapter in the **56F8300 Peripheral User Manual**.

^{3.} This is the minimum time required after the PLL set-up is changed to ensure reliable operation.

10.7 Crystal Oscillator Timing

Table 10-16 Crystal Oscillator Parameters

Characteristic	Symbol	Min	Тур	Max	Unit
Crystal Startup time	T _{CS}	4	5	10	ms
Resonator Startup time	T _{RS}	0.1	0.18	1	ms
Crystal ESR	R _{ESR}	_	_	120	ohms
Crystal Peak-to-Peak Jitter	T _D	70	_	250	ps
Crystal Min-Max Period Variation	T _{PV}	0.12	_	1.5	ns
Resonator Peak-to-Peak Jitter	T _{RJ}	_	_	300	ps
Resonator Min-Max Period Variation	T _{RP}	_	_	300	ps
Bias Current, high-drive mode	I _{BIASH}	_	250	290	μΑ
Bias Current, low-drive mode	I _{BIASL}	_	80	110	μΑ
Quiescent Current, power-down mode	I _{PD}	_	0	1	μΑ

10.8 External Memory Interface Timing

The External Memory Interface is designed to access static memory and peripheral devices. **Figure 10-4** shows sample timing and parameters that are detailed in **Table 10-17**.

The timing of each parameter consists of both a fixed delay portion and a clock related portion; as well as user controlled wait states. The equation:

$$t = D + P * (M + W)$$

should be used to determine the actual time of each parameter. The terms in the above equation are defined as:

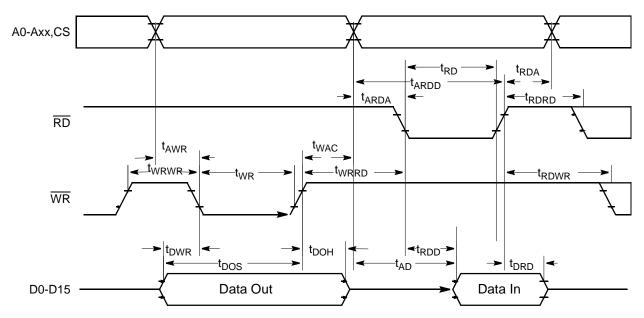
- t parameter delay time
- D fixed portion of the delay, due to on-chip path delays.
- P the period of the system clock, which determines the execution rate of the part (i.e. when the device is operating at 120 MHz, P = 8.33 ns).
- M Fixed portion of a clock period inherent in the design. This number is adjusted to account for possible clock duty cycle derating.
- W the sum of the applicable wait state controls. See the "Wait State Controls" column of **Table 10-17** for the applicable controls for each parameter. See the EMI chapter of the 83x Peripheral Manual for details of what each wait state field controls.

DCA = 0.5 - (XTAL duty cycles), if ZSRC selects prescale clock and prescaler set to \div 1.

- = 0.0 all other cases
- ie. if XTAL duty cycle is 60%, use 0.6

Some of the parameters contain two sets of numbers. These parameters have two different paths and clock edges that must be considered. Check both sets of numbers and use the smaller result. The appropriate entry may change if the operating frequency of the part changes.

The timing of write cycles is different when WWS = 0 than when WWS > 0. Therefore, some parameters contain two sets of numbers to account for this difference. The "Wait States Configuration" column of **Table 10-17** should be used to make the appropriate selection.



Note: During read-modify-write instructions and internal instructions, the address lines do not change state.

Figure 10-4 External Memory Interface Timing

Table 10-17 External Memory Interface Timing

 $Operating\ Conditions:\ V_{SS} = V_{SSIO} = V_{SSA} = 0\ V,\ V_{DD} = 1.62 - 1.98\ V,\ V_{DDIO} = V_{DDA} = 3.0 - 3.6V,\ T_A = -40^{\circ}\ to\ +120^{\circ}C,\ C_L \leq 50 pF,\ P = 8.333 ns$

Characteristic	Symbol	Wait States Configuration	D	М	Wait States Controls	Unit
Address Valid to WR Asserted	t _{AWR}	WWS=0	TBD	TBD	wwss	ns
	AWR	WWS>0	TBD	TBD	WW33	115
WR Width Asserted to WR	t _{WR}	WWS=0	TBD	TBD	wws	ns
Deasserted	TVVK	WWS>0	TBD	TBD	******	110
Data Out Valid to WR Asserted		WWS=0	TBD	TBD		
	t _{DWR}	WWS=0	TBD	TBD	wwss	ns
	DWK	WWS>0	TBD	TBD		
		WWS>0	TBD	TBD		
Valid Data Out Hold Time after WR Deasserted	t _{DOH}		TBD	TBD	WWSH	ns
Valid Data Out Set Up Time to WR	taaa		-2.051	0.5 + DCA	WWS,WWSS	ns
Deasserted	t _{DOS}		-8.995	0.5	vvv3,vvv33	115
Valid Address after WR Deasserted	t _{WAC}		TBD	TBD	WWSH	ns
RD Deasserted to Address Invalid	t _{RDA}		TBD	TBD	RWSH	ns
Address Valid to RD Deasserted	t _{ARDD}		TBD	TBD	RWSS,RWS	ns
Valid Input Data Hold after RD Deasserted	t _{DRD}		TBD	N/A ¹	ı	ns
RD Assertion Width	t _{RD}		TBD	TBD	RWS	ns
Address Valid to Input Data Valid	t _{AD}		-14.798	1.00	RWSS,RWS	ns
·	٩D		-19.661	1.25 + DCA	10000,1000	115
Address Valid to RD Asserted	t _{ARDA}		TBD	TBD	RWSS	ns
RD Asserted to Input Data Valid	t _{RDD}		TBD	TBD	5,4,00 5,4,0	ns
	טטאי		TBD	TBD	RWSS,RWS	113
WR Deasserted to RD Asserted	t _{WRRD}		TBD	TBD	WWSH,RWSS	ns
RD Deasserted to RD Asserted	t _{RDRD}		TBD ²	TBD	RWSS,RWSH MDAR,BMDAR	ns
WR Deasserted to WR Asserted	t _{WRWR}	WWS=0	TBD	TBD	WWSS, WWSH	ns
	*VVKVVK	WWS>0	TBD	TBD		110
RD Deasserted to WR Asserted	t _{RDWR}		TBD	TBD	MDAR, BMDAR,	ns
	אאטאא		TBD	TBD	RWSH, WWSS	110

^{1.} N/A since device captures data before it deasserts RD

^{2.} If RWSS = RWSH = 0, RD does not deassert during back-to-back reads and D=0.00 should be used.

10.9 Reset, Stop, Wait, Mode Select, and Interrupt Timing

Table 10-18 Reset, Stop, Wait, Mode Select, and Interrupt Timing 1,2

Characteristic	Symbol	Typical Min	Typical Max	Unit	See Figure
RESET Assertion to Address, Data and Control Signals High Impedance	t _{RAZ}	_	21	ns	10-5
Minimum RESET Assertion Duration	t _{RA}	16T	_	ns	10-5
RESET Deassertion to First External Address Output ³	t _{RDA}	63T	64T	ns	10-5
Edge-sensitive Interrupt Request Width	t _{IRW}	1.5T	_	ns	10-6
IRQA, IRQB Assertion to External Data Memory Access Out Valid, caused by first instruction execution in the interrupt service routine	t _{IDM}	TBD	TBD	ns	10-7
	t _{IDM - FAST}	TBD	TBD		
IRQA, IRQB Assertion to General Purpose Output	t _{IG}	TBD	TBD	ns	10-7
Valid, caused by first instruction execution in the interrupt service routine	t _{IG - FAST}	TBD	TBD		
IRQA Low to First Valid Interrupt Vector Address	t _{IRI}	TBD	TBD	ns	10-8
Out recovery from Wait State ⁴	t _{IRI -FAST}	TBD	TBD		
IRQA Width Assertion to Recover from Stop State ⁵	t _{IW}	1.5T	_	ns	10-9
Delay from IRQA Assertion to Fetch of first instruction (exiting Stop) from external memory	t _{IF}	_	TBD	ns	10-9
instruction (exiting Stop) from external memory	t _{IF - FAST}	_	TBD		

^{1.} In the formulas, T = clock cycle. For an operating frequency of 60MHz, T = 16.67ns. At 8MHz (used during Reset and Stop modes), T = 125ns.

- 2. Parameters listed are guaranteed by design.
- 3. During Power-On Reset, it is possible to use the 56F8346 internal reset stretching circuitry to extend this period to $2^{21}T$.
- 4. The minimum is specified for the duration of an edge-sensitive $\overline{\text{IRQA}}$ interrupt required to recover from the Stop state. This is not the minimum required so that the $\overline{\text{IRQA}}$ interrupt is accepted.
- 5. The interrupt instruction fetch is visible on the pins only in Mode 3.

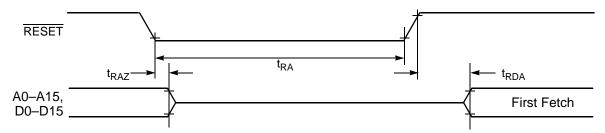


Figure 10-5 Asynchronous Reset Timing



Figure 10-6 External Interrupt Timing (Negative-Edge-Sensitive)

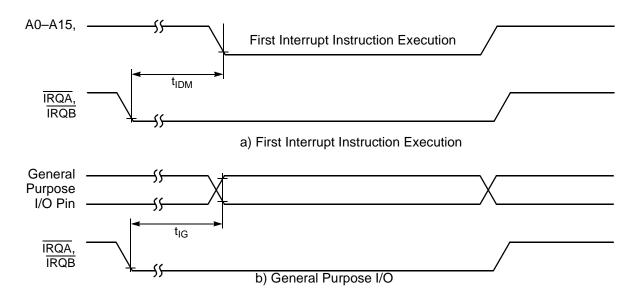


Figure 10-7 External Level-Sensitive Interrupt Timing

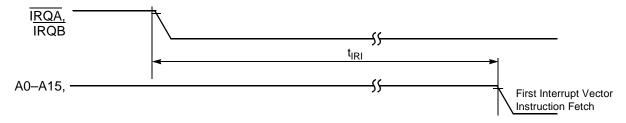


Figure 10-8 Interrupt from Wait State Timing

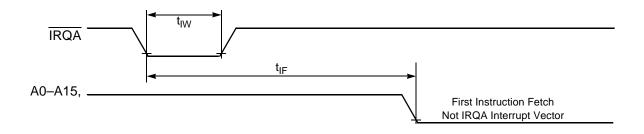


Figure 10-9 Recovery from Stop State Using Asynchronous Interrupt Timing

10.10 Serial Peripheral Interface (SPI) Timing

Table 10-19 SPI Timing¹

Characteristic	Symbol	Min	Max	Unit	See Figure
Cycle time Master Slave	t _C	50 50	_	ns ns	10-10, 10-11, 10-12, 10-13
Enable lead time Master Slave	t _{ELD}	 25	_	ns ns	10-13
Enable lag time Master Slave	t _{ELG}	_ 100	_	ns ns	10-13
Clock (SCK) high time Master Slave	t _{CH}	17.6 25	_	ns ns	10-10, 10-11, 10-12, 10-13
Clock (SCK) low time Master Slave	t _{CL}	24.1 25	_	ns ns	10-13
Data set-up time required for inputs Master Slave	t _{DS}	20 0	_	ns ns	10-10, 10-11, 10-12, 10-13
Data hold time required for inputs Master Slave	t _{DH}	0 2	_	ns ns	10-10, 10-11, 10-12, 10-13
Access time (time to data active from high-impedance state) Slave	t _A	4.8	15	ns	10-13
Disable time (hold time to high-impedance state) Slave	t _D	3.7	15.2	ns	10-13
Data Valid for outputs Master Slave (after enable edge)	t _{DV}	_	4.5 20.4	ns ns	10-10, 10-11, 10-12, 10-13
Data invalid Master Slave	t _{DI}	0	_	ns ns	10-10, 10-11, 10-12
Rise time Master Slave	t _R	_	11.5 10.0	ns ns	10-10, 10-11, 10-12, 10-13
Fall time Master Slave	t _F	_	9.7 9.0	ns ns	10-10, 10-11, 10-12, 10-13

^{1.} Parameters listed are guaranteed by design.

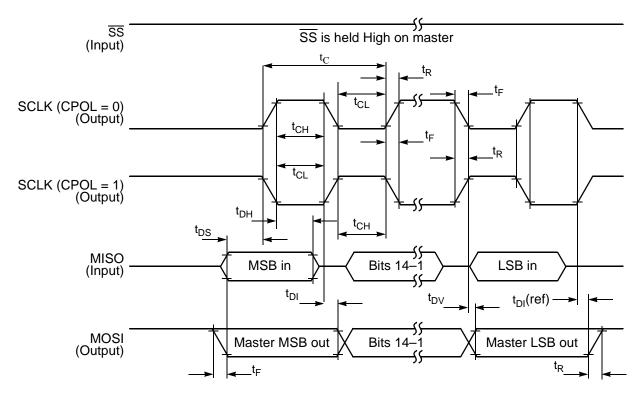


Figure 10-10 SPI Master Timing (CPHA = 0)

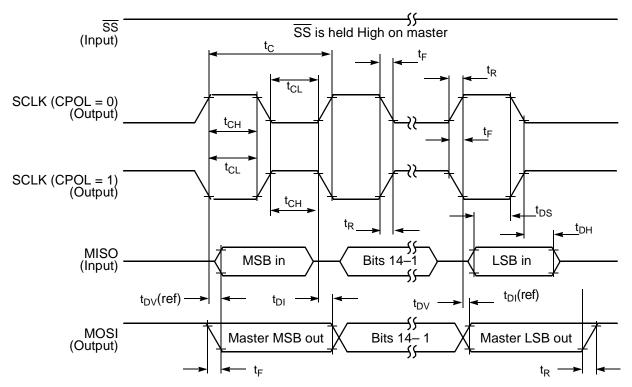


Figure 10-11 SPI Master Timing (CPHA = 1)

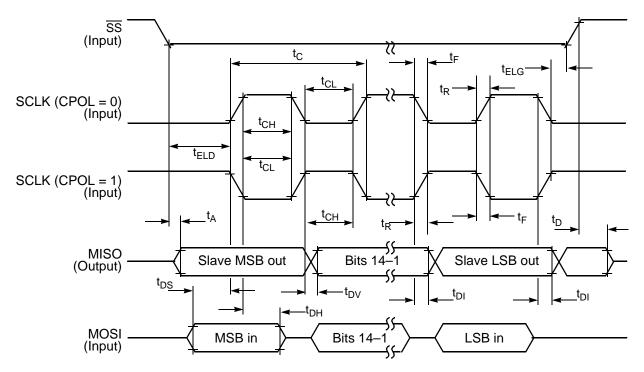


Figure 10-12 SPI Slave Timing (CPHA = 0)

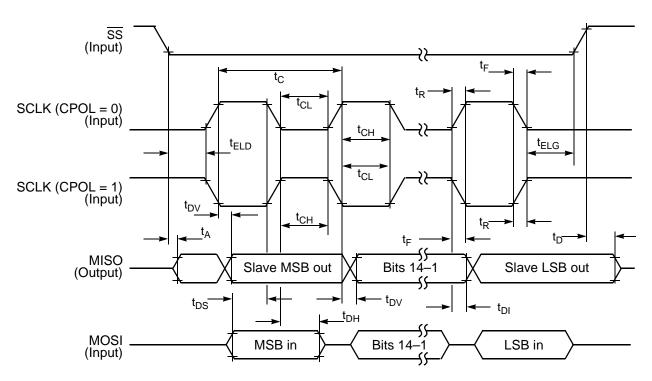


Figure 10-13 SPI Slave Timing (CPHA = 1)

10.11 Quad Timer Timing

Table 10-20 Timer Timing^{1, 2}

Characteristic	Symbol	Min	Max	Unit	See Figure
Timer input period	P _{IN}	2T + 6	1	ns	10-14
Timer input high/low period	P _{INHL}	1T + 3	_	ns	10-14
Timer output period	P _{OUT}	1T - 3	_	ns	10-14
Timer output high/low period	P _{OUTHL}	0.5T - 3	_	ns	10-14

- 1. In the formulas listed, T = the clock cycle. For 60MHz operation, T = 16.67ns.
- 2. Parameters listed are guaranteed by design.

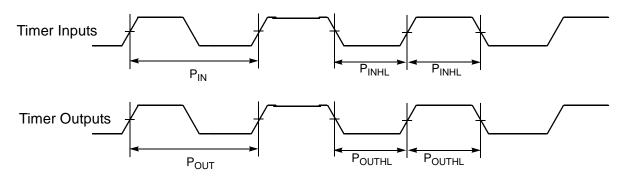


Figure 10-14 Timer Timing

10.12 Quadrature Decoder Timing

Table 10-21 Quadrature Decoder Timing^{1, 2}

Characteristic	Symbol	Min	Max	Unit	See Figure
Quadrature input period	P _{IN}	4T + 12	_	ns	10-15
Quadrature input high/low period	P_{HL}	2T + 6	_	ns	10-15
Quadrature phase period	P _{PH}	1T + 3		ns	10-15

- 1. In the formulas listed, T = the clock cycle. For 60MHz operation, T=16.67ns.
- 2. Parameters listed are guaranteed by design.

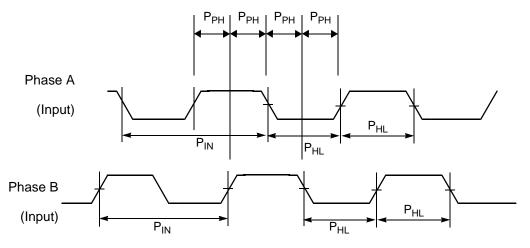


Figure 10-15 Quadrature Decoder Timing

10.13 Serial Communication Interface (SCI) Timing

Table 10-22 SCI Timing¹

Characteristic	Symbol	Min	Max	Unit	See Figure
Baud Rate ²	BR	_	(f _{MAX} /16)	Mbps	_
RXD ³ Pulse Width	RXD _{PW}	0.965/BR	1.04/BR	ns	10-16
TXD ⁴ Pulse Width	TXD _{PW}	0.965/BR	1.04/BR	ns	10-17

- 1. Parameters listed are guaranteed by design.
- 2. f_{MAX} is the frequency of operation of the system clock, ZCLK, in MHz, which is 60MHz for the 56F8346 device.
- 3. The RXD pin in SCI0 is named RXD0 and the RXD pin in SCI1 is named RXD1.
- 4. The TXD pin in SCI0 is named TXD0 and the TXD pin in SCI1 is named TXD1.

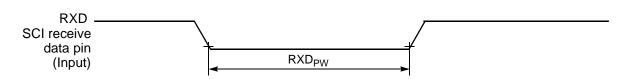


Figure 10-16 RXD Pulse Width



Figure 10-17 TXD Pulse Width

10.14 Controller Area Network (CAN) Timing

Table 10-23 CAN Timing¹

Characteristic	Symbol	Min	Max	Unit	See Figure
Baud Rate	BR _{CAN}	_	1	Mbps	_
Bus Wake Up detection	T _{WAKEUP}	5	_	μs	10-18

^{1.} Parameters listed are guaranteed by design

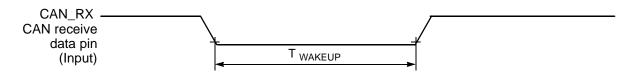


Figure 10-18 Bus Wake Up Detection

10.15 JTAG Timing

Table 10-24 JTAG Timing

Characteristic	Symbol	Min	Max	Unit	See Figure
TCK frequency of operation ¹	f _{OP}	DC	sys_clk/8	MHz	10-19
TCK clock pulse width	t _{PW}	50	_	ns	10-19
TMS, TDI data set-up time	t _{DS}	5	_	ns	10-20
TMS, TDI data hold time	t _{DH}	5	_	ns	10-20
TCK low to TDO data valid	t _{DV}	_	30	ns	10-20
TCK low to TDO tri-state	t _{TS}	_	30	ns	10-20
TRST assertion time	t _{TRST}	2T ²	_	ns	10-21
DE assertion time	t _{DE}	2T	_	ns	10-22

^{1.} TCK frequency of operation must be less than 1/8 the processor rate.

^{2.} T = processor clock period (nominally 1/60MHz)

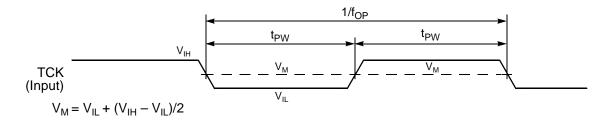


Figure 10-19 Test Clock Input Timing Diagram

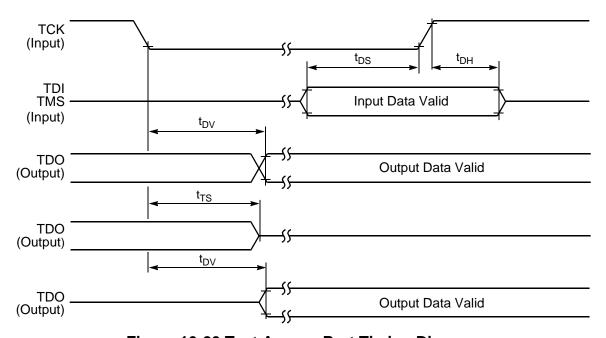


Figure 10-20 Test Access Port Timing Diagram

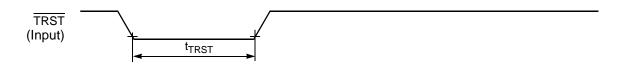


Figure 10-21 TRST Timing Diagram



Figure 10-22 EOnCE - Debug Event

MOTOROLA

10.16 Analog-to-Digital Converter (ADC) Parameters

Table 10-25 ADC Parameters

Characteristic	Symbol	Min	Тур	Max	Unit
Input voltages	V _{ADIN}	V _{REFL}	_	V _{REFH}	V
Resolution	R _{ES}	12	_	12	Bits
Integral Non-Linearity ¹	INL	+/- 1	+/- 2.4	+/- 3.2	LSB ²
Differential Non-Linearity	DNL	> -1	+/- 0.7	< +1	LSB ²
Monotonicity			GUARANTEED	I	
ADC internal clock	f _{ADIC}	0.5	_	5	MHz
Conversion range	R _{AD}	V_{REFL}	_	V _{REFH}	V
ADC channel power-up time	t _{ADPU}	5	6	16	t _{AIC} cycles ²
ADC reference circuit power-up time	t _{VREF}	_	_	25	ms
Conversion time	t _{ADC}	_	6	_	t _{AIC} cycles ⁴
Sample time	t _{ADS}	_	1	_	t _{AIC} cycles ⁴
Input capacitance	C _{ADI}	_	5	_	pF
Input injection current ³ , per pin	I _{ADI}	_	_	3	mA
Input injection current, total	I _{ADIT}	_	_	20	mA
V _{REFH} current	I _{VREFH}	_	1.2	3	mA
ADCA current	I _{ADCA}	_	25	_	mA
ADCB current	I _{ADCB}	_	25	_	mA
Quiescent current	I _{ADCQ}		0	10	mA
Calibrated Gain Error (transfer gain)	E _{GAINC}	_	1	_	_
Calibrated Offset Voltage	V _{OFFSETC}	_	0	_	mV
Uncalibrated Gain Error	E _{GAIN}	.99	.996 to 1.004	1.01	_
Uncalibrated Offset Voltage	V _{OFFSET}	_	+/- 12	+/- 30	mV
Crosstalk between channels		_	-60	_	dB
Common Mode Voltage	V _{common}	_	(V _{REFH} - V _{REFLO}) / 2	_	V
Signal-to-noise ratio	SNR	_	64.6	_	db
Signal-to-noise plus distortion ratio	SINAD	_	59.1	_	db
Total Harmonic Distortion	THD	_	60.6	_	db
Spurious Free Dynamic Range	SFDR	_	61.1	_	db
Effective Number Of Bits	ENOB		9.6	_	bit

INL measured from Vin = .1V_{REFH} to Vin = .9V_{REFH}
 10% to 90% Input Signal Range

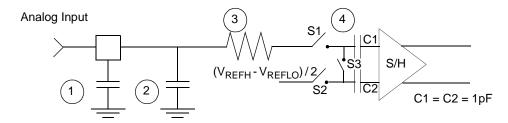
^{2.} ADC clock cycles

^{3.} The current that can be injected or sourced from an unselected ADC signal input without inpacting the performance of the ADC. This allows the ADC to operate in noisy industrial environments where inductive flyback is possible.

10.17 Equivalent Circuit for ADC Inputs

Figure 10-23 illustrates the ADC input circuit during sample and hold. S1 and S2 are always open/closed at the same time that S3 is closed/open. When S1/S2 are closed & S3 is open, one input of the sample and hold circuit moves to V_{REFH} - V_{REFH} / 2 while the other charges to the analog input voltage. When the switches are flipped, the charge on C1 and C2 are averaged via S3, with the result that a single-ended analog input is switched to a differential voltage centered about V_{REFH} - V_{REFH} / 2. The switches switch on every cycle of the ADC clock (open one-half ADC clock, closed one-half ADC clock). Note that there are additional capacitances associated with the analog input pad, routing, etc., but these do not filter into the S/H output voltage, as S1 provides isolation during the charge-sharing phase.

One aspect of this circuit is that there is an on-going input current, which is a function of the analog input voltage, V_{REF} and the ADC clock frequency.



- 1. Parasitic capacitance due to package, pin-to-pin and pin-to-package base coupling; 1.8pf
- 2. Parasitic capacitance due to the chip bond pad, ESD protection devices and signal routing; 2.04pf
- 3. Equivalent resistance for the ESD isolation resistor and the channel select mux; 500 ohms
- 4. Sampling capacitor at the sample and hold circuit. Capacitor C1 is normally disconnected from the input and is only connected to it at sampling time; 1pf

Figure 10-23 Equivalent Circuit for A/D Loading

10.18 Power Consumption

This section provides additional detail which can be used to optimize power consumption for a given application.

Power consumption is given by the following equation:

Total power = A: internal [static component]

+ B: internal [state-dependent component]

+ C: internal [dynamic component]

+ D: external [dynamic component]

+ E: external [static]

A, the internal [static component], is comprised of the DC bias currents for the oscillator, leakage current, PLL, and voltage references. These sources operate independently of processor state or operating frequency.

B, the internal [state-dependent component], reflects the supply current required by certain on-chip resources only when those resources are in use. These include RAM, Flash memory and the ADCs.

C, the internal [dynamic component], is classic C*V²*F CMOS power dissipation corresponding to the 56800E core and standard cell logic.

D, the external [dynamic component], reflects power dissipated on-chip as a result of capacitive loading on the external pins of the chip. This is also commonly described as $C*V^2*F$, although simulations on two of the IO cell types used on the 56F8346 reveal that the power-versus-load curve does have a non-zero Y-intercept.

Table 10-26 IO Loading Coefficients at 10MHz

	Intercept	Slope
PDU08DGZ_ME	2.2	2.0
PDU04DGZ_ME	.14	.14

Power due to capacitive loading on output pins is (first order) a function of the capacitive load and frequency at which the outputs change. **Table 10-26** provides coefficients for calculating power dissipated in the IO cells as a function of capacitive load. In these cases:

 $TotalPower = \Sigma((Intercept + Slope*Cload)*frequency/10MHz)$

where:

- Summation is performed over all output pins with capacitive loads
- TotalPower is expressed in mW
- Cload is expressed in pF

Because of the low duty cycle on most device pins, power dissipation due to capacitive loads was found to be fairly low when averaged over a period of time. The one possible exception to this is if the chip is using the external address and data buses at a rate approaching the maximum system rate. In this case, power from these buses can be significant.

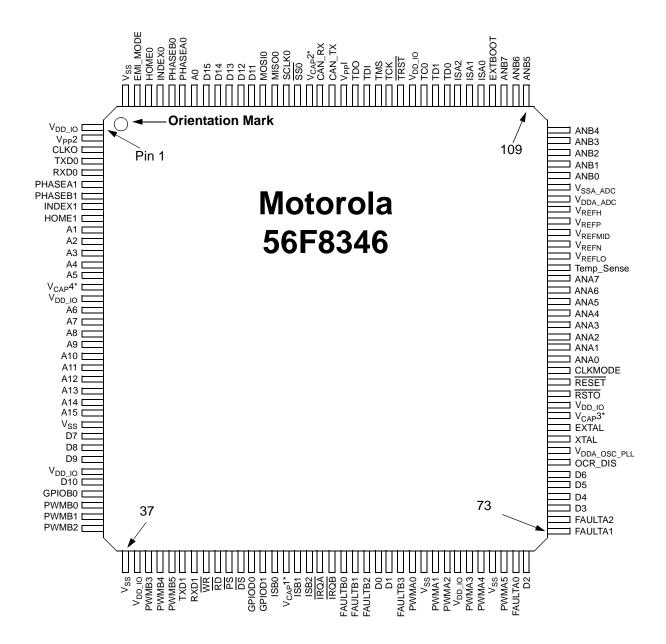
E, the external [static component], reflects the effects of placing resistive loads on the outputs of the device. Sum the total of all V^2/R or IV to arrive at the resistive load contribution to power. Assume V=0.5 for the purposes of these rough calculations. For instance, if there is a total of 8 PWM outputs driving 10mA into LEDs, then P=8*.5*.01=40mW.

In previous discussions, power consumption due to parasitics associated with pure input pins is ignored, as it is assumed to be negligible.

Part 11 Packaging

11.1 Package and Pin-Out Information 56F8346

This section contains package and pin-out information for the 56F8346. This device comes in a 144-pin low-profile quad flat pack (LQFP). The package outline is shown in **Figure 11-1**. **Figure 11-2** shows the mechanical parameters for the 144-pin LQFP case, and **Table 11-1** lists the pin-out for the 144-pin LQFP.



 $^{^{\}star}$ When on-chip regulator is disabled, these four pins are 2.5V V_{DD CORE}

Figure 11-1 Top View, 56F8346 144-Pin LQFP Package

Table 11-1 56F8346 144-Pin LQFP Package Identification by Pin Number

Pin No.	Signal Name	Pin No.	Signal Name	Pin No.	Signal Name	Pin No.	Signal Name
1	V _{DD_IO}	37	V _{SS}	73	FAULTA1	109	ANB5
2	V _{PP} 2	38	V _{DD_IO}	74	FAULTA2	110	ANB6
3	CLKO	39	PWMB3	75	D3	111	ANB7
4	TXD0	40	PWMB4	76	D4	112	EXTBOOT
5	RXD0	41	PWMB5	77	D5	113	ISA0
6	PHASEA1	42	TXD1	78	D6	114	ISA1
7	PHASEB1	43	RXD1	79	OCR_DIS	115	ISA2
8	INDEX1	44	WR	80	V _{DDA_OSC_PLL}	116	TD0
9	HOME1	45	RD	81	XTAL	117	TD1
10	A1	46	PS	82	EXTAL	118	TC0
11	A2	47	DS	83	V _{CAP} 3	119	V _{DD_IO}
12	A3	48	GPIOD0	84	V_{DD_IO}	120	TRST
13	A4	49	GPIOD1	85	RSTO	121	TCK
14	A5	50	ISB0	86	RESET	122	TMS
15	V _{CAP} 4	51	V _{CAP} 1	87	CLKMODE	123	TDI
16	V_{DD_IO}	52	ISB1	88	ANA0	124	TDO
17	A6	53	ISB2	89	ANA1	125	V _{PP} 1
18	A7	54	ĪRQĀ	90	ANA2	126	CAN_TX
19	A8	55	ĪRQB	91	ANA3	127	CAN_RX
20	A9	56	FAULTB0	92	ANA4	128	V _{CAP} 2
21	A10	57	FAULTB1	93	ANA5	129	SS0
22	A11	58	FAULTB2	94	ANA6	130	SCLK0
23	A12	59	D0	95	ANA7	131	MISO0
24	A13	60	D1	96	Temp_Sense	132	MOSI0
25	A14	61	FAULTB3	97	V _{REFLO}	133	D11
26	A15	62	PWMA0	98	V_{REFN}	134	D12
27	V _{SS}	63	V _{SS}	99	V_{REFMID}	135	D13
28	D7	64	PWMA1	100	V_{REFP}	136	D14
29	D8	65	PWMA2	101	V _{REFH}	137	D15

Table 11-1 56F8346 144-Pin LQFP Package Identification by Pin Number

Pin No.	Signal Name	Pin No.	Signal Name	Pin No.	Signal Name	Pin No.	Signal Name
30	D9	66	V_{DD_IO}	102	V _{DDA_ADC}	138	A0
31	V_{DD_IO}	67	PWMA3	103	V _{SSA_ADC}	139	PHASEA0
32	D10	68	PWMA4	104	ANB0	140	PHASEB0
33	GPIOB0	69	V _{SS}	105	ANB1	141	INDEX0
34	PWMB0	70	PWMA5	106	ANB2	142	HOME0
35	PWMB1	71	FAULTA0	107	ANB3	143	EMI_MODE
36	PWMB2	72	D2	108	ANB4	144	V _{SS}

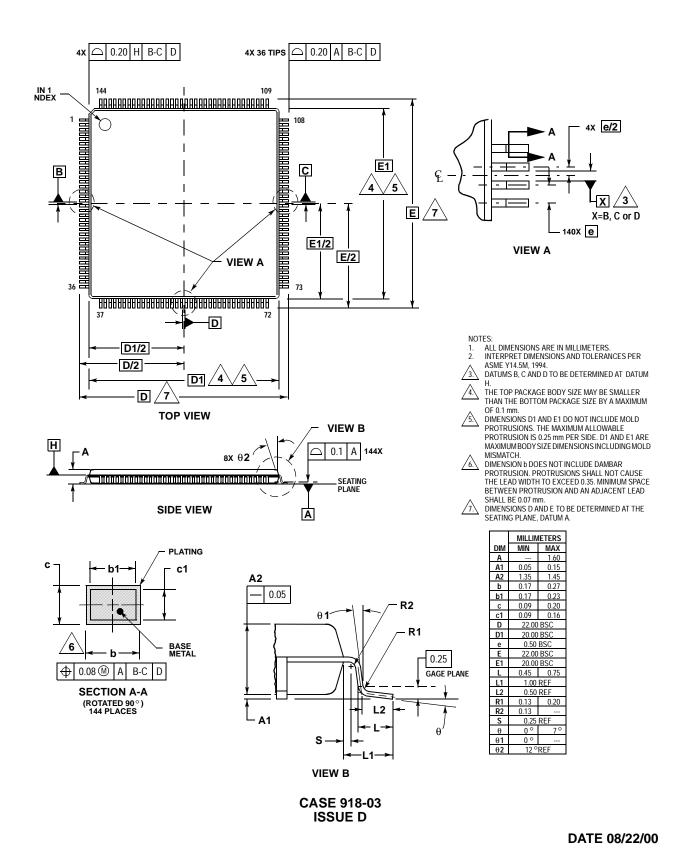


Figure 11-2 56F8346 144-pin LQFP Mechanical Information

Part 12 Design Considerations

12.1 Thermal Design Considerations

An estimation of the chip junction temperature, T_{J} , can be obtained from the equation:

$$T_{J} = T_{A} + (R_{\theta,JA} \times P_{D})$$

where:

 T_A = Ambient temperature for the package (${}^{o}C$)

 $R_{\theta,JA}$ = Junction-to-ambient thermal resistance (${}^{\circ}C/W$)

 P_D = Power dissipation in the package (W)

The junction-to-ambient thermal resistance is an industry-standard value that provides a quick and easy estimation of thermal performance. Unfortunately, there are two values in common usage: the value determined on a single-layer board and the value obtained on a board with two planes. For packages such as the PBGA, these values can be different by a factor of two. Which value is closer to the application depends on the power dissipated by other components on the board. The value obtained on a single-layer board is appropriate for the tightly packed printed circuit board. The value obtained on the board with the internal planes is usually appropriate if the board has low-power dissipation and the components are well separated.

When a heat sink is used, the thermal resistance is expressed as the sum of a junction-to-case thermal resistance and a case-to-ambient thermal resistance:

$$R_{\theta,JA} = R_{\theta,JX} + R_{\theta,CA}$$

where:

 $\begin{array}{lll} R_{\theta JA} & = & Package\ junction-to-ambient\ thermal\ resistance\ ^{\circ}C/W \\ R_{\theta JC} & = & Package\ junction-to-case\ thermal\ resistance\ ^{\circ}C/W \\ R_{\theta CA} & = & Package\ case-to-ambient\ thermal\ resistance\ ^{\circ}C/W \\ \end{array}$

R θ JC is device-related and cannot be influenced by the user. The user controls the thermal environment to change the case-to-ambient thermal resistance, R θ CA. For instance, the user can change the size of the heat sink, the air flow around the device, the interface material, the mounting arrangement on printed circuit board, or change the thermal dissipation on the printed circuit board surrounding the device.

To determine the junction temperature of the device in the application when heat sinks are not used, the Thermal Characterization Parameter (Ψ_{JT}) can be used to determine the junction temperature with a measurement of the temperature at the top center of the package case using the following equation:

$$T_J = T_T + (\Psi_{JT} \times P_D)$$

where:

 T_T = Thermocouple temperature on top of package (${}^{o}C$)

 Ψ_{JT} = Thermal characterization parameter (${}^{o}C$)/W

 P_D = Power dissipation in package (W)

The thermal characterization parameter is measured per JESD51-2 specification using a 40-gauge type T thermocouple epoxied to the top center of the package case. The thermocouple should be positioned so that the thermocouple junction rests on the package. A small amount of epoxy is placed over the thermocouple junction and over about 1mm of wire extending from the junction. The thermocouple wire is placed flat against the package case to avoid measurement errors caused by cooling effects of the thermocouple wire.

When heat sink is used, the junction temperature is determined from a thermocouple inserted at the interface between the case of the package and the interface material. A clearance slot or hole is normally required in the heat sink. Minimizing the size of the clearance is important to minimize the change in thermal performance caused by removing part of the thermal interface to the heat sink. Because of the experimental difficulties with this technique, many engineers measure the heat sink temperature and then back-calculate the case temperature using a separate measurement of the thermal resistance of the interface. From this case temperature, the junction temperature is determined from the junction-to-case thermal resistance.

12.2 Electrical Design Considerations

CAUTION

This device contains protective circuitry to guard against damage due to high static voltage or electrical fields. However, normal precautions are advised to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate voltage level.

Use the following list of considerations to assure correct device operation:

- Provide a low-impedance path from the board power supply to each V_{DD} pin on the device, and from the board ground to each V_{SS} (GND) pin
- The minimum bypass requirement is to place six $0.01-0.1\mu F$ capacitors positioned as close as possible to the package supply pins. The recommended bypass configuration is to place one bypass capacitor on each of the V_{DD}/V_{SS} pairs, including V_{DDA}/V_{SSA} . Ceramic and tantalum capacitors tend to provide better performance tolerances.
- Ensure that capacitor leads and associated printed circuit traces that connect to the chip V_{DD} and V_{SS (GND)} pins are less than 0.5 inch per capacitor lead
- Use at least a four-layer Printed Circuit Board (PCB) with two inner layers for V_{DD} and V_{SS}
- Bypass the V_{DD} and V_{SS} layers of the PCB with approximately 100 μ F, preferably with a high-grade capacitor such as a tantalum capacitor
- Because the 56F8346's output signals have fast rise and fall times, PCB trace lengths should be minimal
- Consider all device loads as well as parasitic capacitance due to PCB traces when calculating capacitance. This is especially critical in systems with higher capacitive loads that could create higher transient currents in the V_{DD} and V_{SS} circuits.

- Take special care to minimize noise levels on the V_{REF}, V_{DDA} and V_{SSA} pins
- Designs that utilize the TRST pin for JTAG port or EOnCE module <u>functionality</u> (such as development or debugging systems) <u>should</u> allow a means to <u>assert TRST</u> whenever RESET is asserted, as well as a means to assert TRST independently of RESET. Designs that do not require debugging functionality, such as consumer products, should tie these pins together.
- Because the Flash memory is programmed through the JTAG/EOnCE port, the designer should provide an interface to this port to allow in-circuit Flash programming

12.3 Power Distribution and I/O Ring Implementation

Figure 12-1 illustrates the general power control incorporated in the 56F8346. This chip contains an internal regulator which cannot be disabled The regulator takes regulated 3.3V power from the V_{DD_IO} pins and provides 2.5V to the internal logic of the chip. This means the entire part is powered from the 3.3V supply.

Notes:

- Flash, RAM and internal logic are powered from the core regulator output
- V_{PP}1 and V_{PP}2 are not connected in the customer system
- All circuitry, analog and digital, share a common V_{SS} bus

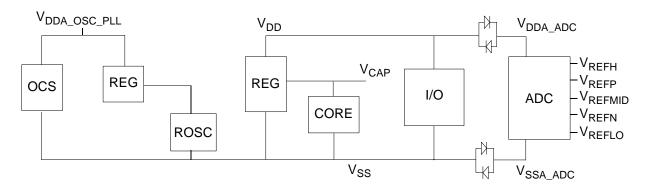


Figure 12-1 56F8346 Power Management

Part 13 Ordering Information

Table 13-1 lists the pertinent information needed to place an order. Consult a Motorola Semiconductor sales office or authorized distributor to determine availability and to order parts.

Table 13-1 56F8346 Ordering Information

Part	Supply Voltage	Package Type	Pin Count	Frequency (MHz)	Temperature Range	Order Number
MC56F8346	3.0-3.6 V	Low-Profile Quad Flat Pack (LQFP)	144	60	-40° to + 105° C	MC56F8346VFV60
MC56F8346	3.0-3.6 V	Low-Profile Quad Flat Pack (LQFP)	144	60	-40° to + 125° C	MC56F8346MFV60

HOW TO REACH US:

USA/EUROPE/LOCATIONS NOT LISTED:

Motorola Literature Distribution P.O. Box 5405, Denver, Colorado 80217 1-800-521-6274 or 480-768-2130

JAPAN:

Motorola Japan Ltd. SPS, Technical Information Center 3-20-1, Minami-Azabu Minato-ku Tokyo 106-8573, Japan 81-3-3440-3569

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